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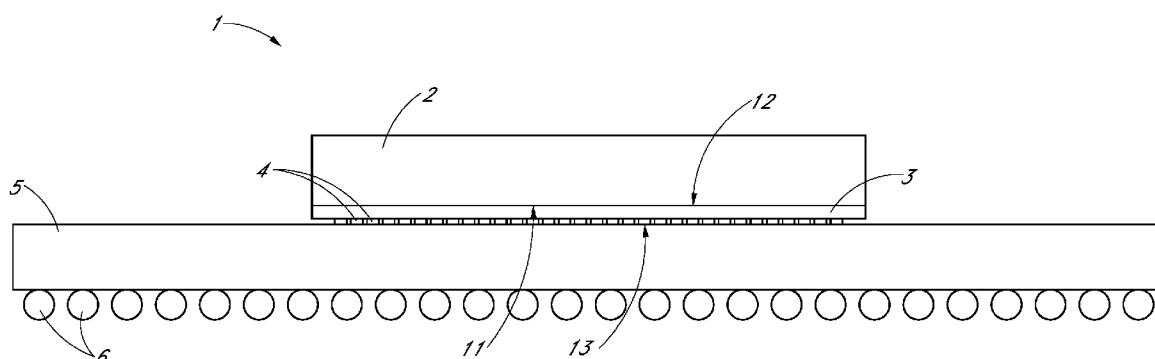


FIG. 1A

(57) Abstract: In various embodiments, a bonded structure is disclosed. The bonded structure can include an element and a passive electronic component having a first surface bonded to the element and a second surface opposite the first surface. The passive electronic component can comprise a first anode terminal bonded to a corresponding second anode terminal of the element and a first cathode terminal bonded to a corresponding second cathode terminal of the element. The first anode terminal and the first cathode terminal can be disposed on the first surface of the passive electronic component.



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BONDED STRUCTURES WITH INTEGRATED PASSIVE COMPONENT

CROSS-REFERENCE TO RELATED APPLICATIONS

[0001] This application claims priority to U.S. Provisional Patent Application No. 62/440,161, filed December 29, 2016, and to U.S. Provisional Patent Application No. 62/518,472, filed June 12, 2017, the entire contents of each of which are incorporated by reference herein in their entirety and for all purposes.

[0002] This application is also related to U.S. Patent Application No. 15/426,942, filed February 7, 2017, which is incorporated by reference herein in its entirety and for all purposes.

BACKGROUND

Field

[0003] The field relates to bonded structures with integrated passive components.

Description of the Related Art

[0004] Passive electronic components, such as capacitors, resistors, and inductors, play important roles in electronic systems. For example, passive components help smooth signals and increase the performance of active devices of the system. Incorporating passive components in an efficient manner may be challenging, since the passive components occupy valuable space on the integrated device die, the package, and/or the system board. Accordingly, there remains a continuing need for improved incorporation of passive electronic components into electronic systems.

BRIEF DESCRIPTION OF THE DRAWINGS

[0005] Figure 1A is a schematic side view of a bonded structure mounted to a carrier such as a package substrate, according to various embodiments.

[0006] Figure 1B is a schematic side view of an element and a passive electronic component prior to forming a bonded structure.

[0007] Figure 2 is a schematic, magnified side cross-sectional view of portions of the bonded structure shown in Figure 1A.

[0008] Figure 3A is a schematic side sectional view of a portion of a passive electronic component configured for relatively low speed connections.

[0009] Figure 3B is a schematic circuit diagram of the passive electronic component of Figure 3A.

[0010] Figure 4A is a schematic side sectional view of a portion of a passive electronic component configured for relatively high speed connections.

[0011] Figure 4B is a schematic circuit diagram of the passive electronic component of Figure 4A.

[0012] Figure 5A is a schematic side sectional view of a passive electronic component that incorporates a high K dielectric material to define a capacitive sheet.

[0013] Figure 5B is a schematic side sectional view of the passive electronic component of Figure 5A, with a bonding layer provided over a patterned electrode.

[0014] Figure 5C is a schematic side sectional view of a portion of the semiconductor element prior to bonding.

[0015] Figure 5D is a schematic side sectional view of a bonded structure, in which the semiconductor element is directly bonded to the passive component that includes a high K dielectric material.

[0016] Figure 5E is a schematic side sectional view of the bonded structure of Figure 5D after removal of the sacrificial base.

[0017] Figure 5F is a schematic side sectional view of a passive electronic component with integrated power electrodes and ground electrodes.

[0018] Figure 5G is a top plan view of the passive electronic component of Figure 5F.

[0019] Figure 5H is a schematic side sectional view of a passive electronic component according to another embodiment.

[0020] Figure 5I is a top plan view of the passive electronic component of Figure 5H.

[0021] Figure 6 is a plot of the transfer impedance as a function of frequency for various devices having different passive electronic components.

[0022] Figure 7A is a schematic side sectional view of a passive electronic component, according to another embodiment.

[0023] Figure 7B is a schematic side sectional view of a passive electronic component, according to yet another embodiment.

[0024] Figure 7C is a schematic side cross-sectional view of a passive electronic component, according to another embodiment.

[0025] Figure 7D is a schematic side cross-sectional view of a passive electronic component, in which capacitor(s) can be defined by aligned fibers.

[0026] Figures 8A is a schematic side sectional view of a first insulating layer, a plurality of capacitors, and a second insulating layer, prior to forming a passive electronic component.

[0027] Figure 8B is a schematic side sectional view of a first insulating layer, a plurality of capacitors, a second insulating layer, and an intermediate third insulating layer disposed between the first and second insulating layers, prior to forming a passive electronic component.

[0028] Figure 8C is a schematic side sectional view of capacitors embedded in an insulating layer, prior to forming a passive electronic component.

[0029] Figure 8D is a schematic cross-sectional view of a passive electronic component formed using any of the techniques shown in Figures 8A-8C.

[0030] Figure 8E is a schematic side sectional view of the passive electronic component shown in Figure 8D, with one or more redistribution layers (RDLs) applied to the passive electronic component.

[0031] Figure 9A is a schematic side sectional view of an insulating layer used in the formation of a passive electronic component, according to various embodiments.

[0032] Figure 9B is a schematic side sectional view of the insulating layer of Figure 9A with one or more cavities formed therein.

[0033] Figure 9C is a schematic side sectional view in which one or more capacitors are provided in the cavities.

[0034] Figure 9D is a schematic side sectional view of the device of Figure 9C after a first RDL is provided on the insulating layer.

[0035] Figure 9E is a schematic side sectional view of a passive electronic component after a second RDL is provided on an opposite side of the insulating layer.

[0036] Figure 10A is a schematic side sectional view of a first insulating carrier used to form a passive electronic component, according to another embodiment.

[0037] Figure 10B is a schematic side sectional view of the first insulating carrier with a first adhesive deposited thereon.

[0038] Figure 10C is a schematic side sectional view of the first insulating carrier with a plurality of capacitors bonded to the first insulating carrier by way of the first adhesive.

[0039] Figure 10D is a schematic side sectional view of a partially defined component in which a second insulating carrier layer is adhered to the first adhesive layer by way of a second adhesive layer.

[0040] Figure 10E is a schematic side sectional view of a passive electronic component having various interconnects and traces defined therein for electrical communication with external elements.

[0041] Figure 10F is a schematic side sectional view of a partially-fabricated passive electronic component comprising capacitors embedded in an insulating layer comprising a plurality of adhesives and a molding compound.

[0042] Figure 10G is a schematic side sectional view of a passive electronic component, according to various embodiments.

[0043] Figure 11A is a schematic side sectional view of a first insulating carrier used to form a passive electronic component, according to another embodiment.

[0044] Figure 11B is a schematic side sectional view of the first insulating carrier with a first adhesive deposited thereon.

[0045] Figure 11C is a schematic side sectional view of the first insulating carrier with a plurality of capacitors and a third insulating carrier bonded to the first insulating carrier by way of the first adhesive.

[0046] Figure 11D is a schematic side sectional view of a partially defined component in which a second insulating carrier layer is adhered to the first adhesive layer and the third carrier by way of a second adhesive layer.

[0047] Figure 11E is a schematic side sectional view of a passive electronic component having various interconnects and traces defined therein for electrical communication with external elements.

[0048] Figure 11F is a schematic side sectional view of a partially-fabricated passive electronic component comprising capacitors embedded in an insulating layer comprising a plurality of adhesives and a molding compound.

[0049] Figure 11G is a schematic side sectional view of a passive electronic component, according to various embodiments.

[0050] Figure 11H is a schematic side sectional view of a passive electronic component having additional insulating carrier layers.

[0051] Figure 11I is a schematic side sectional view of a passive electronic component having additional insulating carrier layers and a molding compound over the passive component.

[0052] Figure 12A is a schematic side sectional view of a first insulating carrier used to form a passive electronic component and having a plurality of contact pads thereon, according to another embodiment.

[0053] Figure 12B is a schematic side sectional view of the first insulating carrier with a first adhesive comprising solder that electrically and mechanically connects the capacitors to the first insulating carrier.

[0054] Figure 12C is a schematic side sectional view of the first insulating carrier with a plurality of capacitors and a molding compound disposed about the capacitors.

[0055] Figure 12D is a schematic side sectional view of a partially defined component in which a second insulating carrier layer is adhered to the first adhesive layer and the molding compound by way of a second adhesive layer.

[0056] Figure 12E is a schematic side sectional view of a passive electronic component having various interconnects and traces defined therein for electrical communication with external elements.

[0057] Figure 13A is a schematic side sectional view of a first insulating carrier used to form a passive electronic component and having a plurality of contact pads thereon, according to another embodiment.

[0058] Figure 13B is a schematic side sectional view of the first insulating carrier with a first adhesive comprising solder that electrically and mechanically connects capacitors to the first insulating carrier.

[0059] Figure 13C is a schematic side sectional view of the first insulating carrier with an insulating carrier adhered to the first insulating carrier and disposed about the capacitors.

[0060] Figure 13D is a schematic side sectional view of the partially defined component of Figure 13C, with a molding compound applied about the capacitors.

[0061] Figure 13E is a schematic side sectional view of the partially defined component with the second insulating carrier provided over the capacitors.

[0062] Figure 13F is a schematic side sectional view of a passive electronic component having various interconnects and traces defined therein for electrical communication with external elements.

[0063] Figure 14A is a schematic side sectional view of a carrier having a plurality of capacitors mounted thereto by way of an adhesive layer.

[0064] Figure 14B is a schematic side sectional view of a passive electronic component according to various embodiments.

[0065] Figure 15 is a flowchart illustrating a method for forming a bonded structure, according to various embodiments.

[0066] Figure 16 is a schematic system diagram of an electronic system incorporating one or more bonded structures, according to various embodiments.

DETAILED DESCRIPTION

[0067] Various embodiments disclosed herein related to a bonded structure comprising a semiconductor element and a passive electronic component directly bonded to the semiconductor element without an intervening adhesive. In various embodiments, the passive electronic component comprises a capacitor. In other embodiments, the passive electronic component can comprise other devices, such as an inductor, a resistor, a voltage regulator, a filter, and/or a resonator. Beneficially, the passive electronic component can be integrated into a layer of passive components that is directly bonded to the semiconductor element (such as an integrated device die). In the illustrated embodiments, for example, the layer of passive components can be disposed between the semiconductor element and another system component such as an interposer, system substrate, etc. The passive electronic component described herein can thereby reduce the space occupied by passive components at the integrated device, at the package, and/or at the system board. Moreover,

positioning the passive electronic component closer to active components of the semiconductor element can beneficially reduce overall inductance, which can improve the bandwidth and signal integrity of the semiconductor element, as compared with passive devices that are mounted to the package substrate or system board. In addition, the overall capacitance provided by the disclosed embodiments enables significantly higher capacitances (and reduced inductance) as compared with discrete passives mounted to a die.

[0068] In various embodiments, the passive component can comprise a layered capacitor structure with a massive capacitance. In some embodiments, for example, high dielectric constant (high K) wafer or sheets can be created with layered capacitors. A wafer-to-wafer bonding layer can be provided on a first element, such as a first semiconductor element or wafer (*e.g.*, a processor wafer comprising a plurality of processors), and a second element, such as a second semiconductor element or wafer (*e.g.*, a capacitor wafer that defines one or a plurality of capacitors). The first and second elements disclosed herein can comprise semiconductor elements that are formed of a semiconductor material, or can comprise other non-semiconductor elements, such as various types of optical devices (*e.g.*, lenses, filters, waveguides, etc.). In various embodiments, an additional direct bonding layer can be added and prepared for direct bonding to both the capacitor wafer and the processor wafer. The layered capacitor structures disclosed herein may be used as alternating current (AC) coupling capacitors connected in series to a signal path to filter out direct current (DC) components of signals for balanced high-speed signaling. The layered capacitor structure may also be used as a decoupling capacitor with high capacitance and extremely low parasitic inductance and resistance for reducing system power delivery network (PDN) impedance. Results show the capacitor structure enables operation for all frequency ranges with PDN impedance reduced by more than 1000 times compared with the use of discrete capacitors mounted to the die or package substrate.

[0069] The direct bond between the semiconductor element and the passive component can include a direct bond between corresponding conductive features of the semiconductor element (*e.g.*, a processor die or wafer) and the passive component (*e.g.*, a bond pad of the semiconductor element and a corresponding contact pad of the passive component) without an intervening adhesive, without being limited thereto. In some embodiments, the conductive features may be surrounded by non-conductive field regions.

To accomplish the direct bonding, in some embodiments, respective bonding surfaces of the conductive features and the non-conductive field regions can be prepared for bonding. Preparation can include provision of a nonconductive layer, such as silicon oxide, with exposed conductive features, such as metal bond pads or contacts. The bonding surfaces of the conductive features and non-conductive field regions can be polished to a very high degree of smoothness (*e.g.*, less than 20 nm surface roughness, or more particularly, less than 5 nm surface roughness). In some embodiments, the surfaces to be bonded may be terminated with a suitable species and activated prior to bonding. For example, in some embodiments, the non-conductive surfaces (*e.g.*, field regions) of the bonding layer to be bonded, such as silicon oxide material, may be very slightly etched for activation and exposed to a nitrogen-containing solution and terminated with a nitrogen-containing species. As one example, the surfaces to be bonded (*e.g.*, field regions) may be exposed to an ammonia dip after a very slight etch, and/or a nitrogen-containing plasma (with or without a separate etch). In a direct bond interconnect (DBI) process, nonconductive features of the die and the passive component layer can directly bond to one another, even at room temperature and without the application of external pressure, while the conductive features of the die and the passive component layer can also directly bond to one another, without any intervening adhesive layers. Bonding by DBI forms stronger bonds than Van der Waals bonding, including significant covalent bonding between the surfaces of interest.

[0070] In some embodiments, the respective conductive features can be flush with the exterior surfaces (*e.g.*, the field regions) of the semiconductor element and the passive component. In other embodiments, the conductive features may extend above the exterior surfaces. In still other embodiments, the conductive features of one or both of the semiconductor element and the passive component layer are recessed relative to the exterior surfaces (*e.g.*, nonconductive field regions) of the semiconductor element and the passive component. For example, the conductive features can be recessed relative to the field regions by less than 20 nm, *e.g.*, less than 10 nm.

[0071] Once the respective surfaces are prepared, the nonconductive field regions (such as silicon oxide) of the semiconductor element can be brought into contact with corresponding nonconductive regions of the passive component. The interaction of the activated surfaces can cause the nonconductive regions of the semiconductor element to

directly bond with the corresponding nonconductive regions of the passive component without an intervening adhesive, without application of external pressure, without application of voltage, and at room temperature. In various embodiments, the bonding forces of the nonconductive regions can include covalent bonds that are greater than Van der Waals bonds and exert significant forces between the conductive features. Prior to any heat treatment, the bonding energy of the dielectric-dielectric surface can be in a range from 150-300mJ/m², which can increase to 1500-4000 mJ/m² after a period of heat treatment. Regardless of whether the conductive features are flush with the nonconductive regions or recessed, direct bonding of the nonconductive regions can facilitate direct metal-to-metal bonding between the conductive features. In various embodiments, the semiconductor element and the passive component may be heated after bonding at least the nonconductive regions. As noted above, such heat treatment can strengthen the bonds between the nonconductive regions, between the conductive features, and/or between opposing conductive and non-conductive regions. In embodiments where one or both of the conductive features are recessed, there may be an initial gap between the conductive features of the semiconductor element and the passive component layer, and heating after initially bonding the nonconductive regions can expand the conductive elements to close the gap. Regardless of whether there was an initial gap, heating can generate or increase pressure between the conductive elements of the opposing parts, aid bonding of the conductive features and form a direct electrical and mechanical connection.

[0072] In some embodiments, the capacitance can be improved by providing capacitors that have electrode surfaces generally disposed along a direction non-parallel to (*e.g.*, generally perpendicular to) a major lateral surface of the element (*e.g.*, a semiconductor element). The undulations that provide the increased surfaces can be relatively simply patterned, compared to multiple layers and masks for producing laterally extending fins. The capacitor can comprise first and second electrodes that include major surfaces extending along the non-parallel direction and spaced apart by an intervening dielectric. The vertically-disposed undulations (*e.g.*, trenches) of the capacitor can have a high aspect ratio, *e.g.*, a first height of the first electrode along the non-parallel direction can be longer than a width of the capacitor along the major lateral surface. The aspect ratio, which can be defined by the first height divided by the width, can be greater than 5:1. In such embodiments, providing the

capacitor primarily vertically relative to the semiconductor element can beneficially increase the overall surface area of the electrodes, improving capacitance relative to other arrangements.

[0073] Additional details of the direct bonding processes used in conjunction with each of the disclosed embodiments may be found throughout U.S. Patent Nos. 7,126,212; 8,153,505; 7,622,324; 7,602,070; 8,163,373; 8,389,378; and 8,735,219, and throughout U.S. Patent Application Nos. 14/835,379; 62/278,354; 62/303,930; and 15/137,930, the contents of each of which are hereby incorporated by reference herein in their entirety and for all purposes.

[0074] Figure 1A is a schematic side view of a bonded structure 1 mounted to a carrier such as a package substrate 5, according to various embodiments. The illustrated carrier comprises a package substrate, but in other embodiments, the carrier can comprise an integrated device die or any other suitable element. The package substrate 5 can comprise any suitable substrate configured to mount to a system motherboard. For example, in various embodiments, the package substrate 5 can comprise a printed circuit board (PCB), an interposer, a leadframe, a ceramic substrate, a polymer substrate, or any other suitable carrier. As shown in Figure 1A, the package substrate 5 can comprise a plurality of solder balls 6 to provide electrical connection with the system motherboard (not shown). In other embodiments, the package substrate 5 can electrically connect to the system motherboard in other ways.

[0075] In Figure 1A, the bonded structure 1 comprises an element (*e.g.*, a semiconductor element 2) and a passive electronic component 3 directly electrically and mechanically connected with the element 2. The element 2 illustrated in Figure 1A comprises a semiconductor element such as a processor die, but other types of integrated device dies or semiconductor elements can be used. For example, in other embodiments, the element 2 can comprise a memory die, a microelectromechanical systems (MEMS) die, an optical device or die, an interposer, a reconstituted die or wafer, or any other suitable device or element. In various embodiments, the element 2 illustrated herein can instead comprise a non-semiconductor element such that the passive electronic component 3 can be mechanically and electrically connected to other types of elements, such as optical elements

(*e.g.*, optical lenses, waveguides, filters, etc.), which may or may not comprise a semiconductor material.

[0076] As explained herein, in various applications (such as high speed communications or power dies), it can be important to provide passive electronic components (such as a capacitor) near the active circuitry of the semiconductor element 2 in order to reduce the overall impedance and/or inductance, which can accordingly improve the signal integrity and reduce switching noise. Thus, as shown in Figure 1A, the passive electronic component 3 can be bonded to an active surface 11 of the semiconductor element 2, *i.e.*, active electronic circuitry can be defined at or near the active surface 11 of the semiconductor element 2. In the illustrated embodiment, the passive electronic component 3 is directly bonded to the active surface 11 of the semiconductor element 2 without an intervening adhesive. In other embodiments, however, the passive electronic component 3 can be adhered to the semiconductor element 2, *e.g.*, by way of a microbump array with reflow, conductive pillars, or by a thermocompression bond. Beneficially, bonding the passive electronic component 3 to the front or active surface 11 of the semiconductor element 2 can reduce the length of the signal lines and the overall impedance and/or inductance, as compared with systems which mount passive devices at the system board or package substrate. The passive component 3 can reduce the voltage requirements for the semiconductor element 2 by acting to quiet the noisy components therein. Moreover, bonding the passive electronic component 3 to the semiconductor element 2 can reduce the overall dimensions of the package, since the passives occupy a thin layer bonded to the semiconductor element 2. The skilled artisan will appreciate, however, direct bonding of passive electronic components between a carrier and a semiconductor element, for example, by way of through silicon vias (TSVs) on the back side thereof.

[0077] As shown in Figure 1A, the passive electronic component 3 can comprise a first surface 12 directly bonded to the semiconductor element 2 and a second exterior surface 13 opposite the first surface 12 of the passive electronic component 3. A plurality of electrical contacts 4 (*e.g.*, solder balls) can be provided on the second exterior surface 13 of the passive electronic component 3. The plurality of electrical contacts 4 can be configured to electrically connect to an external semiconductor element, such as the package substrate 5 shown in Figure 1A (*e.g.*, a printed circuit board, an interposer, etc.). Alternatively, the

second surfaces 13 can have exposed contacts or pads that are configured for direct bond connection to another element that serves as a carrier for the bonded structure, such as another semiconductor element (e.g., die or interposer).

[0078] As shown in Figure 1A, the passive electronic component 3 can cover (e.g., can be disposed over) a majority of the active surface 11 of the semiconductor element 2, e.g., a majority of the surface of the semiconductor element 2 that is used for processing or other active tasks. For example, in various embodiments, the passive electronic component 3 can cover at least 55%, at least 65%, at least 75%, at least 85%, at least 95%, at least 99%, or at least 100% of the active surface 11 of the semiconductor element 2. In Figure 1A, a single unitary passive component 3 is shown as covering substantially the entire active surface 11 of the semiconductor element 2; however, in other embodiments, the passive component 3 can comprise a plurality of discrete or separate passive components that are bonded to cover a majority of the active surface 11 of the element 2. In addition, in other embodiments, the passive electronic component 3 may be mechanically and electrically connected to the back side of the semiconductor element 2, *i.e.*, the surface opposite the active surface 11. In such arrangements, the length of conductors within the element 2 may be sufficiently short so as to sufficiently reduce impedance relative to routing to separate surface mounted passives on a packaging substrate, even though the passive component 3 is mounted to the back side of the element 2. Moreover, as shown in Figure 1A, the passive electronic component 3 can comprise a sheet that is bonded (e.g., directly bonded without an intervening adhesive) to the semiconductor element 2, *i.e.*, the passive electronic component 3 can be dimensioned so as to have a lateral width that is significantly larger than its thickness. For example, the passive electronic component 3 can have a lateral width (e.g., as defined along a direction parallel to the active surface 11 of the element 2) that is at least 3 times, at least 5 times, at least 10 times, or at least 50 times its thickness (e.g., as defined along a direction perpendicular to the active surface 11 of the element 2) of the component 3.

[0079] The passive electronic component 3 can be provided on a sacrificial wafer (e.g., silicon or glass), and the semiconductor element 2 can also be provided on a wafer. The two wafers can be directly bonded to one another at the wafer level (e.g., wafer-to-wafer or W2W), such that a plurality of passive components 3 can be bonded to a corresponding plurality of semiconductor elements 2, which can improve manufacturing throughput. After

bonding, the base material of the wafers can be thinned or removed prior to or after dicing. In other embodiments, the passive electronic component 3 can be picked and placed on the semiconductor element 2, or can be bonded to the semiconductor element 2 using other processing techniques.

[0080] Figure 1B is a schematic side view of a semiconductor element 2 comprising a bulk material portion 37 (*e.g.*, bulk semiconductor material) and active surface 11, and a passive electronic component 3 prior to forming a bonded structure 1. Unless otherwise noted, the features of Figure 1B may be the same as or generally similar to like-numbered features of Figure 1A. As explained above, the passive component 3 and the semiconductor element 2 can comprise respective bonding layers 8a, 8b (see also Figure 2). In the illustrated embodiment, the bonding layer 8a of the passive electronic component 3 can comprise one or a plurality of conductive features 9a, 9a', such as metal, surrounded by non-conductive field regions (see Figure 2), such as a form of silicon oxide material. Similarly, the bonding layer 8b can comprise one or a plurality of conductive features 9b, 9b', such as metal, surrounded by non-conductive field regions (see Figure 2), such as silicon oxide. The conductive features 9a, 9a', 9b, 9b' can act as electrical interconnects to provide electrical communication between the semiconductor element 2 and the passive component 3. The conductive features 9a, 9a', 9b, 9b' can comprise any suitable metal or conductor, such as copper. As explained above, the conductive features 9a, 9a', 9b, 9b' can be recessed below, can protrude above, or can be flush with, exterior surfaces of the non-conductive field regions.

[0081] In the embodiment of Figure 1B, the conductive feature 9a can comprise a first terminal (*e.g.*, an anode of a capacitive device), and the other conductive feature 9a' can comprise a second terminal (*e.g.*, a cathode of a capacitive device) that is of a different type than the first terminal. Similarly, the conductive feature 9b can comprise a first terminal of the element 2 (*e.g.*, an anode), and the other conductive feature 9a' can comprise a second terminal of the element 2 (*e.g.*, a cathode) that is of a different type than the first terminal. Beneficially, various embodiments disclosed herein can include both the anode and the cathode (*e.g.*, conductive features 9a, 9a') on the same first surface 12 of the passive electronic component 3. Thus, respective anode terminals 9b of the semiconductor element 2 can bond and electrically connect to corresponding respective anode terminals 9a of the

passive electronic component 3 disposed on the first surface 12. Respective cathode terminals 9b' of the semiconductor element 2 can bond and electrically connect to corresponding respective cathode terminals 9a' of the passive electronic component 3 disposed on the first surface 12.

[0082] Advantageously, providing the anode terminal 9a and the cathode terminal 9a' on the same first surface 12 of the passive electronic component 3 can enable wafer level bonding of two structures along the same side of the passive component 3 (*e.g.*, bonding of the semiconductor element 2 and the passive component 3). Thus, in the embodiments, disclosed herein, each opposing side of the passive component 3 can comprise one or a plurality of anodes and one or a plurality of cathodes (*e.g.*, terminals of different types). In various embodiments, one or both sides of the component 3 can comprise one or more dummy terminals. An element (such as semiconductor element 2) can have contacts connected (*e.g.*, bonded) to corresponding anode and cathode terminals on one side (*e.g.*, a first side) of the passive component. A second element (such as another semiconductor element, a package substrate, etc.) can have contacts connected (*e.g.*, bonded) to corresponding second anode and cathode terminal on the opposite side (*e.g.*, a second side) of the passive component 3. In the illustrated embodiment of Figure 1B, for example, the element 2 can connect to corresponding first and second terminals which are of a different type (*e.g.*, anode and cathode terminals) on a first side of the passive component 3. Another element (not shown) such as a package substrate can connect to corresponding first and second terminals which are of a different type (*e.g.*, anode and cathode terminals) on the second opposite side of the passive component 3, for example, by way of the interconnects 4 (which may comprise solder balls).

[0083] In various embodiments, the anode terminals 9a, 9b are directly bonded to one another without an intervening adhesive. Similarly, the cathode terminals 9a', 9b' can also be directly bonded to one another without an intervening adhesive. In various embodiments, the respective anode terminals 9a, 9b and cathode terminals 9a', 9b' can be connected by way of thermocompression bonding. In other embodiments, the respective anode terminals 9a, 9b and cathode terminals 9a', 9b' can be connected in other ways, *e.g.*, by way of a conductive adhesive, such as solder, anisotropic conductive film, etc. Furthermore, as shown in Figure 1B, various portions of the passive component 3 can have

different types of interconnects and/or passive components. For example, one portion of the passive electronic component 3 can comprise a multilayer capacitive portion, similar to the portion illustrated in Figure 2, and another portion of the passive electronic component 3 can comprise a series capacitive interconnect similar to what is shown in Figure 4A. In still other portions of the passive electronic component, a low resistance electrical pathway (*e.g.*, a through interconnect), such as that shown in Figure 3A, may be provided. Moreover, passive electronic components such as those shown in Figures 7A-7C may also include anode and cathode terminals 9a, 9a' on the same side of the component.

[0084] Figure 2 is a schematic, magnified side cross-sectional view of portions of the semiconductor element 2 and the passive electronic component 3 shown in Figures 1A-1B, just prior to direct bonding. As explained above, the passive component 3 can comprise a bonding layer 8a, and the semiconductor element 2 can comprise a bonding layer 8b. In the illustrated embodiment, the bonding layer 8a can comprise one or a plurality of conductive features 9a, 9a', such as metal, surrounded by non-conductive field regions 7a, such as a form of silicon oxide material. Similarly, the bonding layer 8b can comprise one or a plurality of conductive features 9b, 9b', such as metal, surrounded by non-conductive field regions 7b, such as silicon oxide. The conductive features 9a, 9a', 9b, 9b' can act as electrical interconnects to provide electrical communication between the semiconductor element 2 and the passive component 3. The conductive features 9a, 9a', 9b, 9b' can comprise any suitable metal or conductor, such as copper. As explained above, the conductive features 9a, 9a', 9b, 9b' can be recessed below, can protrude above, or can be flush with, exterior surfaces of the non-conductive field regions 7a, 7b. The non-conductive field regions 7a, 7b can comprise any suitable non-conductive material, such as silicon oxide, undoped or very lightly doped silicon, silicon nitride, etc., that can be prepared for direct bonding.

[0085] As explained above, the bonding layers 8a, 8b can be polished (*e.g.*, by chemical mechanical polishing, or CMP) to a very low surface roughness (*e.g.*, RMS roughness less than 20 nm, or more particularly, less than 5 nm). As explained above, the bonding layers 8a, 8b (*e.g.*, the non-conductive field regions 7a, 7b) can be activated and terminated with a suitable species, such as nitrogen, *e.g.*, by way of exposure to a nitrogen-containing plasma (*e.g.*, in a reactive ion etch) or by very slightly etching and subsequently

exposing to a nitrogen-containing (*e.g.*, ammonia) solution. The bonding layers 8a, 8b can be brought together at room temperature in some embodiments to form a direct bond between the field regions 7a, 7b. The semiconductor element 2 and the passive component 3 can be heated to strengthen the bond between the field regions 7a, 7b, and/or to cause the conductive features 9a and 9b, and 9a' and 9b' to expand and form an electrical connection. Beneficially, the use of a direct bond can provide a low impedance and low inductance electrical pathway between the semiconductor element 2 and the passive component 3, which can improve power or signal integrity.

[0086] As shown in Figure 2, the semiconductor element 2 can comprise internal conductive traces 14 and vias 15 to route electrical signals within the semiconductor element 2 and/or between the semiconductor element 2 and the passive electronic component 3. The electrical signals can pass through the conductive features 9a, 9a' and 9b, 9b' (which may be directly bonded to one another, respectively) to and/or from the passive electronic component 3. The conductive features 9a, 9a' can define, can act as, or can connect to a contact pad 21 at or near the first surface 12 of the passive electronic component 3. As shown in Figure 2, in various embodiments, the passive electronic component 3 can comprise a plurality of (*e.g.*, two or more, or three or more) conductive layers 16 spaced apart by one or a plurality of dielectric or nonconductive layers 10. As shown in Figure 2, the bonded structure 1 can include conductive features 9a, 9a', 9b, 9b' that define an interconnect structure 17 that includes the contact pads 21 and electrical pathways or interconnects 18 between the semiconductor element 2 and the electrical contacts 4 on the second surface 13 of the passive electronic component 3. In Figure 2, a plurality of conductive features 9a, 9a', 9b, 9b' are shown on each of the bonding layers 8a, 8b, which may reduce dishing. However, in other embodiments, the contact pads 21 may be defined sufficiently small so as to avoid the effects of dishing during processing. In such arrangements, each contact pad 21 can comprise one conductive feature.

[0087] Although Figure 2 illustrates three contact pads 21 and three interconnects 4, in various embodiments, the number of contact pads 21 and interconnects 4 may differ. For example, in some embodiments, the pitch of the contact pads 21 on the semiconductor element 2 and/or passive component 3 may be smaller than the pitch of the interconnects 4. In various implementations, for example, the pitch of the interconnects 4 may be

significantly greater than the pitch of the contact pads 21, *e.g.*, the pitch of the interconnects 4 may be at least 10 times, at least 20 times, at least 30 times the pitch of the contact pads 21. As an example, the pitch of the interconnects 4 can be in a range of 100 microns to 300 microns, or in a range of 100 microns to 200 microns (*e.g.*, about 150 microns). The pitch of the contact pads 21 can be in a range of 0.5 microns to 50 microns, in a range of 0.5 microns to 20 microns, or in a range of 1 micron to 10 microns (*e.g.*, about 5 microns).

[0088] In some embodiments, a first conductive interconnect 18a extends from the first surface 12 (or the contact pad 21) to a corresponding electrical contact 4 at the second surface 13 of the passive electronic component 3. Second and third conductive interconnects 18b, 18c can also extend from the contact pad 21 to corresponding electrical contacts 4 at the second surface 13. In Figure 2, for example, each of the conductive electrical interconnects 18a-18c can comprise a longitudinal conductive portion 19 extending from a corresponding contact pad 21 at or near the first surface 12 to a corresponding electrical contact 4. As shown in Figure 2, the longitudinal portions 19 can extend vertically through the thickness of the passive electronic component 3 (*e.g.*, transverse to the active surface 11 of the semiconductor element 2). The conductive interconnects 18a-18c can include one or more lateral conductive portions 20 extending laterally outward from the longitudinal conductive portions 19. The longitudinal conductive portions 19 can define resistive electrical pathways, and the one or more lateral conductive portions 20 can define capacitive electrical pathways in parallel with the resistive electrical pathways. As shown in Figure 2, the one or more lateral conductive portions 20 of the first interconnect 18a can be interleaved with the lateral portions 20 of the second interconnect 18b and can be separated by the intervening dielectric layers 10. Similarly, the lateral conductive portions 20 of the second interconnect 18b can be interleaved with the lateral portions 20 of the third interconnect 18c and can be separated by the intervening dielectric layers 10. The interleaving of the lateral portions 20 of the respective interconnects 18a-18c can define, at least in part, the respective capacitive electrical pathways, such that each lateral portion 20 acts as an electrode of a capacitor and the intervening dielectric layer 10 acts as the capacitor dielectric. In various embodiments, the dielectric layer 10 can comprise a high K dielectric layer, such as titanates, ($\text{Ba}_x\text{Sr}_{1-x}\text{TiO}_3$, $\text{Bi}_4\text{Ti}_3\text{O}_{12}$, $\text{PbZr}_x\text{Ti}_{1-x}\text{O}_3$), niobates (LiNbO_3), and/or zirconates (BaZrO_3 , CaZrO_3 etc). In other embodiments, the dielectric layer 10 may

comprise any suitable dielectric material, such as silicon oxide, silicon nitride, etc. In some embodiments, the dielectric layer can have a dielectric constant in a range of 1 to 1000. In some embodiments, the dielectric layer can have a dielectric constant in a range of 1 to 10. As explained above in connection with Figure 1B, in the illustrated embodiment, the anode and cathode terminals of the passive component 3 may be disposed along the same side of the component 3.

[0089] In various embodiments, the first and third interconnect structures 18a, 18c can be configured to connect to a power source, and the second interconnect structure 18b can be configured to connect to electrical ground, or vice versa. The passive electronic component 3 of Figure 2 can beneficially act as multi-layer decoupling capacitors in parallel connection between power and ground to reduce power delivery network (PDN) impedance so as to improve power integrity. Moreover, providing the decoupling capacitors (*e.g.*, the capacitors defined by the interconnect structures 18a-18c) near the active surface 11 of the semiconductor element 2 (*e.g.*, near switches of a processing die) can further improve the power integrity of the bonded structure 1. Decoupling capacitance (such as that provided by the disclosed embodiments) in the core region of the die can provide a stable power supply to the computation engines in electronic devices. Increasing this decoupling capacitance provides more stability in the voltage swings which reduces the amount of additional margins that are accommodated in timing analysis to account for voltage uncertainty. By contrast, adding decoupling capacitance in parallel plate structures offers relatively small capacitance values. Deep trench capacitors may provide higher capacitances but occupy a valuable footprint which may add area and cost to electronic devices.

[0090] Figure 3A is a schematic side sectional view of a portion of a passive electronic component 3 configured for relatively low speed connections. Figure 3B is a schematic circuit diagram of the passive electronic component 3 of Figure 3A. As shown in Figure 3A, the passive component 3 can comprise an electrical pathway 18 having a low resistance and low capacitance between the first and second surfaces 12, 13 of the passive component 3. For example, in Figure 3A, the pathway 18 can include a longitudinal conductive portion 19 that directly connects the contact pad 21 and the electrical contact 4. The longitudinal conductive portion 19 acts to short the signal between the contact pad 21 and the contact 4. In addition, as shown in Figure 3A, lateral conductive portions 20 can be

disposed offset from the longitudinal conductive portion 19. The lateral conductive portions 20 can be spaced from one another along the thickness of the passive component 3 and can be separated by intervening dielectric layer(s) 10. The electrical pathway 18 defined in the passive component 3 of Figures 3A-3B may be suitable for relatively low speed connections, since the longitudinal conductive portion 19 shorts the connection between the contact pad 21 and the electrical contact 4.

[0091] Figure 4A is a schematic side sectional view of a portion of a passive electronic component 3 configured for high speed series link signaling. Figure 4B is a schematic circuit diagram of the passive electronic component 3 of Figure 4A. In the series link, the passive electronic component 3 can act as a DC-blocking capacitor, which can serve various purposes. For example, the passive electronic component 3 can regulate the average DC-bias level (*e.g.*, filtering out the DC component), can protect the transmitter/receiver from destructive overload events that can occur due to poor power-up sequencing, and/or can function as part of a circuit that detects when the lines are disconnected. In these applications, the DC-blocking capacitor does not distort the high frequency components of signals passing through it. In various embodiments, all high frequency components, except the DC component of a signal, can pass through without any distortion. Hence, a large capacitance value with low connection parasitic resistance and/or inductance can be provided. The embodiment of Figures 4A-4B can be beneficial for frequencies of at least 500 MHz, although in other embodiments, lower frequency ranges may be used in conjunction with the disclosed embodiments. As shown in Figure 4A, the passive electronic component 3 can comprise an electrical pathway that includes a multi-layer capacitor disposed between the contact pad 21 and the electrical contact 4. Indeed, unlike the embodiment of Figure 3A, in Figure 4A, the pathway 18 between the contact pad 21 and the contact 4 is a capacitive electrical pathway defined by a plurality of lateral conductive portions 20 spaced apart by intervening dielectric layer(s) 10 through the thickness of the passive electronic component 3. The multiple layers shown in Figure 4A can function electrically as multiple capacitors electrically connected in series. The effective capacitance provided by the pathway 18 of Figure 4A can be in a range of 10 nF/mm² to 1μF/mm². Beneficially, in the illustrated embodiment, the capacitor(s) defined along the electrical pathway 18 can filter out DC components of signals to provide balanced, high-speed

signaling (*e.g.*, the pathway 18 can act as a high pass filter). Moreover, positioning the passive component 3 closer to the active circuitry of the semiconductor element 2 can further improve the performance of the bonded structure 1 and can reduce reflection noises.

[0092] Figures 5A-5I illustrate another embodiment in which a passive electronic component 3 is bonded (*e.g.*, directly bonded) to a semiconductor element 2. As explained above in connection with Figure 1B, in Figures 5A-5I, the anode and cathode terminals of the passive electronic component 3 can be disposed along the same side or surface of the component 3. In various arrangements, the passive component 3 can comprise a high dielectric constant (a high K) thin film capacitor layer with integrated interconnects for direct bonding and integration with other components, such as a processor. For example, in the embodiments of Figures 5A-5I, the passive component 3 can comprise dielectric materials that have a dielectric constant greater than 5, greater than 10, greater than 20, or greater than 100. Such high K materials may be difficult to manufacture, and may be processed at high temperatures that may be unsuitable for exposing other types of devices (*e.g.*, processor or other semiconductor manufacture), such that it is difficult to integrate such materials into a conventional semiconductor device. Accordingly, in the embodiments disclosed herein, the semiconductor element 2 can be manufactured in one facility (*e.g.*, a complementary metal oxide semiconductor, or CMOS, facility), and the passive component 3 can be manufactured in another facility that can accommodate the processing parameters for the high K materials. The semiconductor element 2 and the passive component 3 can be provided with bonding layers and can be directly bonded so as to connect the semiconductor element 2 and the passive component 3. Thus, the embodiments disclosed herein can enable the separate manufacture and subsequent integration of thin film, high K dielectric materials with any suitable type of semiconductor or optical element.

[0093] Figure 5A is a schematic side sectional view of a passive electronic component 3 that incorporates a high K dielectric material to define a capacitive sheet. The passive electronic component 3 can comprise a base 122 upon which the capacitive sheet can be defined. The base 122 may be sacrificial, such that the base 122 can be removed prior to bonding the passive component 3 to the semiconductor element 2. In various embodiments, the base 122 can comprise a semiconductor material, such as silicon. A first electrode 120 can be formed on the base 122 in any suitable manner. For example, the first electrode 120

can be deposited on the base 122 using a metal organic chemical vapor deposition (MOCVD) process, a physical vapor deposition (PVD) or sputtering process, or a sol-gel process (spin on and cure). The first electrode 120 can comprise a refractory metal, such as platinum (Pt) or ruthenium (Ru). In the illustrated embodiment, the first electrode 120 can be deposited as a continuous or blanket film atop the base 122, and can serve as a common electrode for multiple capacitors.

[0094] A high K dielectric layer 110 can be deposited or otherwise formed on the first electrode 120. For example, in various embodiments, the dielectric layer 110 can be deposited using CVD, PVD, powder sintering, or other suitable techniques. Beneficially, the dielectric layer 110 can have a dielectric constant greater than 5, greater than 10, greater than 20, greater than 100, or greater than 200 (*e.g.*, about 300), or greater than 1000. In various embodiments, for example, the dielectric layer can comprise a complex oxide high K material, such as the ternary oxide barium strontium titanate (BaSrTiO_3 or BST), other titanates, ($\text{Ba}_x\text{Sr}_{1-x}\text{TiO}_3$, $\text{Bi}_4\text{Ti}_3\text{O}_{12}$, $\text{PbZr}_x\text{Ti}_{1-x}\text{O}_3$), niobates (LiNbO_3), and/or zirconates (BaZrO_3 , CaZrO_3 etc). Unlike the embodiment of Figures 2-4B, therefore, only a single thin dielectric layer (rather than alternating multiple layers with conductors) may be used with the passive component 3. In some embodiments, multiple layers of dielectric material may be provided to form the dielectric layer 110.

[0095] A second electrode 121 can be deposited on the dielectric layer 110. The second electrode 121 can be any suitable conductive material, such as a refractory metal, and particularly a noble metal (*e.g.*, Pt or Ru). The refractory or noble metals of one or both of the first electrode 120 and the second electrode 121 (*e.g.*, Pt) can beneficially form a Schottky barrier (as opposed to ohmic contact) which can improve the performance of the capacitor. In the illustrated embodiment, therefore, the refractory or noble metals of the electrodes 120, 121 can remain in the final bonded structure 1 to provide improved performance. In some embodiments, the noble or refractory metal of the first and/or second electrodes 120, 121 can be plated with another metal (*e.g.*, copper) to reduce resistance. In other embodiments, however, the first and/or second electrodes 120, 121 may be removed after formation of the passive component 3 and replaced with another metal (*e.g.*, copper) to serve as the first and second electrodes 120, 121.

[0096] The second electrode 121 can be patterned to define a number of gaps 123 between portions of the second electrode 121. Patterning the electrode into a plurality of portions can define the overall capacitance provided by passive electronic component 3. For example, larger portions of the second electrode 121 may provide increased area and increased capacitance, while smaller portions of the second electrode 121 may provide reduced area and reduced capacitance. In various embodiments, the passive component 3 can comprise an array of capacitive cells, with a cell being similar to that illustrated in Figure 5A. In some embodiments, the passive component 3 can include cells having an effective capacitance per unit area of at least 5 nF/mm², at least 10 nF/mm², at least 20 nF/mm², at least 50 nF/mm², at least 100 nF/mm², or at least 200 nF/mm². For example, in various embodiments, the passive component 3 can include cells having an effective capacitance per unit area in a range of 5 nF/mm² to 400 nF/mm², in a range of 10 nF/mm² to 300 nF/mm², in a range of 10 nF/mm² to 250 nF/mm², in a range of 10 nF/mm² to 150 nF/mm², or in a range of 10 nF/mm² to 100 nF/mm². In some embodiments, for example, the passive component 3 can include cells having an effective capacitance per unit area in a range of 1 nF/mm² to 10 nF/mm², in a range of 10 nF/mm² to 100 nF/mm², in a range of 100 nF/mm² to 400 nF/mm², or above 400 nF/mm² (e.g., in a range of 400 nF/mm² to 1000 nF/mm²). Beneficially, only the high K dielectric material may be used, such that there are no low K materials in series with the high K material. By using only high K materials, the overall capacitance of the passive component 3 can be improved.

[0097] Figure 5B is a schematic side sectional view of the passive electronic component 3 of Figure 5A, with a bonding layer 8a provided over the second patterned electrode 121. The bonding layer 8a can act as an interconnect layer, such as a redistribution layer (RDL) to bond the passive electronic component 3 to other structures, such as the element 2. For example, as explained above, the bonding layer 8a can comprise conductive features 9a connected to or defining contact pads and surrounding non-conductive field regions 7a. The conductive features 9a can comprise any suitable metal such as copper. The field regions 7a can comprise any suitable non-conductive material, such as silicon oxide. As shown in Figure 5B, the non-conductive field regions 7a can be disposed in the gaps 123 of Figure 5A so as to electrically separate the patterned portions of the second electrode 121 to define separate capacitive cells in some embodiments. Advantageously, providing the

bonding layer 8a (*e.g.*, with metals such as copper) on the passive electronic component 3 can enable the use of a low temperature anneal (*e.g.*, less than 150°C) to improve the direct bond and to reduce or eliminate thermal mismatch of materials due to different coefficients of thermal expansion (CTE). Figure 5C is a schematic side sectional view of a portion of the semiconductor element 2 prior to bonding. The semiconductor element 2 can be the same as or generally similar to the semiconductor element 2 shown in Figure 2, with traces 14 and vias 15 providing electrical communication with the element 2 between the conductive features 9b and active circuitry.

[0098] Figure 5D is a schematic side sectional view of a bonded structure 1, in which the semiconductor element 2 is directly bonded to the passive component 3 that includes a high K dielectric material. As explained above, the bonding layers 8a, 8b of the passive component 3 and the semiconductor element 2 can be polished to a very low surface roughness. The polished surfaces can be activated and terminated with a desired species (such as nitrogen). The bonding layers 8a, 8b can be brought into direct contact (*e.g.*, at room temperature) to form strong bonds between the respective field regions 7a, 7b, such as oxide materials. The structure 1 can be heated to increase the bond strength and to cause electrical connection between the conductive features 9a, 9b. Thus, as shown in Figure 5D, the passive electronic component 3 can be directly bonded to the semiconductor element 2 along a direct bond interface 24 without an intervening adhesive. Beneficially, the use of a direct bond can provide a low impedance and low inductance electrical pathway between the semiconductor element 2 and the passive component 3, which can improve power or signal integrity. In other embodiments, however, the conductive features 9a, 9b can be adhered to one another with a conductive adhesive (*e.g.*, solder) or can be bonded using thermocompression bonding techniques.

[0099] As shown in Figure 5E, the base 122 can be removed from the backside of the passive electronic component 3 (for example, by grinding, polishing, etching, etc.). In some embodiments, the first electrode 120 may also be patterned to further define the capacitance of the component 3. For example, noble or refractory metals can be used during processing to define the passive electronic component 3. In some arrangements, it may be desirable to add or deposit an additional metal electrode on the refractory metal to reduce the pad resistance or to meet a specific integration requirement. In other embodiments, however,

the noble or refractory metals that serve as the first and second electrodes 120, 121 may not be removed and may thus remain in the resulting bonded structure 1. These noble or refractory metals may or may not be patterned to produce additional discrete electrode regions. In other embodiments, the first electrode 120 and/or the second electrode 121 can comprise sacrificial materials that can be removed and replaced by other metals. In Figure 5E, the passive electronic component 3 is illustrated as being laterally wider than the semiconductor element 2. However, it should be appreciated that the passive electronic component 3 may cover only a portion of the semiconductor element 2. For example, as explained above, the passive component 3 can cover at least 55%, at least 65%, at least 75%, at least 85%, at least 95%, at least 99%, or at least 100% of the active surface 11 of the semiconductor element 2.

[0100] Figure 5F is a schematic side sectional view of a passive electronic component 3 with integrated power electrodes 126 (or signal electrodes) and ground electrodes 125. Figure 5G is a top plan view of the passive electronic component 3 of Figure 5F. As shown in Figure 5F, the ground electrodes 125 can extend from the first surface 12, through the field regions 7a and the dielectric layer 110, and can contact the first electrode 120. In various embodiments, the first electrode 120 can be connected to electrical ground, which can provide a ground pin or terminal when connected with the semiconductor element 2. The power electrodes 126 shown in Figures 5A and 5B can comprise capacitive electrical pathways between the first surface 12 and the first electrode 120. Thus, when connected to the semiconductor element 2, electrical power can be transferred between the first surface 12 (by way of the conductive features 9a and/or contact pads 21) and portions of the first electrode 120, which can in turn connect to another structure, such as the package substrate 5. Although not illustrated, the first electrode 120 can be patterned or can be removed and replaced by an interconnect layer (such as a back-end of the line metallization layer) so as to provide electrical power along predefined electrical pathways.

[0101] Figure 5H is a schematic side sectional view of a passive electronic component 3 according to another embodiment. Figure 5I is a top plan view of the passive electronic component 3 of Figure 5H. Unlike the embodiment of Figures 5F and 5G, in Figures 5H and 5I, the passive electronic component 3 can include shorted power electrodes 127, in addition to the power electrodes 126 and ground electrodes 125 shown in Figures 5F

and 5G. As shown in Figure 5H, for example, some power electrodes 127 may be connected to the second surface 13 of the component 3 by way of direct conductive interconnects. Thus, in Figures 5H and 5I, the power electrodes 126 may comprise capacitive electrical pathways between the conductive features 9a (or contact pads 21) and the second surface 13, while the shorted power electrodes 127 may comprise conductive or resistive electrical pathways between the conductive features 9a (or contact pads 21) and the second surface 13.

[0102] Thus, in the embodiments of Figures 5A-5I, high K, thin film dielectric materials can be used to define the passive electronic component 3. In some embodiments, the passive component 3 may be manufactured in one facility in order to form the high K material and electrodes (which may comprise noble or refractory metals suitable for contact with high K materials), and the semiconductor element 2 can be formed in another facility to form the active components and interconnects of the element 2. Beneficially the noble or refractory metals can be provided to enable high temperature processing. As explained above, in some embodiments, the noble or refractory metals can be removed and replaced by other metals, such as copper, or by other metallization or routing layers. In other embodiments, the noble or refractory metals can be kept in the ultimate bonded structure 1. The passive component 3 can be bonded (*e.g.*, directly bonded) to the semiconductor element 2, which can provide a low impedance and low inductance connection to improve signal and/or power integrity of the bonded structure 1.

[0103] Figure 6 is a plot of the transfer impedance of various devices as a function of signal frequency, including a processor die without a capacitive element (plot A), a processor die with a 100 nF discrete capacitor mounted thereon (plot B), a processor die with a 100 nF capacitor mounted to the package substrate (plot C), a processor die with a 100 nF capacitive sheet similar to those disclosed in the embodiments of Figures 1-5I (plot D), a processor die with a 10 nF capacitive sheet similar to those disclosed in the embodiments of Figures 1-5I (plot E), and a processor die with a 1 nF capacitive sheet similar to those disclosed in the embodiments of Figures 1-5I (plot F). As shown in Figure 6, the conventional devices reflected in plots A, B, and C have relatively high transfer impedance values at frequencies above 500 MHz and/or above 1 GHz. Such high impedances above 500 MHz or 1 GHz may reduce the power or signal integrity of the processor dies. By contrast, as reflected in Plots D, E, and F, the embodiments disclosed herein enable

significantly reduced impedance at frequencies above 500 MHz, *e.g.*, at or above 1 GHz, which can provide improved signal or power integrity at these higher frequencies. For example, the embodiments disclosed herein can provide impedance at 1 GHz that is at least 10 times, *e.g.*, at least 100 times, less than the impedance of the conventional devices shown in Plots A-C. At the same capacitance levels, the directly bonded capacitance sheets show improved performance over discrete capacitors mounted on either the processor die or the package substrate. Moreover, as shown in Figure 6, the embodiments disclosed herein can provide the reduced impedance, even at significantly lower effective capacitances (*e.g.*, at capacitances as low as about 1 nF or 10 nF). Thus, the embodiments disclosed herein can advantageously provide reduced impedances with effective capacitance values in a range of about 0.5 nF to 10 mF, in a range of about 0.5 nF to 1 mF, in a range of about 0.5 nF to 1 μ F, in a range of about 0.5 nF to 150 nF, in a range of about 1 nF to 100 nF, or in a range of about 1 nF to 10 nF.

[0104] Figure 7A is a schematic side sectional view of a passive electronic component 3, according to another embodiment. Unless otherwise noted, the passive electronic component 3 of Figure 7A can be bonded to the element 2 (which may comprise a semiconductor element or a non-semiconductor element) described herein. In various embodiments, the passive electronic component can comprise a first surface 12 directly bonded to the element 2 (not shown in Figure 7A) without an intervening adhesive. A second surface 13 can electrically connect to a package substrate (such as the substrate 5) or other packaging or system structure. The passive component 3 shown in Figure 7A beneficially comprises capacitors in which a majority of electrode surfaces are disposed non-parallel to (*e.g.*, generally perpendicular to) the element 2 and the surfaces 12, 13. For example, as shown in Figure 7A, one or more capacitors 220 can be defined in which a majority of electrode surfaces generally extend parallel to the *z*-axis, which can be non-parallel or perpendicular to the major surface of the passive element 3 (*e.g.*, the *x-y* plane), *e.g.*, the surfaces 12, 13.

[0105] In the embodiment illustrated in Figure 7A, the capacitor 220 can comprise a first electrode 221a (which may comprise one of an anode and a cathode) and a second electrode 221b (which may comprise the other of the anode and the cathode) spaced apart from one another by an intervening dielectric 210. As explained above in connection

with Figure 1B, in Figure 7A, the anode and cathode terminals of the passive electronic component 3 can be disposed along the same side or surface of the component 3. The capacitor 220 can be defined within a base 205 that can comprise an insulating or dielectric material, such as silicon, silicon oxide, etc. The electrodes 221a, 221b and the dielectric 210 can include major surfaces that primarily extend along the direction non-parallel to the surfaces 12, 13, which corresponds to the z-axis in Figure 7A. In various embodiments, the capacitor 220 can have a serpentine profile extending along the x-axis. For example, as shown in Figure 7A, the electrodes 221a, 221b and dielectric 210 can have respective vertical portions 225 that are generally vertical, *e.g.*, extending along the z-axis non-parallel or perpendicular to the first and second surfaces 12, 13. The vertical portions 225 can be connected by corresponding lateral portions 226 of the electrodes 221a, 22b and dielectric 210, such that the vertical portions 225 and the lateral portions 226 define a generally serpentine capacitor within the passive element 3. As shown in Figure 7A, a capacitance C can be provided between the two electrodes 221a, 221b along the entirety of the serpentine capacitor 220. In various embodiments, the overall capacitance C along the capacitor 220 can be in a range of 100 nF/mm^2 to $20 \text{ }\mu\text{F/mm}^2$, or in a range of 100 nF/mm^2 to $10 \text{ }\mu\text{F/mm}^2$. Beneficially, the use of a serpentine capacitor in which the predominant surfaces of the capacitor 220 lie along planes parallel (or close to parallel) to the vertical z-axis can significantly increase the overall surface area of the electrodes 221a, 221b, and, therefore, can accordingly increase the overall capacitance provided by the passive element 2. The electrodes 221a, 221b can comprise any suitable type of conductor, such as aluminum, silicon, doped silicon, nickel, or other materials. The dielectric 210 can comprise any suitable dielectric material, such as aluminum oxide, silicon oxide, etc. In some embodiments, increased capacitance can be provided by using high dielectric materials (*e.g.*, $k > 10$), such as HfO_2 , ZrO_2 , BST, SBT, etc.

[0106] The capacitors 220 can electrically connect to the element 2 (not shown) by way of upper terminals 231a, 231b and to the package substrate 5 (not shown) or another element by way of lower terminals 232a, 232b. As shown in Figure 7A, first terminals 231a can provide electrical communication to the first electrode 221a. Second terminals 231b can provide electrical communication to the second electrode 221b which may be of a different type than the first terminals 231a. For example, as shown in Figure 7A, first terminals 231a

can extend through the insulating base 205 to contact an upper portion of the first electrode 221a, and can be exposed at the first surface 12 of the passive component 3. The second terminals 231b can extend through the insulating base 205 and can contact an extension portion 236 of the second electrode 221b. As shown in Figure 7A, for example, the extension portion 236 of the second electrode 221b can extend through the material of the first electrode 221a, with the dielectric 210 intervening between the first electrode 221a and the extension portion 236 of the second electrode 221b. Still other ways to electrically connect to the capacitors 220 may be suitable.

[0107] Further, as shown in Figure 7A, first lower terminals 232a can provide electrical communication to the first electrode 221a. The second lower terminals 232b can provide electrical communication to the second electrode 221b. Thus, in various embodiments, at the first surface 12, upper terminals 231a can electrically connect to the first electrodes 221a (*e.g.*, one of an anode or a cathode), and upper terminals 231b can electrically connect to the second electrodes 221b (*e.g.*, the other of an anode and a cathode). At the second surface 13, lower terminals 232a can electrically connect to the first electrodes 221a (*e.g.*, one of an anode or a cathode), and lower terminals 232b can electrically connect to the second electrodes 221b (*e.g.*, the other of an anode and a cathode). Accordingly, each surface 12, 13 can comprise anode and cathode terminals (*e.g.*, different types of terminals).

[0108] The passive electronic component 3 can also have a through signal connector 235 extending through the thickness of the passive electronic component 3. The through signal connector 235 can comprise a conductor that provides a conductive pathway between a first through signal terminal 234 on the first surface 12 and a second through signal terminal 233 on the second surface 13. Any or all of the upper terminals 231a, 231b, the lower terminals 232a, 232b, and the through signal terminals 234, 233 can be configured for direct bonding to the element 2 and/or to the system board. Thus, the passive electronic component 3 shown in Figure 7A can beneficially provide capacitive pathway(s) and conductive through signal pathway(s). Accordingly, passive devices with relatively high capacitance can be provided in line with the integrated circuit, without occupying separate real estate for the system, without interfering with direct signal connections. Disposing the capacitor 220 with a majority of electrode surfaces along (or close to parallel with) the

vertical direction can beneficially improve capacitance by significantly increasing the effective surface area of the electrodes 221a, 221b.

[0109] As shown in Figure 7A, the upper terminals 231a, 231b and the through signal terminals 234 can be laterally spaced at a finer pitch than the lower terminals 232a, 232b and the through signal terminals 233. For example, in various embodiments, an upper pitch p_1 of the terminals on the first surface 12 (*e.g.*, the terminals 231a, 231b, and 234) can be spaced at a pitch less than 50 microns, or less than 40 microns. In various embodiments, the upper pitch p_1 can be in a range of 0.5 microns to 50 microns, in a range of 0.5 microns to 40 microns, in a range of 0.5 microns to 20 microns, in a range of 0.5 microns to 10 microns, or in a range of 1 micron to 10 microns. The fine pitch of the upper terminals 231a, 231b and the terminals 234 can provide a relatively high number of channels for connection to the element 2. By contrast, a lower pitch p_2 of the lower terminals 232a, 232b and the terminals 233 can be selected for suitable connection to the system motherboard. The lower pitch p_2 can be less than 200 microns, or less than 150 microns. For example, the lower pitch p_2 can be in a range of 50 microns to 200 microns or in a range of 50 microns to 150 microns. Accordingly, the passive component serves both to provide high capacitance passive devices and serves as an interposer without occupying separate real estate.

[0110] The vertical capacitors 220 can be defined in any suitable manner. For example, the second electrode 221b can be defined from an initially planar sheet of porous silicon, porous aluminum, etc. The upper surface of the planar sheet can be masked and etched such that channels can be etched into the sheet of the second electrode 221b material. The dielectric 210 can be conformally deposited into the channels over the etched surface of the porous aluminum or porous silicon. For example, the dielectric 210 can be deposited by physical vapor deposition (PVD), chemical vapor deposition (CVD) or atomic layer deposition (ALD). An additional conductive material (*e.g.*, aluminum) can be deposited, coated or otherwise applied over the dielectric 210 to define the first electrodes 221a. In some embodiments, the first and second electrodes 221a, 221b can comprise the same material. In other embodiments, the first and second electrodes 221a, 221b can comprise different materials. Advantageously, the illustrated structure with vertical channels or fins can be readily defined with fewer masking steps compared to horizontal fins.

[0111] Figure 7B is a schematic side sectional view of a passive electronic component 3 according to another embodiment. Unless otherwise noted, reference numerals in Figure 7B refer to the same or similar features as like-numbered components in Figure 7A. For example, as with Figure 7A, the passive electronic component 3 of Figure 7B can comprise a capacitor 220 in which a majority of electrode surfaces are vertically positioned and that defines a serpentine pattern along the x-axis. Major surfaces of the first and second electrodes 221a, 221b and the intervening dielectric 210 can primarily extend non-parallel or perpendicular to the first and second surfaces 12, 13. As with Figure 7A, first upper terminals 231a can electrically connect to the first electrode 221a at or near the first surface 12. Further, as with Figure 7A, in Figure 7B, each surface 12, 13 of the passive component 3 can comprise anode and cathode terminals, such that anode and cathode terminals can be disposed along the same side or surface of the component 3 (*e.g.*, terminals 231, 231b at surface 12 and terminals 232a, 232b at surface 13). Unlike in Figure 7A, however, in which an extension portion 236 of the second electrode 221b contacts the corresponding second upper terminal 231b, in Figure 7B, a separate vertical connector 237 can extend downwardly into the passive element 3 to electrically connect the second upper terminal 231b with the second electrode 221b.

[0112] Figure 7C is a schematic side cross-sectional view of a passive electronic component 3, in which one or more serpentine capacitors may be defined along both sides of the second electrode 221b. Multiple, separate capacitors may be defined within the passive electronic component 3 in various embodiments. Unless otherwise noted, reference numerals in Figure 7C refer to the same or similar features as like-numbered components in Figures 7A and 7B. As with Figures 7A-7B, the passive electronic component 3 of Figure 7C with a majority of electrode surfaces that can extend generally vertically and non-parallel relative to the first and second surfaces 12, 13. Further, as with Figures 7A-7B, in Figure 7C, each surface 12, 13 of the passive component 3 can comprise anode and cathode terminals, such that anode and cathode terminals can be disposed along the same side or surface of the component 3 (*e.g.*, terminals 231, 231b at surface 12 and terminals 232a, 232b at surface 13). Unlike the embodiment of Figures 7A-7B, however, in Figure 7C, upper capacitor(s) 220a can be defined in an upper portion 240a of the passive component 3, and lower capacitor(s) 220b can be defined in a lower portion 240b of the passive component 3. In the embodiment

of Figure 7C, both sides of the initial planar sheet of aluminum or silicon can be masked and simultaneously etched to define channels within the second electrode 221b. Dielectric 210 can be deposited on both the upper and lower portions 240a, 240b. Similarly, conductive material can be deposited over the dielectric 210 on the upper and lower portions 240a, 240b to define the first electrode 221a. The embodiment of Figure 7C can beneficially further increase the overall surface area of the electrodes 221a, 221b and thus the overall capacitance of the passive electronic component 3.

[0113] Figure 7D is a schematic side cross-sectional view of a passive electronic component 3, in which capacitor(s) 220 can be defined by aligned fibers (*e.g.*, carbon fibers) extending along the non-parallel direction z . Unless otherwise noted, reference numerals in Figure 7D refer to the same or similar features as like-numbered components in Figures 7A-7C. As with Figures 7A-7C, the passive electronic component 3 of Figure 7D can have a majority of electrode surfaces that can extend generally vertically and non-parallel relative to the first and second surfaces 12, 13. Further, as with Figures 7A-7C, in Figure 7D, each surface 12, 13 of the passive component 3 can comprise anode and cathode terminals, such that anode and cathode terminals can be disposed along the same side or surface of the component 3 (*e.g.*, terminals 231a, 231b at surface 12 and terminals 232a, 232b at surface 13). In such embodiments, fibers (such as elongate carbon fibers) can act as the second electrode 221b. The fibers can be coated with non-conductive material to define the dielectric 210, and can be subsequently coated with conductive material to define the first electrode 221a. Still other ways of forming the vertical capacitors 220 may be suitable.

[0114] The capacitors 220 shown in Figures 7A-7D can be elongated, *e.g.*, heights l of the electrode surfaces of the capacitors 220 (*e.g.*, which may be defined by the lengths of the electrodes 221a, 221b) along the non-parallel direction z may be longer than corresponding widths w of undulations of the capacitors 220 along the major lateral surface x - y . As shown in Figures 7A-7D, the widths w can be defined according to the pitch of the capacitors 220, *e.g.*, a width of a single undulation of the capacitor. An aspect ratio of the capacitors 220 can be defined by l divided by w . In various arrangements, the aspect ratio can be greater than 5:1. Beneficially, the elongate capacitors 220 illustrated in Figures 7A-7D can provide increased electrode surface area as compared with other passive devices

without entailing greater masking steps. The increased surface areas can significantly increase overall capacitance, even when used with low dielectric constant materials.

[0115] As explained herein, various types of elements, such as dies or wafers, may be stacked in a three-dimensional arrangement as part of various microelectronic packaging schemes. This can include stacking a layer of one or more dies or wafers on a larger base die or wafer, stacking multiple dies or wafers in a vertical arrangement, and various combinations of both. Dies in the stacks can include memory devices, logic devices, processors, discrete devices, and the like. In various embodiments disclosed herein, very small or thin profile capacitors can be embedded within an insulating material and can be included in a stacked die arrangement, to decouple adjacent bonded devices, for example.

[0116] Dies or wafers may be bonded in a stacked arrangement using various bonding techniques, including direct bonding, non-adhesive techniques such as the direct bonding techniques disclosed above (see for example, U.S. Patent No. 7,485,968, which is incorporated by reference herein in its entirety). When bonding stacked dies using a direct bonding technique, it is desirable that the surfaces of the dies to be bonded be extremely flat and smooth. For instance, as explained above, the surfaces should have a very low variance in surface topology, so that the surfaces can be closely mated to form a lasting bond. It is also desirable that the surfaces be clean and free from impurities, particles, or other residue.

[0117] According to various embodiments disclosed herein, capacitors (*e.g.*, multi-layered capacitors or other passive components) can be embedded within an insulating material such as a ceramic or polymer to form wafer level stackable capacitor or other passive devices. In various embodiments, using a ceramic, polymer, or the like, results in a device that may be planarized to have a smoother bonding surface than may be possible with some other conventional insulating materials. For instance co-fired ceramic, liquid crystal polymer (LCP), glass, silicon, or other semiconductor, and like materials may be used in various embodiments. In some implementations, the ceramic is precast, or a paste or liquid may be used to form self-leveling bonding surfaces for the devices. The bonding surfaces of the capacitor devices can be planarized after firing in preparation for bonding.

[0118] The capacitors to be embedded can comprise single or multi-layered components (to provide the capacitance desired) with edge conductors to electrically couple the terminals of the capacitors. One or more of the capacitors can be embedded in an

insulating material (such as the “green sheet” illustrated in the figures) using a variety of techniques. In a first embodiment, the capacitors can be deposited on a layer of insulating material (e.g., pre co-fired ceramic), and another layer of the insulating material can be placed or deposited over the capacitors. The two layers of insulating material can be pressed together, sandwiching the capacitors, and the combination can be fired. The insulating material layers can be joined together during firing, forming a unified device, with the capacitors embedded within. Thus, in various embodiments, the dielectric material of the capacitor can be monolithically integrated with the layer(s) of insulating material.

[0119] In embodiments where the multi-layer capacitor is thicker, an additional layer of insulating material can be placed between the top and bottom insulating layers and around the capacitors (forming a middle layer that includes the capacitors). When the combination is fired, all of the insulating material layers can be joined together, forming a unified device. In various embodiments, any number of insulating layers may be used with any number of capacitors or layers of capacitors to form the device. Alternately, the capacitors can be coated with a liquid or paste insulating material that can be fired or cured to solidify the insulating material and form the embedded device.

[0120] In various embodiments, the insulating material can be selected to have a coefficient of thermal expansion (CTE) that is low, or that has a value close to the CTE value of the dies (which may be made of silicon in some examples) that will be bonded to the capacitive device. For instance, the CTE of the capacitive device can be selected to be similar to the CTE of a logic device, processor, etc., to be bonded to the capacitive device, so that the combination of devices can be packaged together (in a stacked arrangement, for instance) if desired.

[0121] Vias may be formed in the capacitive device, through the insulating material, to allow signal or power transfer through the capacitive device or to the embedded capacitors. In various implementations, the vias may be formed prior to or after firing the capacitive device. In some embodiments, redistribution layers may be formed on one or both surfaces of the capacitive device, which may be coupled to the vias if desired.

[0122] Further, conductive traces can be coupled to the edge connectors of the capacitors to form external terminals for the capacitors on one or both surfaces of the capacitive device. For instance, the terminals for the capacitors can be located one on each

surface of the capacitive device (*e.g.*, anode and cathode terminals can be on opposing sides of the capacitive device), both on a single surface of the capacitive device (*e.g.*, anode and cathode terminals can be on the same side or surface of the capacitive device), or there may be terminals for each of the edge connectors on each side of the capacitive device (*e.g.*, each surface of the capacitive device can comprise both anode and cathode terminals). Thus, for example, two terminals may be connected to one edge connector of the capacitor and may be configured to carry a power signal from one side of the capacitive device to the other. Two other terminals may be connected to a second edge connector of the capacitor and may be configured to provide a ground from one side of the capacitive device to the other. In such a configuration one side of the capacitor is coupled to a power signal and the other side of the capacitor coupled to ground. The terminals may be coupled to one or more of the vias or to a redistribution layer (RDL) (on one or both surfaces) if desired. The terminals, vias, and/or RDL connections can be formed as direct bonding interconnects on the one or more surfaces of the capacitive device, when the capacitive device is to be bonded using direct bonding techniques. In such cases, at least some of the interconnects can have a pitch in the range of a single micron, where the vias may have a size in the 10 – 15 micron range. In an embodiment, the direct bonding interconnects may only be used on one surface of the capacitive device, with the terminals for the capacitors on the one surface.

[0123] In another embodiment, one or more cavities may be formed into a surface of a pre-fired insulating material layer. A capacitor can be deposited within each cavity and vias can be formed within the insulating layer (in any order). A redistribution layer can be formed over the layer and the capacitors, embedding the capacitors within the device. The opposite surface can be planarized, and another RDL formed on the planarized surface if desired.

[0124] The techniques described can result in fewer processing steps, higher manufacturing through-put, and improved yield. Other advantages of the disclosed techniques will also be apparent to those having skill in the art.

[0125] Figures 8A-8C illustrate various techniques for embedding a capacitor 220 in an insulating layer, according to various embodiments. Figures 8D-8E are schematic side sectional views of the passive electronic component 3 which can be formed using any of the techniques shown in Figures 8A-8C. Figures 8A is a schematic side sectional view of a first

insulating layer 260a, a plurality of capacitors 220, and a second insulating layer 260b, prior to forming the passive electronic component. The embodiments shown in Figures 8A-8C illustrate a plurality of capacitors 220, which may be used in wafer-level processing. In other embodiments, only one capacitor 220 may be provided. The capacitors 220 can comprise any suitable type of capacitor, including, *e.g.*, single-layered capacitors with a single dielectric layer between two conductive electrode layers, or multi-layered capacitors having a plurality of dielectric layers between a plurality of conductive electrode layers. The capacitors 220 may also be similar to or the same as any of the capacitive structures disclosed herein, including horizontally- or vertically-oriented capacitors. The first and second insulating layers 260a, 260b can comprise any suitable type of insulating or non-conductive material, such as a ceramic, a glass, or a polymer. In various embodiments, the first and second insulating layers 260a, 260b can comprise ceramics, such as aluminum oxide. In other embodiments, the first and second insulating layers 260a, 260b can comprise polymers, such as liquid crystal polymer (LCP).

[0126] In various embodiments, the first and second insulating layers 260a, 260b can comprise soft or flexible ceramic green sheets, *e.g.*, ceramic sheets that when heated or fired at or above a suitable firing temperature, harden to form a stiffer ceramic material. In such embodiments, the capacitor 220 can be provided on the first insulating layer 260a. The second insulating layer 260b can be provided (*e.g.*, deposited) on the capacitor 220. The first and second layers 260a, 260b can be pressed together such that the first and second layers 260a, 260b contact one another in gaps 262 and around edge portions 261 of the capacitors 220. In various embodiments, the first and second layers 260a, 260b can accordingly conform around the capacitors 262 and can contact one another when pressed. After the pressing, the first and second layers 260a, 260b and the embedded capacitors 220 can be fired or co-fired at a temperature at or above a ceramic firing temperature so as to cause the first and second layers 260a, 260b to meld or blend together to form a harder or stiffer structure.

[0127] The first and second layers 260a, 260b can comprise the same material in various embodiments. In other embodiments, the first and second layers 260a, 260b can comprise different materials. In arrangements in which the first and second layers 260a, 260b comprise different materials, the materials can be selected such that the materials

harden at or around the same firing or co-firing temperature, *e.g.*, the temperature or temperature range at which the first and second layers 260a, 260b are sufficiently hardened. For example, some materials may comprise high temperature ceramics (*e.g.*, with a firing temperature at or above 1000 °C) or low temperature ceramics (*e.g.*, those with a firing temperature at or above 500 °C or at or above 600 °C, *e.g.*, between 500 °C and 1200 °C, or between 550 °C and 1100 °C. The resulting passive electronic component 3 is illustrated in Figure 8D, which is described in more detail below.

[0128] Figure 8B is a schematic side sectional view of a first insulating layer 260a, a plurality of capacitors 220, a second insulating layer 260b, and an intermediate third insulating layer 260c disposed between the first and second insulating layers 260a, 260b, prior to forming the passive electronic component. Unless otherwise noted, the embodiment of Figure 8B is generally similar to or the same as the embodiment of Figure 8A. For example, like Figure 8A, the method for forming a passive component of Figure 8B may also form the passive component 3 shown in Figure 8D. Unlike in Figure 8A, however, in Figure 8B, the intermediate third insulating layer 260c can be deposited around the side edges 261 of the capacitors 220 prior to firing. Beneficially, the third intermediate layer 260c can have a thickness selected such the first and second layers 260a, 260b can contact the intermediate layer 260c with little or no applied pressure. In other arrangements, pressure may be applied to cause the first layer 260a to contact the third layer 260c and to cause the third layer 260c to contact the second layer 260b. After pressing the first and second layers 260a, 260b together (with the third layer 260c intervening therebetween), the first layer 260a, second layer 260b, third layer 260c, and the capacitors 220 can be co-fired at a temperature sufficient to cause the layers 260a-260c to meld or otherwise join together to form a unitary or unified device, *e.g.*, the unified passive component 3 shown in Figure 8D.

[0129] Figure 8C is a schematic side sectional view of capacitors 220 embedded in an insulating layer 260, prior to forming the passive electronic component. Unless otherwise noted, the embodiment of Figure 8C is generally similar to or the same as the embodiments of Figures 8A-8B. For example, like in Figures 8A-8B, the method for forming a passive component of Figure 8B may also form the passive component 3 shown in Figure 8D. However, in the embodiments of Figures 8A-8B, the first, second, and third insulating layers 260a-260c may be formed prior to depositing or connecting to the

capacitors 220. Unlike the embodiments of Figures 8A-8B, in the embodiment of Figure 8C, a powder or other solid mixture can be provided on a carrier 263. The capacitors 220 can be provided over the powder or mixture, and a solution can be added to the powder or mixture. The solution can cause the powder or mixture to thicken into a soft, flexible insulating layer 260 (*e.g.*, a soft ceramic or polymer). The resulting soft, flexible layer 260 can be molded or otherwise formed over and around the capacitors 220 to embed the capacitors 220 within the insulating layer 260. After molding or forming the insulating layer 260 over the capacitors 220, the insulating layer 260 and the capacitors 260 can be co-fired at a temperature sufficient to cause the layer 260 to meld, mix or otherwise join together to form a unitary or unified device, *e.g.*, the unified passive component 3 shown in Figure 8D. The carrier 263 can be removed after co-firing. The embodiment of Figure 8C can beneficially enable the formation of a passive component without utilizing multiple deposition processes, such as those shown in Figures 8A-8B. Rather, the base insulating layer 260 can be formed about the capacitors 220 and co-fired to form the passive component 3 in relatively few process steps.

[0130] Figure 8D is a schematic cross-sectional view of a passive electronic component 3 formed using any of the techniques shown in Figures 8A-8C. The passive electronic component 3 may include features similar to or the same as those shown in Figures 7A-7D, such that reference numerals in Figure 8D may represent similar components to like reference numerals of Figures 7A-7D, except where noted. After co-firing the structures of Figures 8A-8C, the capacitors 220 can be embedded within a layer 250 of insulating material. In the illustrated embodiment, for example, the capacitors 220 can be completely embedded in the layer 250 such that the layer 250 of insulating material is disposed along the side edges 261 of the capacitor 220, as well as along upper and lower surfaces 264a, 264b of the capacitor 220. In Figure 8D, the layer 250 of insulating material can comprise a first insulator 210a formed by firing or co-firing the assemblies shown in Figures 8A-8C. Thus, the first insulator 210a can comprise a hardened ceramic, polymer, glass, etc.

[0131] As with Figures 7A-7D, the capacitors 220 shown in Figure 8D can be defined at least in part by a first electrode 221a, a second electrode 221b, and a second insulator 210b intervening between the first and second electrodes 221a, 221b. The first and second insulators 210a, 210b can be selected so as to have similar co-firing temperatures,

and/or with a relatively low CTE that matches the components to which the passive electronic component 3 is to be bonded (*e.g.*, a semiconductor element 2, which may comprise silicon). In various embodiments, the insulators 210a, 210b comprise the same material. In other embodiments, the insulators 210a, 210b comprise different materials that each have firing temperatures at which the layers 210a, 210b both harden and merge or meld with one another. Thus, after co-firing the assemblies shown in any of Figures 8A-8C, the first and second insulators 210a, 210b can merge or mix with one another to form a monolithically integrated and unified or unitary structure. For example, co-firing the first and second insulators 210a, 210b can cause portions of the first insulator 210a to merge or mix with portions of the second insulator 210b, *e.g.*, at the boundary between the two insulators 210a, 210b. In the embodiment of Figure 8D, therefore, the monolithically integrated insulator 210a of the layer 250 may seamlessly integrate with the insulator 210b of the capacitor 220. As explained above, in various embodiments, the insulators 210a, 210b can comprise dielectrics in various embodiments, *e.g.*, ceramic dielectrics. In other embodiments, the insulators 210a and/or 210b may comprise polymers, glass, etc.

[0132] In various embodiments, as with the embodiments of Figures 7A-7D, the capacitor 220 can comprise first terminal(s) 232a connected to the corresponding first electrode(s) 221a. Second terminal(s) 232b can be connected to corresponding second electrode(s) 221b of the capacitor 220. Each of the first and second terminals 232a, 232b can be defined at least in part by respective outermost layers of the electrodes 221a, 221b (*e.g.*, those electrodes 221a, 221b disposed at or near the respective upper and lower surfaces 264a, 264b of the capacitor 220), and by edge connectors 251a, 251b that electrically connect respective alternating electrodes 221a, 221b. For example, as shown in Figure 8D, the first edge connector 251a can be disposed vertically, *e.g.*, non-parallel relative to the electrodes 221a and can electrically connect respective ends of the electrodes 221a. Similarly, the second edge connector 251b can be disposed vertically, *e.g.*, non-parallel relative to the electrodes 221b and can electrically connect respective ends of the electrodes 221b. As explained above, the electrodes 221a, 221b may be of a different type, *e.g.*, one electrode 221a may comprise an anode and the other electrode 221b may comprise a cathode, or vice versa.

[0133] Furthermore, as with the embodiments of Figures 7A-7B, one or more through signal connectors 235 (*e.g.*, conductive vias) can extend through the thickness of the passive electronic component 3, from a first surface 265a of the insulating layer 250 to a second surface 265b of the insulating layer 250. In some embodiments, the through signal connectors 235 can be formed after co-firing and forming the passive component 3. For example, in some embodiments, the insulating layers 260a, 260b, and/or 260c, and the capacitors 220 can be co-fired to form a passive component. Subsequently, holes can be provided (*e.g.*, drilled, etched, etc.) through the insulating layer 250, and the through signal connectors 235 can be provided or deposited in the holes. In such an arrangement, in which the signal connectors 235 are formed after firing, the conductive material for the connectors 235 may not be able to withstand the high temperatures used during the firing or co-firing process. In other embodiments, however, the connectors 235 can comprise a conductor with material properties configured to withstand the high temperatures used for firing the structure. In such arrangements, the connectors 235 may be co-fired along with the capacitors 220 and insulating layers 260a-260c.

[0134] Figure 8E is a schematic side sectional view of the passive electronic component 3 shown in Figure 8D, with one or more redistribution layers (RDLs) 252a, 252b (*e.g.*, interconnect layer(s)) applied to the passive electronic component 3. The RDLs 252a, 252b can be provided on at least one of the first surface 265a and the second surface 265b of the insulating layer 250. The RDLs 252a, 252b can be pre-formed in some embodiments, prior to providing on the component 3. For example, in some embodiments, the RDLs 252a, 252b can be pre-formed and directly bonded to the component 3 without an intervening adhesive. In other arrangements, the RDLs 252a, 252b can be built up in layers over the insulating layer 250. The RDLs 252a, 252b can be configured to route electrical signals between selected terminals of the capacitors 220 and corresponding terminals or contact pads of the element(s) to which the passive electronic component 3 is to be connected. For example, in the embodiment of Figure 8E, a first RDL 252a can be provided over the first surface 265a of the insulating layer 250. A second RDL 252b can be provided over the second surface 265b of the insulating layer 250. The RDLs 252a, 252b can comprise a plurality of metallic traces at least partially embedded in corresponding RDL insulating layers 266a, 266b. The first surface 12 of the passive component 3 can be defined at an

upper surface of the RDL 252a, and the second surface 13 of the passive component 3 can be defined at a lower surface of the RDL 252b.

[0135] As shown in Figure 8E, first conductive traces 253a or conductive vias of the respective RDLs 252a, 252b can electrically connect to the first electrodes or terminals 221a of the capacitor at or by way of the first terminals 232a. As shown, the traces 253a or vias (also referred to as interconnect(s)) can extend through at least a portion of the insulating material, or insulator 210b to connect to respective terminals of the capacitor. Similarly, second conductive traces 253b of the respective RDLs 252a, 252b can electrically connect to the second electrodes 221b at or by way of the second terminals 232b. In the illustrated embodiment, the terminals 232a, 232b can be defined at least in part by respective portions of the edge connectors 251a, 252b (which connect interleaving electrodes 221a, 221b.), and by outermost electrodes 221a, 221b (*e.g.*, the electrodes 221a, 221b at or near the respective first or second surfaces 265a, 265b of the capacitors 220). Thus, electrical connection to the respective electrodes 221a, 222b can be made to the edge connectors 251a, 251b and/or to the outermost electrodes 221a, 221b at the surfaces 265a, 265b.

[0136] The traces 253a, 253b can electrically connect the terminals 232a, 232b to respective interconnects 254a, 254b at the first or second surfaces 265a, 265b of the insulating material layer 250. As shown in Figure 8E, the interconnects 254a, 254b can extend through the RDL insulators 266a, 266b and can be exposed at the first and second surfaces 12, 13. In various embodiments, as explained below, the insulating layers 266a, 266b can act as respective layers or substrates through which the interconnects (or portions thereof) can extend to connect to the capacitor. The exposed surfaces of the interconnects 254a, 254b can be configured to electrically connect to other elements, such as elements 2 (*e.g.*, semiconductor elements such as integrated device dies), package substrates, interposers, etc. As explained herein, the RDL insulating layers 266a, 266b and the exposed surfaces of the interconnects 254a, 254b at the surfaces 12, 13 can be polished and prepared for direct bonding in various embodiments. The insulating layers 266a, 266b and the exposed interconnects 254a, 254b can be directly bonded to corresponding insulating and/or conductive features of other elements, without an intervening adhesive. In some embodiments, elements may be bonded to both surfaces 12, 13 of the component 3. In other embodiments, elements may be bonded to only one surface 12 or 13 of the passive

component 3. In still other embodiments, the insulating layers 266a, 266b and/or the interconnects 254a, 254b can be bonded to the other elements with various adhesives.

[0137] As with the above-described embodiments, in some arrangements, each surface 12, 13 of the passive component 3 can comprise first and second respective interconnects 254a, 254b that connect to different types of terminals 232a, 232b on each side of the capacitor 220. For example, each of the surfaces 265a, 265b of the insulating material 250 can comprise an anode and a cathode terminal. In other embodiments, however, one surface 265a can comprise anode terminal(s) and the other surface 265b can comprise cathode terminal(s). Still other combinations of terminals can be provided herein, based on, *e.g.*, the structure of the RDLs 252a, 252b and how they route electrical signals. For example, in the embodiments disclosed herein, some terminals 232a may connect to electrical power, and other terminals 232b may connect to electrical ground, or vice versa.

[0138] Figures 9A-9E illustrate a process for forming a passive electronic component 3 according to various embodiments. Unless otherwise noted, the components of Figures 9A-9E can be similar to or the same as like numbered components of Figures 7A-8E. Figure 9A is a schematic side sectional view of an insulating layer 250. The insulating layer 250 can comprise any suitable type of insulator, such as a ceramic, a polymer, a glass, a semiconductor (*e.g.*, silicon), etc. Turning to Figure 9A, one or more cavities 267 can be formed in the insulating layer 250, *e.g.*, by etching, drilling, etc. The through signal interconnects 235 (or conductive vias) can also be provided through at least a portion of the thickness of the insulating layer 250. For example, in some embodiments, holes can be formed (*e.g.*, drilled, etched, etc.), and conductive material can be provided in the holes to form the vias or interconnects 235. In Figure 9C, one or more capacitors 220 can be provided in the cavities 267. In some embodiments, a low CTE insulating filler 268 can be provided over and/or around the capacitors 220 in the cavities 267 in order to support, stabilize, and/or reduce stress on the capacitors 220.

[0139] As shown in Figure 9D, the first RDL 252a can be provided over the first surface 265a of the insulating layer 250. Interconnects 254a in the first RDL 252a can connect to corresponding terminals 232a of the capacitor 220, and other interconnects 254b (not shown) in the first RDL 252a can connect to corresponding terminals 232b of the capacitor 220. For example, portions of the interconnects 254a, 254b can extend through the

insulating layer 266a, 266b of the RDLs 252a, 252b (which can act as insulating layers or substrates) to connect to the capacitor. In Figure 9E, the back side of the insulating material 250 can be partially removed (*e.g.*, polished, grinded, etched, etc.) to expose the surface 264b of the capacitor 220 and the ends of the vias 235. The second RDL 252b can be provided over the surface 265b of the insulating material 250 and the surface 264b of the capacitor 220. As explained above, the RDLs 252a, 252b can be bonded (*e.g.*, direct bonded in some arrangements) to the insulating layer 250 and the capacitors 220. In other embodiments, the RDLs 252a, 252b can be bonded in other ways, *e.g.*, using adhesives. In still other embodiments, the RDLs 252a, 252b can be built up layer-by-layer.

[0140] As with the embodiment of Figures 8D-8E, in Figure 9E, the capacitor 3 can be embedded in the insulating layer 250, which can act as an insulating element between the insulating layers 266a, 266b. For example, as shown in Figure 9E, the insulating layer 250 can be disposed along the side edges 261 of the capacitors 220, and may cover a majority of the side edges 261, *e.g.*, all or substantially the entirety of the side edges 261. In the embodiment of Figure 9E, the RDLs 252a, 252b can be provided over the upper and lower surfaces 264a, 264b of the capacitors 220. Unlike Figures 8D-8E, however, in Figure 9E, the capacitor 3 is not monolithically integrated with the insulating material 250, but is instead inserted in the cavities 267 (with the filler 268). As with other embodiments disclosed herein, each surface 12, 13 of the passive component 3 can comprise different types of terminals, *e.g.*, each surface 12, 13 can comprise an anode terminal or interconnect and a cathode terminal or interconnect. In other embodiments, one surface 12 may comprise only anode terminals or interconnects, and the other surface 13 may comprise only cathode terminals or interconnects, or vice versa. In various embodiments, a pitch of the interconnects 254a and/or 254b on the first surface 12 of the component may have a pitch smaller than a pitch of the interconnects 254a, 254b on the second surface 13. For example, the interconnects 254a and/or 254b on the first surface 12 may be spaced and configured for direct bonding to another element. In some embodiments, a pitch of the interconnects 254a and/or 254b on the first surface 12 can be 50 microns or less, 10 microns or less, or 1 micron or less. In some embodiments, terminals of the capacitor 220 can be connected to corresponding interconnects 254a and/or 254b of the RDL at the first surface 12, and may not be connected to any interconnects at the second surface 13, or vice versa.

[0141] Figures 10A-10G illustrate another method for forming a passive electronic component 3 in which the passive component is embedded in an insulating layer 250. Figure 10A is a schematic side sectional view of a first insulating substrate 270a. The first insulating substrate 270a can comprise any suitable type of insulator, such as a ceramic, a polymer, a glass, an insulating composite, etc. Beneficially, the substrates 270a, 270b can comprise a material that has a coefficient of thermal expansion (CTE) of no more than 6 ppm/°C, or no more than 5 ppm/°C. In various embodiments, the CTE of the substrates 270a, 270b can be in a range of 2 ppm/°C to 6 ppm/°C, in a range of 3 ppm/°C to 6 ppm/°C, or in a range of 3 ppm/°C to 5 ppm/°C. In various embodiments, the substrates 270a, 270b can comprise the same material. In other embodiments, the substrates 270a, 270b may comprise different materials. Turning to Figure 10B, a first adhesive 250a can be applied or deposited on the first insulating substrate 270a. The first adhesive 250a can comprise any suitable type of adhesive, such as an insulating adhesive. In various embodiments, the first adhesive 250a can comprise a non-conductive epoxy.

[0142] In Figure 10C, the capacitors 220 can be provided (*e.g.*, placed, deposited, etc.) on the first adhesive layer 250a. In some embodiments, the capacitors 220 can partially embed within the first adhesive layer 250a such that at least a portion of the first adhesive layer 250a is disposed along the side edge 261 of the capacitor 220 and that at least another portion of the first adhesive layer 250a is disposed along the second surface 264b of the capacitor 220. In Figure 10D, a second adhesive layer 250b can be provided or applied over and around the capacitors 220. As shown in Figure 10D, at least a portion of the second adhesive layer 250b can be disposed along the side edge 261 of the capacitor 220, and at least another portion of the second adhesive layer 250b can be disposed along the first surface 264a of the capacitor 220. A second insulating substrate 270b (which may comprise the same insulating material or a different insulating material from the first substrate 270a). Thus, in Figure 10D, the insulating layer 250 can comprise the first and second adhesive layers 250a, 250b, and the capacitors 220 can be fully embedded within the insulating layer.

[0143] Turning to Figure 10E, conductive interconnects can be formed in the passive component 3. For example, the through conductive vias 235 can be provided in through holes provided through the thickness of the passive component 3, so as to provide through electrical communication in the component 3. Additionally, interconnects 254a,

254b can be formed in corresponding holes of the insulating substrates 270a, 270b in order to electrically connect with corresponding terminals 232a, 232b of the capacitors 220. Thus, in the embodiments disclosed herein, the insulating substrates 270a, 270b can act as interconnect layers to provide electrical communication with other elements or devices. As with other embodiments disclosed herein, each surface 12, 13 of the passive component 3 can comprise different types of terminals, *e.g.*, each surface 12, 13 can comprise an anode terminal or interconnect 254a and a cathode terminal or interconnect 254b. In other embodiments, one surface 12 may comprise only anode terminals or interconnects, and the other surface 13 may comprise only cathode terminals or interconnects, or vice versa.

[0144] As shown in Figure 10E, the adhesives 250a, 250b can serve as an insulating element disposed between the first and second substrates. The interconnects 254a, 254b can act as conductive vias that extend through at least a portion of the insulating element (*e.g.*, portions of the first and second adhesives 250a, 250b). Further, the interconnects 254a, 254b can extend through the substrates 270a, 270b to connect to the capacitors. The adhesives 250a, 250b can be disposed adjacent to (and/or contacting) side edges of the capacitor 220. As shown, the capacitors 220 can be disposed in a first region between the first and second substrates 270a, 270b, and the insulating element (*e.g.*, adhesives 250a, 250b of the insulating material 250) can be disposed in a different second region between the first and second substrates 270a, 270b. Beneficially, the use of the low CTE substrates 270a, 270b and intervening insulating material 250 can provide the overall passive component 3 with a low overall effective CTE that is close to the CTE of the component(s) to which the passive component 3 is to be mounted, *e.g.* a semiconductor or silicon substrate. In such arrangements, beneficially, the overall effective CTE of the passive component 3 (*e.g.*, including the insulating and conductive materials shown in Figure 10E) can be no more than 8 ppm/°C, no more than 7 ppm/°C, or no more than 6 ppm/°C. In various embodiments, the overall effective CTE of the passive component 3 (also referred to as a microelectronic device herein) can be in a range of 3 ppm/°C to 7 ppm/°C, in a range of 4 ppm/°C to 8 ppm/°C, or in a range of 4 ppm/°C to 7 ppm/°C.

[0145] Figure 10F illustrates an alternative method for forming a passive component after the step shown in Figure 10C. For example, subsequent to providing the capacitors 220 on the first adhesive layer 250a in Figure 10C, instead of providing the second

adhesive 250b over the capacitors 220 and the first adhesive layer 250a as shown in Figure 10D, a molding compound 269 can be provided at least around the side edges 261 of the capacitors 220. The molding compound 269 can comprise an insulating sub-layer of the insulating layer 250, *e.g.*, the molding compound 269 can comprise a non-conductive epoxy, encapsulant, etc. In some embodiments, the molding compound 269 may be applied around only the side edges 261. In other embodiments, the molding compound 269 can be applied around the side edges 261 and the surfaces 264a of the capacitors. The portions of the molding compound 269 over the surfaces 264a may be removed in any suitable manner.

[0146] Further, as shown in Figure 10F, the second adhesive layer 250b (which can comprise a non-conductive or insulating adhesive) can be applied over the first surface 264a and the upper surface of the molding compound 269. The second insulating substrate 270b can be provided over the second adhesive layer 250b. Thus, in the embodiment of Figure 10F, the insulating layer 250 can comprise the first and second adhesive layers 250a, 250b and the molding compound 269. The capacitors 220 can be embedded in (*e.g.*, completely embedded in) the insulating layer 250. Turning to Figure 10G, as with Figure 10E, through vias 235 and interconnects 254a, 254b can be provided to provide electrical communication through the component 3 and to the capacitors 220, respectively.

[0147] The adhesives 250a, 250b, and the molding compound 269 can serve as an insulating element disposed between the first and second substrates 270a, 270b. The interconnects 254a, 254b can act as conductive vias that extend through at least a portion of the insulating element (*e.g.*, portions of the first and second adhesives 250a, 250b). Further, the interconnects 254a, 254b can extend through the substrates 270a, 270b to connect to the capacitors. In Figure 10G, the adhesives 250a, 250b can be disposed adjacent to (and/or contacting) upper surfaces of the capacitor 220. The molding compound 269 can be disposed adjacent to (and or contacting) side edges of the capacitors 220. The capacitors 220 can therefore be embedded within the insulating element (*e.g.*, embedded within the adhesives 250a, 250b and the molding compound 269). As shown, the capacitors 220 can be disposed in a first region between the first and second substrates 270a, 270b, and at least a portion of the insulating element (*e.g.*, adhesives 250a, 250b of the insulating material 250) can be disposed in a different second region between the first and second substrates 270a, 270b. Beneficially, the use of the low CTE substrates 270a, 270b and intervening insulating

material 250 can provide the overall passive component 3 with a low overall effective CTE that is close to the CTE of the component(s) to which the passive component 3 is to be mounted, *e.g.* a semiconductor or silicon substrate. In such arrangements, beneficially, the overall effective CTE of the passive component 3 (*e.g.*, including the insulating and conductive materials shown in Figure 10G) can be no more than 8 ppm/°C, no more than 7 ppm/°C, or no more than 6 ppm/°C. In various embodiments, the overall effective CTE of the passive component 3 (also referred to as a microelectronic device herein) can be in a range of 3 ppm/°C to 7 ppm/°C, in a range of 4 ppm/°C to 8 ppm/°C, or in a range of 4 ppm/°C to 7 ppm/°C. The component 3 of Figures 10A-10G can comprise a laminated structure in which a plurality of substrates (such as substrates 270a, 270b) can be coupled to one or more capacitors, *e.g.* by way of one or more adhesives and/or by way of a molding compound. In the illustrated embodiments, the substrates 270a, 270b may comprise materials or layers that are laminated or applied to the capacitor 220 without being deposited using a deposition process.

[0148] Figures 11A-11G illustrate another method for forming a passive electronic component 3 in which the passive component is embedded in an insulating layer 250. Figures 11A-11B are generally the same as Figures 10A-10B, respectively. In Figure 11C, however, a third insulating substrate 270c can be provided over the first adhesive layer 250a and around the capacitors 220. The third insulating substrate 270c may be the same material as the substrates 270a, 270b. In other embodiments, the material of the third substrate 270c may differ from the material(s) of the substrates 270a, 270b. The first adhesive layer 250a can be provided over the second surface 264b and over portions of the side edges 261. As shown in Figure 11C, beneficially, first via portions 235a can be provided through the third insulating substrate 270. The first via portions 235a can define a part of the through signal via or interconnect 235.

[0149] As with Figure 10D, in Figure 11D, the second adhesive 250b can be provided over and around the capacitors 220. For example, the second adhesive layer 250b can be provided around portions of the side edges 261 of the capacitors 220 and over the first surfaces 264a of the capacitors 220. The second insulating substrate 270b can be provided or deposited over the second adhesive layer 250b. Thus, in Figure 11D, the capacitors 220 can be embedded in the insulating layer 250, which can comprise the first and second adhesive

layers 250a, 250b. In the illustrated embodiment, for example, the capacitors 220 can be completely or fully embedded in the insulating layer 250, such that portions of the insulating layer cover most or all of the surfaces of the capacitors 220.

[0150] Turning to Figure 11E, interconnects 254a, 254b can be provided to connect to the terminals 232a, 232b of the capacitors 220. Second via portions 235b can be provided in each of the first and second insulating substrates 270a, 270b. The second via portions 235b can be electrically connected to the first via portions 235a formed through the third insulating substrate 270c. For example, in some embodiments, the first via portions 235a can be directly bonded to corresponding second via portions 235b without an intervening adhesive. In other embodiments, the first via portions 235a can be bonded to second via portions 235b with a conductive adhesive. Advantageously, using the first via portions 235a in the third insulating substrate 270c can enable a layer-by-layer construction of the resulting through via or interconnect 235, without providing through holes through the insulating layer 250. Instead, the third insulating substrate 270c can have a thickness about the same as the thickness of the capacitors 220 such that separate vias need not be formed through the insulating layer 250.

[0151] As above, the adhesives 250a, 250b, and the third substrate 270c can serve as an insulating element disposed between the first and second substrates 270a, 270b. The interconnects 254a, 254b can act as conductive vias that extend through at least a portion of the insulating element (*e.g.*, portions of the first and second adhesives 250a, 250b). Further, the interconnects 254a, 254b can extend through the substrates 270a, 270b to connect to the capacitors. In Figure 11E, the insulating material 250 can be disposed adjacent to (and/or contacting) upper surfaces of the capacitor 220 and side edges of the capacitors 220. The capacitors 220 can therefore be embedded within the insulating element. As shown, the capacitors 220 can be disposed in a first region between the first and second substrates 270a, 270b, and at least a portion of the insulating element (*e.g.*, portions of adhesives 250a, 250b and the third substrate(s) 270c) can be disposed in a different second region between the first and second substrates 270a, 270b. Beneficially, the use of the low CTE substrates 270a, 270b, the third intervening substrate 270c, and intervening insulating material 250 can provide the overall passive component 3 with a low overall effective CTE that is close to the CTE of the component(s) to which the passive component 3 is to be mounted, *e.g.* a

semiconductor or silicon substrate. In such arrangements, beneficially, the overall effective CTE of the passive component 3 (*e.g.*, including the insulating and conductive materials shown in Figure 11E) can be no more than 8 ppm/°C, no more than 7 ppm/°C, or no more than 6 ppm/°C. In various embodiments, the overall effective CTE of the passive component 3 (also referred to as a microelectronic device herein) can be in a range of 3 ppm/°C to 7 ppm/°C, in a range of 4 ppm/°C to 8 ppm/°C, or in a range of 4 ppm/°C to 7 ppm/°C.

[0152] Figure 11F illustrates an alternative method for forming a passive component after the step shown in Figure 11C. For example, subsequent to providing the capacitors 220 on the first adhesive layer 250a in Figure 11C, instead of providing the second adhesive 250b over the capacitors 220, the third substrate 270c, and the first adhesive layer 250a as shown in Figure 11D, a molding compound 269 can be provided at least around the side edges 261 of the capacitors 220. The molding compound 269 can comprise an insulating sub-layer of the insulating layer 250, *e.g.*, the molding compound 269 can comprise a non-conductive epoxy, encapsulant, etc. In some embodiments, the molding compound 269 may be applied around only the side edges 261. In other embodiments, the molding compound 269 can be applied around the side edges 261 and the surfaces 264a of the capacitors. The portions of the molding compound 269 over the surfaces 264a may be removed in any suitable manner.

[0153] Further, as shown in Figure 11F, the second adhesive layer 250b (which can comprise a non-conductive or insulating adhesive) can be applied over the first surface 264a and the upper surface of the molding compound 269. The second insulating substrate 270b can be provided over the second adhesive layer 250b. Thus, in the embodiment of Figure 11F, the insulating layer 250 can comprise the first and second adhesive layers 250a, 250b and the molding compound 269. The capacitors 220 can be embedded in (*e.g.*, completely embedded in) the insulating layer 250. Turning to Figure 11G, as with Figure 11E, through vias 235 and interconnects 254a, 254b can be provided to provide electrical communication through the component 3 and to the capacitors 220, respectively.

[0154] The adhesives 250a, 250b, and the molding compound 269 (*e.g.*, the insulating material 250) can serve as an insulating element disposed between the first and second substrates 270a, 270b. The interconnects 254a, 254b can act as conductive vias that extend through at least a portion of the insulating element (*e.g.*, portions of the first and

second adhesives 250a, 250b). Further, the interconnects 254a, 254b can extend through the substrates 270a, 270b to connect to the capacitors. In Figure 11G, the adhesives 250a, 250b can be disposed adjacent to (and/or contacting) upper surfaces of the capacitor 220. The molding compound 269 can be disposed adjacent to (and/or contacting) side edges of the capacitors 220. The capacitors 220 can therefore be embedded within the insulating element (e.g., embedded within the adhesives 250a, 250b and the molding compound 269). As shown, the capacitors 220 can be disposed in a first region between the first and second substrates 270a, 270b, and at least a portion of the insulating element (e.g., adhesives 250a, 250b of the insulating material 250 and the molding compound 269) can be disposed in a different second region between the first and second substrates 270a, 270b. Beneficially, the use of the low CTE substrates 270a, 270b and intervening insulating element can provide the overall passive component 3 with a low overall effective CTE that is close to the CTE of the component(s) to which the passive component 3 is to be mounted, e.g. a semiconductor or silicon substrate. In such arrangements, beneficially, the overall effective CTE of the passive component 3 (e.g., including the insulating and conductive materials shown in Figure 11G) can be no more than 8 ppm/°C, no more than 7 ppm/°C, or no more than 6 ppm/°C. In various embodiments, the overall effective CTE of the passive component 3 (also referred to as a microelectronic device herein) can be in a range of 3 ppm/°C to 7 ppm/°C, in a range of 4 ppm/°C to 8 ppm/°C, or in a range of 4 ppm/°C to 7 ppm/°C.

[0155] Figures 11H and 11I illustrate alternative arrangements to Figures 11E and 11G, respectively. In Figure 11H, for example, additional insulating substrates 270d can be provided around the capacitors 220. The substrate 270d may comprise a material that is the same as or different from the substrates 270a-270c. In Figure 11I, the molding compound 269 can be provided as part of the insulating layer 250. The features of Figures 11H and 11I may otherwise be generally similar to the features explained above in Figures 11A-11G. The component 3 of Figures 11A-11I can comprise a laminated structure in which a plurality of substrates (such as substrates 270a, 270b) can be coupled to one or more capacitors, e.g., by way of one or more adhesives, by an intervening third substrate 270c, and/or by way of a molding compound. In the illustrated embodiments, the substrates 270a, 270b may comprise materials or layers that are laminated or applied to the capacitor 220 without being deposited using a deposition process.

[0156] Figures 12A-12E illustrate another method for forming a passive electronic component 3. In Figure 12A, the first insulating substrate 270a can have a plurality of conductive contact pads 275 on an exterior surface thereof. In Figure 12B, the capacitors 220 can be connected to the contact pads 275 of the substrate 270a by way of a first adhesive, *e.g.*, by way of a conductive adhesive 276, which comprises solder in the illustrated embodiment. In other embodiments, the capacitors 220 can be connected to the contact pads 275 by direct bonding without an intervening adhesive. Turning to Figure 12C, a molding compound 269 can be provided around and/or over the capacitors 220 and over surfaces of the substrate layer 270a.

[0157] In Figure 12D, the adhesive layer 250b can be applied over the upper surface of the molding compound 269 and over the first surfaces 264a of the capacitors 220. The second insulating substrate 270b can be provided over the adhesive layer 250b. In the embodiment of Figure 12D, therefore, the capacitors 220 can be embedded in the insulating layer 250, which can be defined by the molding compound 269 (which is applied over the second surfaces 264b of the capacitors 220 and the side edges 261) and the adhesive layer 250b (which is applied over the first surfaces 264a of the capacitors 220). In the illustrated embodiment, the capacitors 220 can be completely or fully embedded in the insulating layer 250. In Figure 12E, as explained above, various traces and interconnects 254a, 254b can penetrate through a portion of the insulating layer 250 to connect to terminals of the capacitors 220.

[0158] The insulating material 250 (*e.g.*, the adhesive 250b and molding compound 269) can serve as an insulating element disposed between the first and second substrates 270a, 270b. The interconnects 254a, 254b can act as conductive vias that extend through at least a portion of the insulating element (*e.g.*, portions of the adhesive 250b). Further, the interconnects 254a, 254b can extend through the substrates 270a, 270b to connect to the capacitors. In Figure 12E, the molding compound 269 can be disposed adjacent to side edges of the capacitors 220. The capacitors 220 can therefore be embedded within the insulating element (*e.g.*, embedded within the adhesive 250b and the molding compound 269). As shown, the capacitors 220 can be disposed in a first region between the first and second substrates 270a, 270b, and at least a portion of the insulating element can be disposed in a different second region between the first and second substrates 270a, 270b.

Beneficially, the use of the low CTE substrates 270a, 270b and intervening insulating element can provide the overall passive component 3 with a low overall effective CTE that is close to the CTE of the component(s) to which the passive component 3 is to be mounted, *e.g.* a semiconductor or silicon substrate. In such arrangements, beneficially, the overall effective CTE of the passive component 3 (*e.g.*, including the insulating and conductive materials shown in Figure 12E) can be no more than 8 ppm/°C, no more than 7 ppm/°C, or no more than 6 ppm/°C. In various embodiments, the overall effective CTE of the passive component 3 (also referred to as a microelectronic device herein) can be in a range of 3 ppm/°C to 7 ppm/°C, in a range of 4 ppm/°C to 8 ppm/°C, or in a range of 4 ppm/°C to 7 ppm/°C. The component 3 of Figures 12A-12E can comprise a laminated structure in which a plurality of substrates (such as substrates 270a, 270b) can be coupled to one or more capacitors, *e.g.*, by way of one or more adhesives, and/or by way of a molding compound. In the illustrated embodiments, the substrates 270a, 270b may comprise materials or layers that are laminated or applied to the capacitor 220 without being deposited using a deposition process.

[0159] Figures 13A-13E illustrate another method for forming a passive electronic component 3. In Figure 13A, the first insulating substrate 270a can have a plurality of conductive contact pads 275 on an exterior surface thereof. In Figure 13B, the capacitors 220 can be connected to the contact pads 275 of the substrate 270a by way of a first adhesive, *e.g.*, by way of a conductive adhesive 276, which comprises solder in the illustrated embodiment. In other embodiments, the capacitors 220 can be connected to the contact pads 275 by direct bonding without an intervening adhesive. Turning to Figure 13C, a third insulating substrate 270c with first via portions 235a can be adhered to the first adhesive layer 250a, which can comprise a non-conductive adhesive. In Figure 13D, the molding compound 269 can be provided underneath the surfaces 264b and around the side edges 261 of the capacitors 220. In Figure 13E, the second adhesive layer 250b can be applied over the first surfaces 264a of the capacitors, and over the upper surfaces of the molding compound 269 and the third substrate layer 270c. The second substrate layer 270b can be provided over the second adhesive layer 250b. In Figure 13F, various interconnects 254 and through vias 235 can be provided, as explained above.

[0160] The adhesives 250a, 250b, molding compound 269, and substrate 270c can serve as an insulating element disposed between the first and second substrates 270a, 270b. The interconnects 254a, 254b can act as conductive vias that extend through at least a portion of the insulating element. Further, the interconnects 254a, 254b can extend through the substrates 270a, 270b to connect to the capacitors. In Figure 11G, the molding compound 269 can be disposed adjacent to (and or contacting) side edges of the capacitors 220. The capacitors 220 can therefore be embedded within the insulating element. As shown, the capacitors 220 can be disposed in a first region between the first and second substrates 270a, 270b, and at least a portion of the insulating element can be disposed in a different second region between the first and second substrates 270a, 270b. Beneficially, the use of the low CTE substrates 270a, 270b and intervening insulating element can provide the overall passive component 3 with a low overall effective CTE that is close to the CTE of the component(s) to which the passive component 3 is to be mounted, *e.g.* a semiconductor or silicon substrate. In such arrangements, beneficially, the overall effective CTE of the passive component 3 (*e.g.*, including the insulating and conductive materials shown in Figure 13F) can be no more than 8 ppm/°C, no more than 7 ppm/°C, or no more than 6 ppm/°C. In various embodiments, the overall effective CTE of the passive component 3 (also referred to as a microelectronic device herein) can be in a range of 3 ppm/°C to 7 ppm/°C, in a range of 4 ppm/°C to 8 ppm/°C, or in a range of 4 ppm/°C to 7 ppm/°C. The component 3 of Figures 13A-13F can comprise a laminated structure in which a plurality of substrates (such as substrates 270a, 270b) can be coupled to one or more capacitors, *e.g.*, by way of one or more adhesives, an intervening substrate 270c, and/or by way of a molding compound. In the illustrated embodiments, the substrates 270a, 270b may comprise materials or layers that are laminated or applied to the capacitor 220 without being deposited using a deposition process.

[0161] Figures 14A and 14B illustrate another embodiment of a technique for forming a passive electronic component 3. In Figure 14A, a carrier 277 can be provided. The adhesive layer 250a can be applied over the carrier 277. The substrate layer 270 can be adhered to the carrier 277 with the adhesive layer 250a, and the capacitors 220 can be applied within a cavity of the substrate layer 270a (or the substrate layer 270 can be applied about previously deposited capacitors 220). The molding compound 269 (which can have a low CTE as explained above) can be applied about the capacitors 220, *e.g.*, about the side

surfaces 261 of the capacitors 220. The insulating layer 250 can be defined at least in part by the molding compound 269 and the adhesive layer 250a, such that the capacitors 220 are embedded in the insulating layer 250, *e.g.*, partially embedded in the insulating layer 250. The carrier 277 can be removed in various embodiments, and RDLs 252a, 252b can be provided on opposing sides of the capacitors 220, molding compound 269, and insulating substrate 270. In Figures 14A-14B, the interconnects 254a, 254b can extend through insulating portions of the RDLs 252a, 252b (see layers 266a, 266b above) to connect to terminals of the capacitors 220. The overall effective CTE of the passive component 3 (*e.g.*, including the insulating and conductive materials shown in Figure 14B) can be no more than 8 ppm/°C, no more than 7 ppm/°C, or no more than 6 ppm/°C. In various embodiments, the overall effective CTE of the passive component 3 (also referred to as a microelectronic device herein) can be in a range of 3 ppm/°C to 7 ppm/°C, in a range of 4 ppm/°C to 8 ppm/°C, or in a range of 4 ppm/°C to 7 ppm/°C. As above, the component 3 can comprise a laminated structure.

[0162] As explained herein, the embodiments of the passive components 3 (*e.g.*, a microelectronic component) of Figures 8A-14B can be bonded (*e.g.*, directly bonded without an intervening adhesive) to one or more other elements (such as one or more semiconductor elements). In some embodiments, the passive components 3 of Figures 8A-14B can be directly bonded to an element on one side of the component 3. In other embodiments, the passive component 3 can be directly bonded to elements on opposite sides of the passive component 3 such that the passive component 3 is between the elements. Indeed, such bonded structures can be realized for any and/or all of the embodiments disclosed herein.

[0163] Figure 15 is a flowchart illustrating a method 70 for forming a bonded structure, according to various embodiments. The method 70 can begin in a block 72 to provide an element having one or more active devices. The element can comprise a semiconductor element in various embodiments. In other embodiments, the element can comprise a material that may or may not comprise a semiconductor material. In embodiments that utilize a semiconductor element, such as a processor die, the element can be manufactured in a semiconductor processing facility to define the active devices on a wafer using semiconductor processing techniques (such as complementary metal oxide semiconductor, or CMOS, processing). A bonding layer for direct bonding can be formed on

the element in the semiconductor processing facility using the semiconductor processing techniques. For example, as explained above, conductive features and non-conductive field regions can be defined at or near an exterior surface of the element. Beneficially, the bonding layer can enable the use of a low temperature anneal to improve bonding and reduce thermal mismatch.

[0164] In a block 74, a passive electronic component can be directly bonded to the element without an intervening adhesive. In various embodiments, anode and cathode terminals of the passive electronic component may be provided along the same side of the passive component. The passive component can be any suitable passive component described herein, including a capacitor. The capacitor can have a massive capacitance defined by a high K dielectric in some embodiments. In other embodiments, the capacitor can comprise a dielectric with a lower dielectric constant, such as silicon oxide or silicon nitride. In some embodiments, the passive electronic component can be manufactured in a facility that is different from the semiconductor processing facility used to manufacture the element. Manufacturing the passive component in a different facility can enable the use of high temperature processing to form high K dielectric layers in some embodiments. As with the element, a bonding layer can also be formed on the passive electronic component.

[0165] The wafer comprising the element and the wafer comprising the passive electronic component can be prepared for direct bonding as explained above. For example, the bonding layers can be polished to a very high surface smoothness, and can be activated and terminated with a desired species. The nonconductive field regions can be brought into contact with one another at room temperature to form a direct bond. The element and the passive component can be heated to strengthen the bond and/or to cause electrical contact between the conductive features.

[0166] In some embodiments, after direct bonding, additional interconnects can be provided on the bonded structure to provide a next level of communication with the package substrate. For example, any temporary carriers, such as the base 122 can be removed. One or more layers of conductive routing material (such as a back end of the line, or BEOL, layer) can be provided to improve the reliability of electrical connections with other components (such as a package substrate, interposer, or other die). The bonded wafer

can be singulated, *e.g.*, by sawing. The singulated bonded structures can be assembled into a package, *e.g.*, the structures can be attached to a package substrate.

[0167] In some embodiments, such as the embodiment shown in Figures 7A-7B, the passive electronic component can comprise one or a plurality of elongate capacitors in which a majority of electrode surfaces are vertically disposed. The element can define a major lateral surface. The capacitor can comprise major surfaces of the first and second electrodes extending along a direction non-parallel to the major lateral surface of the component, with the first and second electrodes spaced apart by a dielectric. In some embodiments, the capacitors can be defined by providing a plurality of fibers extending along the non-parallel direction to define a plurality of capacitors. The plurality of fibers can serve as first electrodes and be coated with a non-conductive material to define the dielectric and subsequently coated with a conductive material to define second electrodes. Still other ways of forming the capacitors may be suitable.

[0168] In some embodiments, such as those shown in Figures 8A-14B, the passive electronic component can comprise a capacitor embedded in an insulating layer. In some embodiments, as explained above, the capacitor can be provided between one or more green sheets, and the capacitor and green sheets can be co-fired to form the hardened passive electronic component. In other embodiments, the capacitor can be provided in a cavity of an insulating layer. In still other embodiments, the capacitor can be provided on a first adhesive layer, and a second adhesive layer can be provided over the capacitor. First and second insulating carrier layers can couple to the first and second adhesive layers, respectively. In some embodiments, a molding compound can be provided about the passive component between the first and second adhesive layers.

[0169] Figure 16 is a schematic system diagram of an electronic system 80 incorporating one or more bonded structures 1, according to various embodiments. The system 80 can comprise any suitable type of electronic device, such as a mobile electronic device (*e.g.*, a smartphone, a tablet computing device, a laptop computer, etc.), a desktop computer, an automobile or components thereof, a stereo system, a medical device, a camera, or any other suitable type of system. In some embodiments, the electronic system 80 can comprise a microprocessor, a graphics processor, an electronic recording device, or digital memory. The system 80 can include one or more device packages 82 which are

mechanically and electrically connected to the system 80, *e.g.*, by way of one or more motherboards. Each package 82 can comprise one or more bonded structures 1. The system 80 shown in Figure 16 can comprise any of the structures 1 and passive components 3 shown and described herein.

[0170] In one embodiment, a bonded structure is disclosed. The bonded structure an element and a passive electronic component directly bonded to the element without an intervening adhesive. In some embodiments, the passive electronic component comprises a capacitor.

[0171] In another embodiment, a bonded structure is disclosed. The bonded structure can include an element having one or more active devices at or near an active surface of the element. The bonded structure can comprise a passive electronic component bonded to the element. The passive electronic component can comprise a sheet having a lateral width at least three times its thickness, the sheet covering a majority of the active surface of the element. In some embodiments, the passive electronic component can comprise a capacitor.

[0172] In another embodiment, a method of forming a bonded structure is disclosed. The method can include providing an element having one or more active devices. The method can include directly bonding a passive electronic component to the element without an intervening adhesive. In some embodiments, the passive electronic component can comprise a capacitor.

[0173] In one embodiment, a microelectronic device is disclosed. The microelectronic component can comprise a layer of insulating material having a first surface and a second surface. A multi-layer capacitor can be embedded within the layer of insulating material, between the first surface and the second surface. One or more conductive vias can be formed through the layer of insulating material, from the first surface to the second surface. A redistribution layer can be disposed on at least one of the first surface and the second surface, and arranged to electrically couple one or more terminals of the capacitor to one or more interconnects at the at least one of the first surface and the second surface.

[0174] In some embodiments, the redistribution layer can be configured to electrically couple two terminals of the multi-layer capacitor to at least two interconnects at the first surface, and no interconnects at the second surface. The redistribution layer can

have a substantially planar surface and the one or more interconnects have a pitch of 1 micron or less. The insulating material can comprise a ceramic, a glass, or a liquid crystal polymer.

[0175] In another embodiment, a method for forming a microelectronic device is disclosed. The method can comprise depositing a multi-layer capacitor on a first layer of insulating material. The method can comprise depositing a second layer of insulating material over the multi-layer capacitor and the first layer of insulating material. The method can comprise pressing the second layer of the insulating material over the multi-layer capacitor and the first layer of the insulating material. The method can comprise co-firing the second layer of the insulating material, the multi-layer capacitor, and the first layer of the insulating material to form a unified device.

[0176] In some embodiments, the method can comprise depositing an intermediate layer of the insulating material between the first and second layers, and around the capacitor prior to the pressing and the co-firing. The method can comprise forming one or more vias through the first and second layers of the insulating material after the co-firing. The method can comprise forming one or more vias through the first and second layers of the insulating material prior to the co-firing. The method can comprise forming a redistribution layer on an exterior surface of the first or second layers of the insulating material, the redistribution layer including one or more electrical interconnects coupled to one or more terminals of the capacitor. The redistribution layer can include at least one interconnect coupled to each of the terminals of the capacitor. The method can comprise bonding the redistribution layer to a prepared bonding surface, by a direct bonding technique without adhesive.

[0177] In another embodiment, a method for forming a microelectronic device is disclosed. The method can comprise forming a cavity in a surface of an insulating layer. The method can comprise forming one or more vias through at least a portion of the thickness of the insulating layer. The method can comprise depositing a multi-layer capacitor into the cavity. The method can comprise forming a redistribution layer over the capacitor and the insulating layer, the redistribution layer including one or more electrical interconnects coupled to one or more terminals of the capacitor.

[0178] In some embodiments, the method can comprise planarizing a surface of the insulating layer opposite the redistribution layer, and forming another redistribution layer on the planarized surface. The other redistribution layer can include one or more electrical interconnects coupled to one or more terminals of the capacitor.

[0179] In another embodiment, a bonded structure is disclosed. The bonded structure can comprise an element and a passive electronic component having a first surface bonded to the element and a second surface opposite the first surface. The passive electronic component can comprise a capacitor between the first surface and the second surface. The capacitor can comprise first and second terminals on a first surface of the capacitor, a first conductive electrode electrically connected to the first terminal, a second conductive electrode electrically connected to the second terminal, and a high K dielectric between the first and second conductive electrodes.

[0180] In some embodiments, the high K dielectric comprises a ceramic. The element can be directly bonded to the passive electronic component without an intervening adhesive. The ceramic dielectric can comprise at least one of a titanate, a niobate, and a zirconate.

[0181] In another embodiment, a microelectronic device is disclosed. The microelectronic device can include an insulating material having a first surface and a second surface. A capacitor can be embedded within the insulating material, between the first surface and the second surface, the capacitor monolithically integrated with the insulating material to define a monolithic structure. A first interconnect can be disposed at or through the first surface and electrically connected to a first terminal of the capacitor. The capacitor can comprise a ceramic dielectric. The ceramic dielectric can comprise aluminum oxide. The capacitor can comprise a multi-layer capacitor having a plurality of dielectric layers between a plurality of conductive layers. The ceramic dielectric can be monolithically integrated with the insulating material. A redistribution layer (RDL) can be connected to one of the first surface and the second surface, the first interconnect at least partially disposed in the RDL. A second interconnect can be disposed at the first surface and electrically connected to a second terminal of the capacitor, the first terminal of a different type than the second terminal. A through conductive via can extend through the insulating layer from the first surface to the second surface. The layer of insulating material can be disposed along an

upper surface of the capacitor, along a lower surface of the capacitor, and along side edges of the capacitor.

[0182] In another embodiment, a microelectronic device is disclosed. The microelectronic device can comprise an insulating material having a first surface and a second surface opposite the first surface. A capacitor can be at least partially embedded within the insulating material, between the first surface and the second surface. An interconnect layer can be disposed on the first surface, and can be arranged to electrically couple one or more terminals of the capacitor to one or more interconnects at or extending through the first surface of the insulating material.

[0183] In some embodiments, the capacitor can be completely embedded within the insulating material. The capacitor can be partially embedded within the insulating material, the insulating material disposed along outer side edges of the capacitor. The microelectronic device can comprise a first insulating substrate, wherein a first surface of the capacitor is mechanically coupled to the first insulating substrate by way of a first adhesive, the insulating material comprising the first adhesive. The microelectronic device can comprise a second insulating substrate, the second surface of the capacitor mechanically coupled to the second insulating substrate by way of a second adhesive, the insulating material further comprising the second adhesive. A molding compound can be disposed about portions of the capacitor, the insulating material further comprising the molding compound. A third intermediate insulating substrate can be disposed about the capacitor between the first and second insulating substrate. The first adhesive can comprise solder in some embodiments. A second interconnect layer can be disposed on the second surface, and can be arranged to electrically couple one or more terminals of the capacitor to one or more interconnects at the second surface of the insulating material. The microelectronic device can include a first interconnect and a second interconnect in the interconnect layer, the first interconnect connected to a first terminal of the capacitor at a first side of the capacitor and the second interconnect connected to a second terminal at the first side, the first terminal of a different type from the second terminal. The microelectronic device can include a third terminal at a second side of the capacitor and a fourth terminal at the second side, the third terminal of a different type from the fourth terminal. The layer of insulating material comprises multiple layers in some embodiments. The microelectronic device can include a

conductive through via extending through the insulating material. In some embodiments, a bonded structure can comprise the microelectronic device and an element, the element directly bonded to the microelectronic device without an intervening adhesive.

[0184] In another embodiment, a microelectronic device is disclosed. The microelectronic component can comprise a first insulating substrate and a capacitor having a first surface and a second surface opposite the first surface, the first surface of the capacitor mechanically coupled to the first insulating substrate. The microelectronic device can include a second insulating substrate, the second surface of the capacitor mechanically coupled to the second insulating substrate such that the capacitor is disposed between the first and second insulating substrates. An insulating element can be disposed between the first and second insulating substrates. A first interconnect can extend through the first insulating substrate to electrically connect to a first terminal of the capacitor.

[0185] In some embodiments, the first surface of the capacitor can be mechanically coupled to the first insulating substrate by way of a first adhesive, the insulating element comprising the first adhesive. The second surface of the capacitor can be mechanically coupled to the second insulating substrate by way of a second adhesive, the insulating element further comprising the second adhesive. The first adhesive can comprise solder in some embodiments. The insulating element can comprise a molding compound disposed about portions of the capacitor. The insulating element can comprise a third intermediate insulating substrate disposed about the capacitor between the first and second insulating substrates. A coefficient of thermal expansion (CTE) of one or more of the first and second insulating substrates can be no more than 5 ppm/°C. The CTE of the one or more of the first and second insulating substrates can be in a range of 2 ppm/°C to 5 ppm/°C. An overall effective coefficient of thermal expansion (CTE) of the microelectronic device can be no more than 7 ppm/°C. The overall effective CTE can be in a range of 3 ppm/°C to 7 ppm/°C. A second interconnect can extend through the first insulating substrate, the first interconnect connected to a first terminal of the capacitor at a first side of the capacitor and the second interconnect connected to a second terminal at the first side, the first terminal of a different type from the second terminal. The microelectronic component can comprise a third terminal at a second side of the capacitor and a fourth terminal at the second side, the third terminal of a different type from the fourth terminal. At least a portion of the insulating

element can be disposed adjacent a side edge of the capacitor. The capacitor can be disposed in a first region between the first and second substrates and at least a portion of the insulating element is disposed in a second region between the first and second substrates, the first and second regions different from one another. A bonded structure can comprise the microelectronic device and an element, the element directly bonded to the microelectronic device without an intervening adhesive.

[0186] In another embodiment, a method of forming a microelectronic device is disclosed. The method can comprise mechanically coupling a first surface of a capacitor to a first insulating substrate. The method can comprise mechanically coupling a second surface of the capacitor to a second insulating substrate such that the capacitor is disposed between the first and second insulating substrates. The method can comprise disposing an insulating element between the first and second insulating substrates. The method can comprise providing a first interconnect extending through the first insulating substrate to electrically connect to a first terminal of the capacitor.

[0187] In some embodiments, the method can comprise adhering the capacitor to the first insulating substrate with an adhesive. The method can comprise adhering the second substrate to the capacitor with a second adhesive. The method can comprise providing a molding compound around at least a portion of the capacitor between the first and second insulating substrates.

[0188] In another embodiment, a bonded structure is disclosed. The bonded structure can comprise an element and a passive electronic component having a first surface bonded to the element and a second surface opposite the first surface. The passive electronic component can comprise a first anode terminal bonded to a corresponding second anode terminal of the element and a first cathode terminal bonded to a corresponding second cathode terminal of the element, the first anode terminal and the first cathode terminal disposed on the first surface of the passive electronic component.

[0189] In some embodiments, the passive electronic component is directly bonded to the element without an intervening adhesive. The passive electronic component can comprise a capacitor. The capacitor can comprise three or more metallic layers spaced apart by a plurality of dielectric layers. The passive electronic component can comprise a third anode terminal and a third cathode terminal on the second surface of the passive

electronic component. The element can comprise a semiconductor element. The bonded structure can comprise a plurality of electrical contacts on the second surface of the passive electronic component, the plurality of electrical contacts configured to electrically connect to an external component. The bonded structure can comprise an interconnect structure defining an electrical pathway between the element and a first electrical contact of the plurality of electrical contacts. The interconnect structure can comprise a conductive electrical interconnect that extends from the first surface to the first electrical contact, the conductive electrical interconnect embedded within a dielectric disposed between the first and second surfaces. The conductive electrical interconnect can comprise a longitudinal conductive portion extending from a first contact pad at or near the first surface to the first electrical contact and one or more lateral conductive portions extending laterally outward from the longitudinal conductive portion, the longitudinal conductive portion defining a resistive electrical pathway and the one or more lateral conductive portions defining a capacitive electrical pathway in parallel with the resistive electrical pathway. The element can define a major lateral surface and the capacitor comprises first and second electrode surfaces extending along a direction non-parallel to the major lateral surface, the first and second electrode surfaces spaced apart by a dielectric. A first height of the first electrode surface along the non-parallel direction can be longer than a width of an undulation of the capacitor along the major lateral surface. An aspect ratio can be defined by the first height divided by the width, the aspect ratio being greater than 5:1. At least one of the first electrode surface and the second electrode surface can comprise aluminum, silicon, doped silicon, or nickel. The capacitor can comprise a serpentine pattern extending through the passive electronic component. The serpentine pattern can comprise respective vertical portions of the first and second electrode surfaces and corresponding lateral portions of the first and second electrode surfaces that connect the vertical portions.

[0190] In another embodiment, a bonded structure is disclosed. The bonded structure can comprise an element having one or more active devices at or near an active surface of the element, the active surface defining a major lateral surface of the bonded structure. The bonded structure can comprise a passive electronic component bonded to the element, the passive electronic component comprising a capacitor having first and second

electrode surfaces extending along a direction non-parallel to the major lateral surface, the first and second electrode surfaces spaced apart by a dielectric.

[0191] In some embodiments, the passive electronic component can be directly bonded to the element without an intervening adhesive. A first height of the first electrode surface along the non-parallel direction can be longer than a width of an undulation of the capacitor along the major lateral surface. An aspect ratio can be defined by the first height divided by the width, the aspect ratio being greater than 5:1. At least one of the first electrode surface and the second electrode surface can comprise aluminum. The capacitor can comprise a serpentine pattern extending through the passive electronic component. The serpentine pattern can comprise respective vertical portions of the first and second electrode surfaces and corresponding lateral portions of the first and second electrode surfaces that connect the vertical portions. The bonded structure can comprise a first terminal electrically connected to the first electrode surface and a second terminal electrically connected to the second electrode surface, the first and second terminals exposed at an upper surface of the passive electronic component. An extension portion of the second electrode surface can extend through the first electrode surface to connect to the second terminal.

[0192] In another embodiment, a bonded structure is disclosed. The bonded structure can comprise an element and a passive electronic component having a first surface bonded to the element and a second surface opposite the first surface. The passive electronic component can comprise a passive device. The passive device can include first and second terminals on the first surface of the passive electronic component, a first conductive interconnect electrically connected to the first terminal, a second conductive interconnect electrically connected to the second terminal, and a dielectric between the first and second conductive interconnects.

[0193] In some embodiments, the element can be directly bonded to the passive electronic component without an intervening adhesive. The passive device can comprise a capacitor.

[0194] In another embodiment, a bonded structure is disclosed. The bonded structure can comprise an element and a passive electronic component directly bonded to the element without an intervening adhesive.

[0195] In some embodiments, the passive electronic component can comprise a capacitor. The capacitor can comprise three or more metallic layers spaced apart by a plurality of dielectric layers. The capacitor can comprise a dielectric layer having a dielectric constant in a range of 1 to 10. The passive electronic component can comprise a first electrode, a second electrode, and a dielectric material between the first and second electrodes, wherein the dielectric material comprises a high K dielectric. The high K dielectric can comprise titanates, ($\text{Ba}_x\text{Sr}_{1-x}\text{TiO}_3$, $\text{Bi}_4\text{Ti}_3\text{O}_{12}$, $\text{PbZr}_x\text{Ti}_{1-x}\text{O}_3$), niobates (LiNbO_3), and/or zirconates (BaZrO_3 , CaZrO_3). The first electrode can comprise a noble metal. The passive electronic component can have a capacitance per unit area in a range of 1 nF/mm² to 1 $\mu\text{F/mm}^2$. The passive electronic component can have a capacitance per unit area in a range of 5 nF/mm² to 400 nF/mm². The passive electronic component can have a capacitance per unit area in a range of 100 nF/mm² to 400 nF/mm². The passive electronic component can have a capacitance per unit area in a range of 400 nF/mm² to 1000 nF/mm². The bonded structure can comprise a plurality of passive electronic components directly bonded to the element without an intervening adhesive. The passive component can be provided within a passive component layer directly bonded to the element, the passive component layer covering a majority of the element. The passive component can comprise a first surface directly bonded to the element and a second exterior surface opposite the first surface. The bonded structure can comprise a plurality of electrical contacts on the second exterior surface, the plurality of electrical contacts configured to electrically connect to an external component. The bonded structure can comprise an interconnect structure defining an electrical pathway between the element and a first electrical contact of the plurality of electrical contacts. The interconnect structure can comprise a conductive electrical interconnect that extends from the first surface to the first electrical contact, the conductive electrical interconnect embedded within a dielectric disposed between the first and second surfaces. The conductive electrical interconnect can comprise a longitudinal conductive portion extending from a first contact pad at or near the first surface to the first electrical contact and one or more lateral conductive portions extending laterally outward from the longitudinal conductive portion, the longitudinal conductive portion defining a resistive electrical pathway and the one or more lateral conductive portions defining a capacitive electrical pathway in parallel with the resistive electrical pathway. The bonded structure can

comprise a second interconnect structure comprising a second conductive electrical interconnect that extends from the first surface to a second electrical contact of the plurality of electrical contacts. The second conductive electrical interconnect can comprise a second longitudinal conductive portion extending from a second contact pad at or near the first surface to the first electrical contact and one or more second lateral conductive portions extending laterally outward from the second longitudinal conductive portion, the second longitudinal conductive portion defining a second resistive electrical pathway and the one or more second lateral conductive portions defining a second capacitive electrical pathway in parallel with the second resistive electrical pathway. The one or more lateral conductive portions and the one or more second lateral conductive portions can be interleaved with one another and separated by intervening dielectric material. One of the interconnect structure and the second interconnect structure can be configured to connect to a power source, and wherein the other of the interconnect structure and the second interconnect structure can be configured to connect to electrical ground. The passive electronic component can comprise a plurality of alternating conductive and dielectric features disposed between first and second opposing surfaces of the passive electronic component. The passive electronic component can comprise a first electrode at a first surface of the passive electronic component that is directly bonded to the element, a second electrode at a second exterior surface of the passive electronic component, and an intervening dielectric material, the first electrode patterned into a plurality of bond pads with intervening dielectric. The second electrode can comprise a noble metal. The noble metal can comprise platinum or ruthenium. The intervening dielectric material comprises a high K dielectric. The intervening dielectric material can comprise a complex oxide. The intervening dielectric material can comprise titanates, ($\text{Ba}_x\text{Sr}_{1-x}\text{TiO}_3$, $\text{Bi}_4\text{Ti}_3\text{O}_{12}$, $\text{PbZr}_x\text{Ti}_{1-x}\text{O}_3$), niobates (LiNbO_3), and/or zirconates (BaZrO_3 , CaZrO_3).

[0196] In another embodiment, a bonded structure is disclosed. The bonded structure can comprise an element having one or more active devices at or near an active surface of the element, and a passive electronic component bonded to the element, the passive electronic component comprising a sheet having a lateral width at least three times its thickness, the sheet covering a majority of the active surface of the element.

[0197] In some embodiments, the passive electronic component can comprise a capacitive sheet. The passive electronic component can be directly bonded to the element without an intervening adhesive.

[0198] In another embodiment, a method of forming a bonded structure is disclosed. The method can comprise providing an element having one or more active devices. The method can comprise directly bonding a passive electronic component to the element without an intervening adhesive.

[0199] In some embodiments, the method can comprise forming three or more metallic layers spaced apart by a plurality of dielectric layers in the passive electronic component. The passive electronic component can comprise a sheet having a lateral width at least three times its thickness, the method comprising covering a majority of an active surface of the element with the sheet. The method can comprise forming the passive electronic component to include a first electrode comprising a refractory metal, a second electrode, and an intervening dielectric layer having a dielectric constant greater than 10. The method can comprise patterning the second electrode to define a plurality of portions of the second electrode. The method can comprise forming the passive electronic component in a first facility and forming the element in a second facility different from the first facility.

[0200] For purposes of summarizing the disclosed embodiments and the advantages achieved over the prior art, certain objects and advantages have been described herein. Of course, it is to be understood that not necessarily all such objects or advantages may be achieved in accordance with any particular embodiment. Thus, for example, those skilled in the art will recognize that the disclosed implementations may be embodied or carried out in a manner that achieves or optimizes one advantage or group of advantages as taught or suggested herein without necessarily achieving other objects or advantages as may be taught or suggested herein.

[0201] All of these embodiments are intended to be within the scope of this disclosure. These and other embodiments will become readily apparent to those skilled in the art from the following detailed description of the embodiments having reference to the attached figures, the claims not being limited to any particular embodiment(s) disclosed. Although this certain embodiments and examples have been disclosed herein, it will be understood by those skilled in the art that the disclosed implementations extend beyond the

specifically disclosed embodiments to other alternative embodiments and/or uses and obvious modifications and equivalents thereof. In addition, while several variations have been shown and described in detail, other modifications will be readily apparent to those of skill in the art based upon this disclosure. It is also contemplated that various combinations or sub-combinations of the specific features and aspects of the embodiments may be made and still fall within the scope. It should be understood that various features and aspects of the disclosed embodiments can be combined with, or substituted for, one another in order to form varying modes of the disclosed implementations. Thus, it is intended that the scope of the subject matter herein disclosed should not be limited by the particular disclosed embodiments described above, but should be determined only by a fair reading of the claims that follow.

WHAT IS CLAIMED IS:

1. A microelectronic device comprising:
 - a first insulating substrate;
 - a capacitor having a first surface and a second surface opposite the first surface, the first surface of the capacitor mechanically coupled to the first insulating substrate;
 - a second insulating substrate, the second surface of the capacitor mechanically coupled to the second insulating substrate such that the capacitor is disposed between the first and second insulating substrates;
 - an insulating element disposed between the first and second insulating substrates; and
 - a first interconnect extending through the first insulating substrate to electrically connect to a first terminal of the capacitor.
2. The microelectronic device of Claim 1, wherein the first surface of the capacitor is mechanically coupled to the first insulating substrate by way of a first adhesive.
3. The microelectronic device of Claim 2, wherein the second surface of the capacitor is mechanically coupled to the second insulating substrate by way of a second adhesive, the insulating element further comprising the second adhesive.
4. The microelectronic device of Claim 2, wherein the first adhesive comprises solder.
5. The microelectronic device of Claim 1, wherein the insulating element comprises a molding compound disposed about portions of the capacitor.
6. The microelectronic device of Claim 1, wherein the insulating element comprises a third intermediate insulating substrate disposed about the capacitor between the first and second insulating substrates.
7. The microelectronic device of Claim 1, wherein a coefficient of thermal expansion (CTE) of one or more of the first and second insulating substrates is no more than 5 ppm/°C.
8. The microelectronic device of Claim 1, wherein an overall effective coefficient of thermal expansion (CTE) of the microelectronic device is no more than 7 ppm/°C.

9. The microelectronic device of Claim 1, further comprising a second interconnect extending through the first insulating substrate, the first interconnect connected to a first terminal of the capacitor at a first side of the capacitor and the second interconnect connected to a second terminal at the first side, the first terminal of a different type from the second terminal.

10. The microelectronic device of Claim 9, further comprising a third terminal at a second side of the capacitor and a fourth terminal at the second side, the third terminal of a different type from the fourth terminal.

11. A bonded structure comprising the microelectronic device of Claim 1 and an element, the element directly bonded to the microelectronic device without an intervening adhesive.

12. A microelectronic device, comprising:

an insulating material having a first surface and a second surface opposite the first surface;

a capacitor at least partially embedded within the insulating material, between the first surface and the second surface; and

an interconnect layer disposed on the first surface, and arranged to electrically couple one or more terminals of the capacitor to one or more interconnects at or extending through the first surface of the insulating material.

13. The microelectronic device of Claim 12, wherein the capacitor is completely embedded within the insulating material.

14. The microelectronic device of Claim 12, further comprising a first insulating substrate, wherein a first surface of the capacitor is mechanically coupled to the first insulating substrate by way of a first adhesive, the insulating material comprising the first adhesive.

15. The microelectronic device of Claim 14, further comprising a second insulating substrate, the second surface of the capacitor mechanically coupled to the second insulating substrate by way of a second adhesive, the insulating material further comprising the second adhesive.

16. The microelectronic device of Claim 12, further comprising a molding compound disposed about portions of the capacitor, the insulating material further comprising the molding compound.

17. A bonded structure comprising:

an element; and

a passive electronic component having a first surface bonded to the element and a second surface opposite the first surface, the passive electronic component comprising a first anode terminal bonded to a corresponding second anode terminal of the element and a first cathode terminal bonded to a corresponding second cathode terminal of the element, the first anode terminal and the first cathode terminal disposed on the first surface of the passive electronic component.

18. The bonded structure of Claim 17, wherein the passive electronic component is directly bonded to the element without an intervening adhesive.

19. The bonded structure of Claim 17, wherein the passive electronic component comprises a capacitor.

20. The bonded structure of Claim 19, wherein a dielectric material of the capacitor comprises a high K dielectric.

21. The bonded structure of Claim 19, wherein the capacitor comprises a serpentine pattern extending through the passive electronic component.

22. The bonded structure of Claim 19, wherein the passive electronic component comprises a through-signal conductor extending through the passive electronic component.

23. A bonded structure comprising:

an element; and

a passive electronic component directly bonded to the element without an intervening adhesive.

24. The bonded structure of Claim 23, wherein the passive electronic component comprises a capacitor.

25. The bonded structure of Claim 24, wherein the capacitor comprises three or more metallic layers spaced apart by a plurality of dielectric layers.

26. The bonded structure of Claim 23, wherein the passive electronic component comprises a first electrode, a second electrode, and a dielectric material between the first and second electrodes, wherein the dielectric material comprises a high K dielectric.

27. The bonded structure of Claim 26, wherein the high K dielectric comprises titanates, ($\text{Ba}_x\text{Sr}_{1-x}\text{TiO}_3$, $\text{Bi}_4\text{Ti}_3\text{O}_{12}$, $\text{PbZr}_x\text{Ti}_{1-x}\text{O}_3$), niobates (LiNbO_3), and/or zirconates (BaZrO_3 , CaZrO_3).

28. The bonded structure of Claim 23, wherein the passive electronic component comprises a through-signal conductor extending through the passive electronic component.

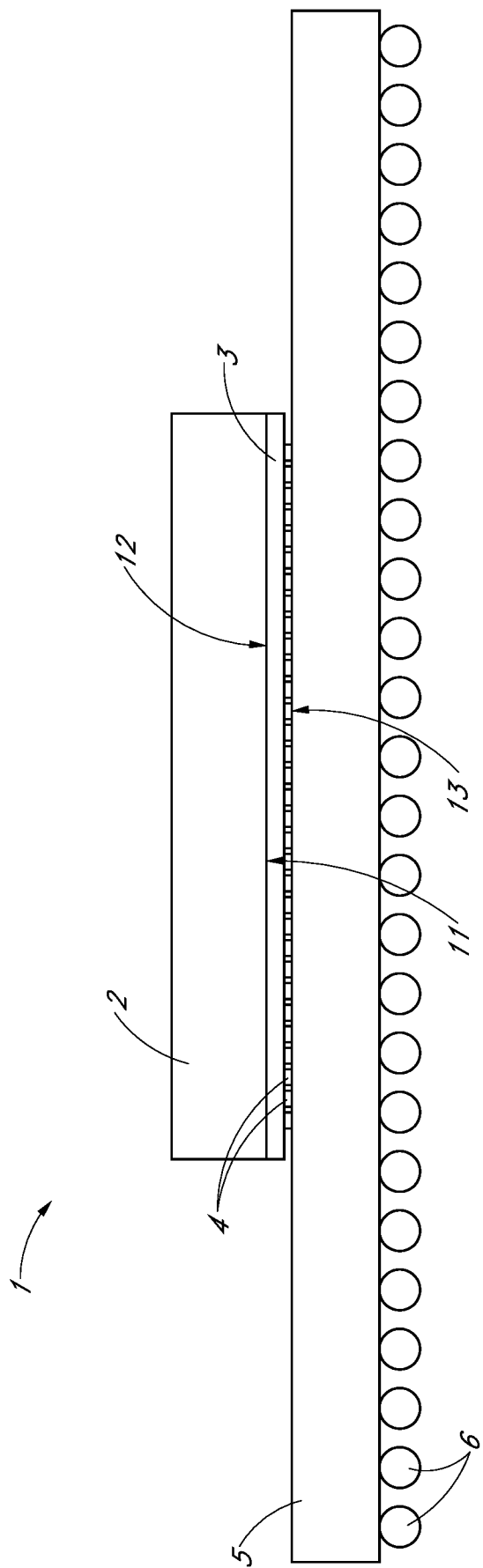


FIG. 1A

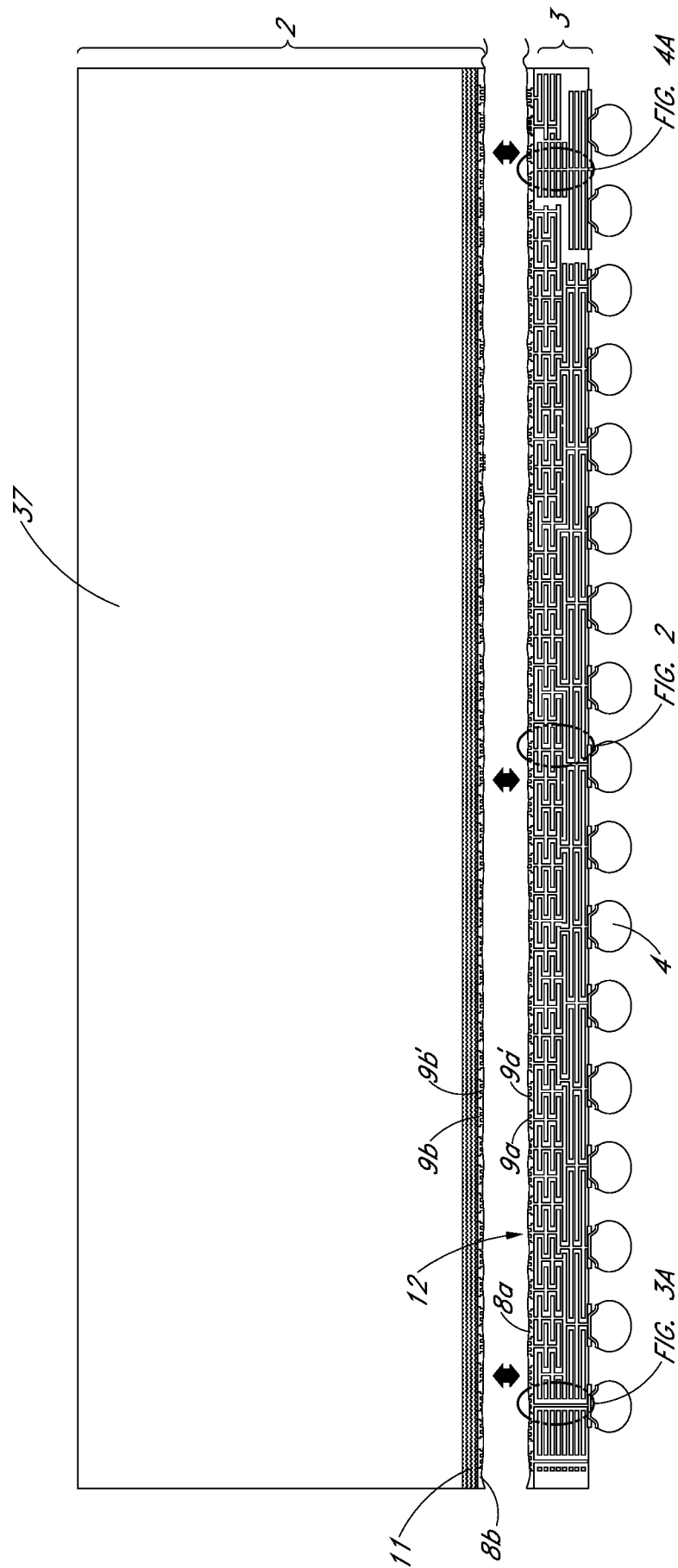
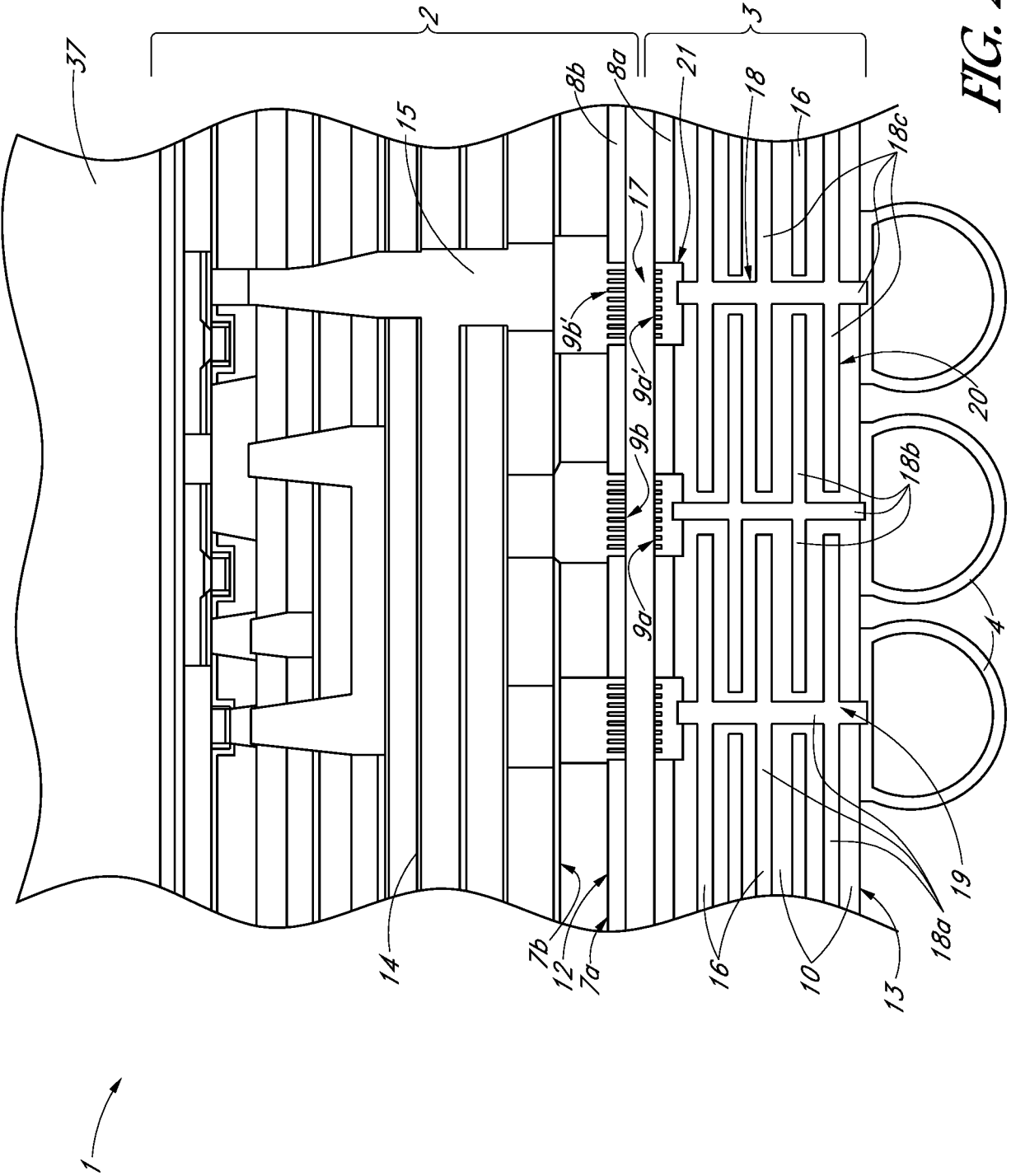


FIG. 1B



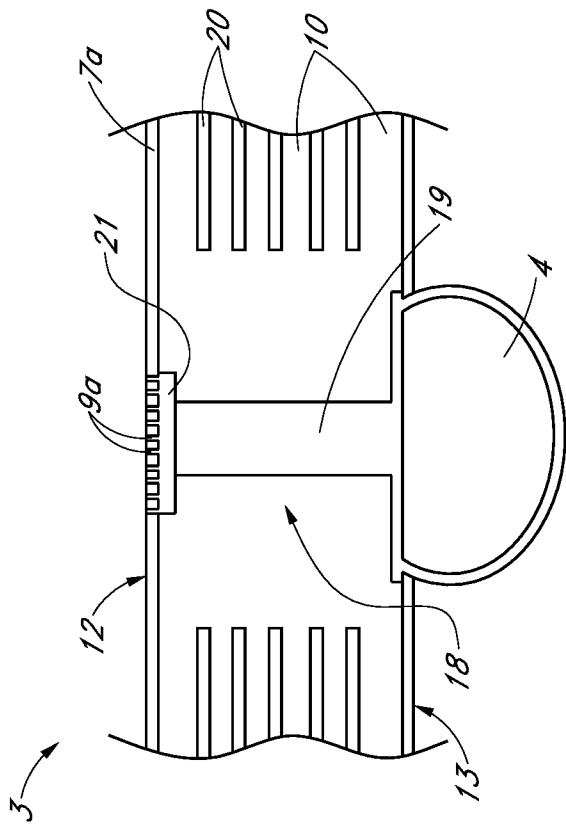


FIG. 3A

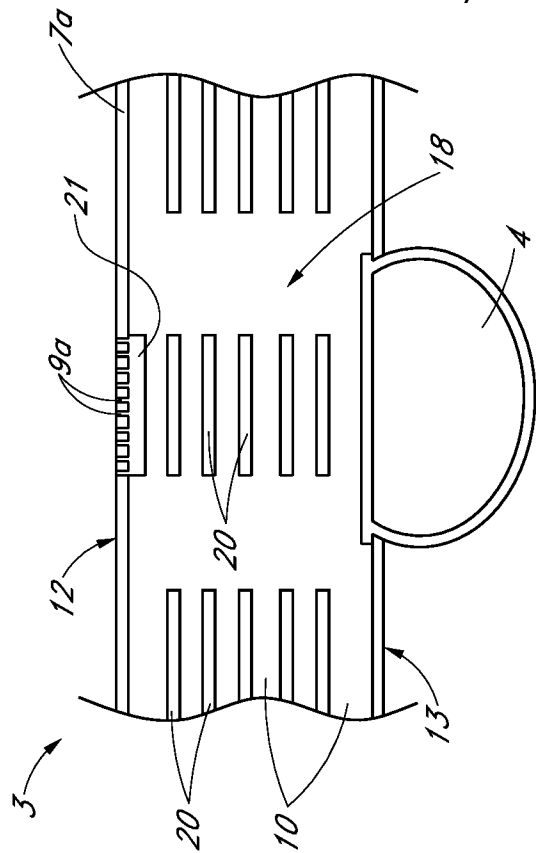


FIG. 4A

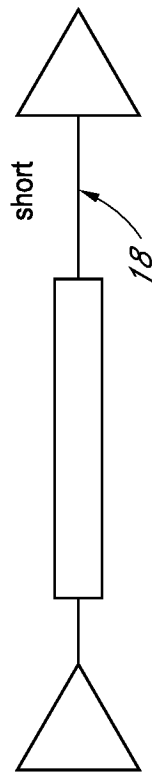


FIG. 3B

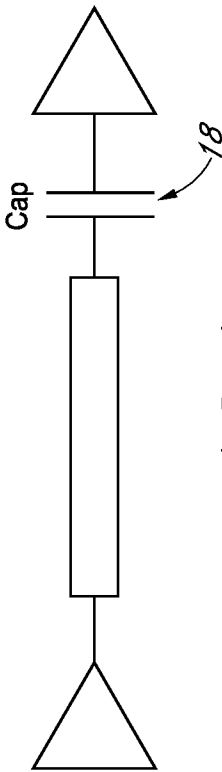
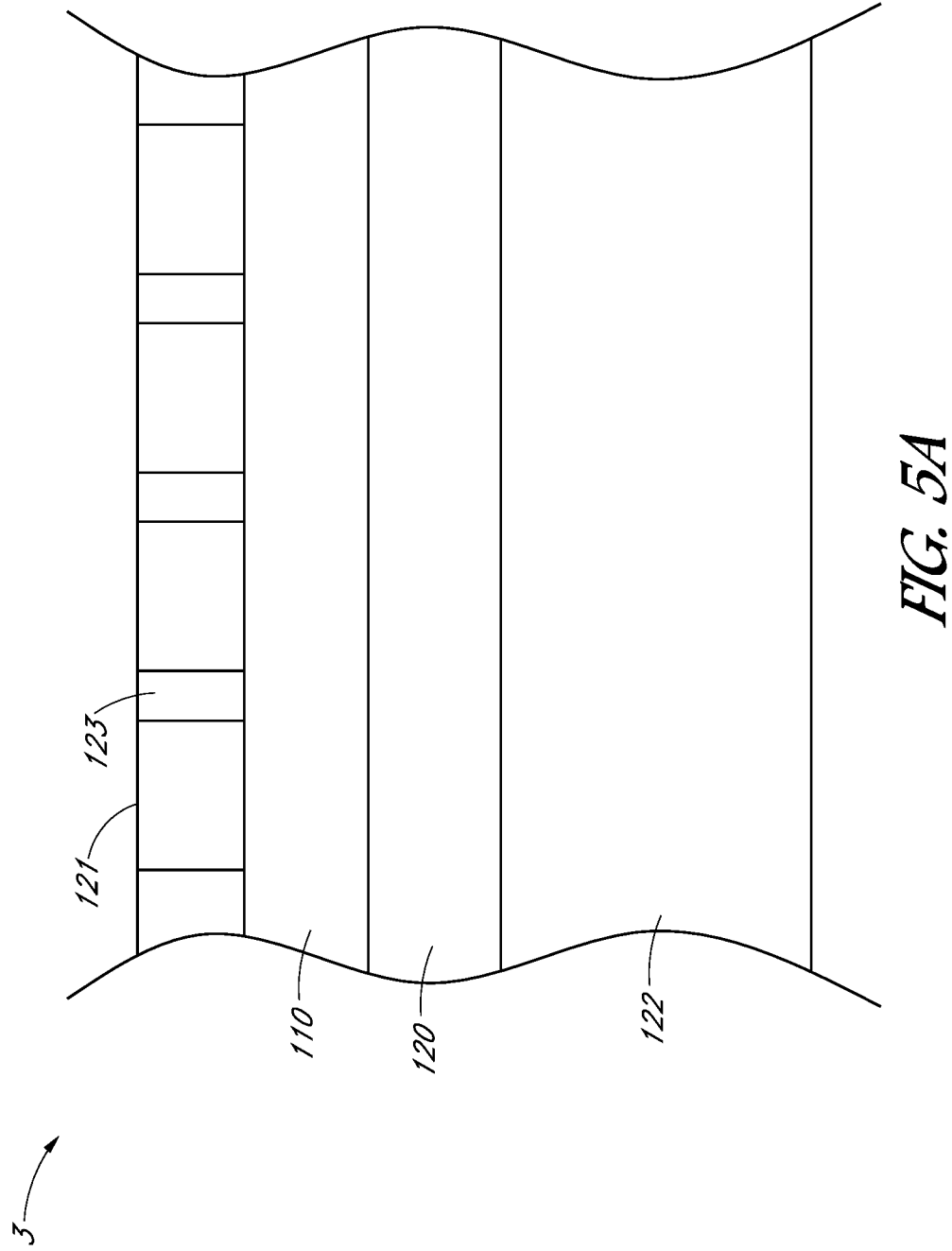


FIG. 4B



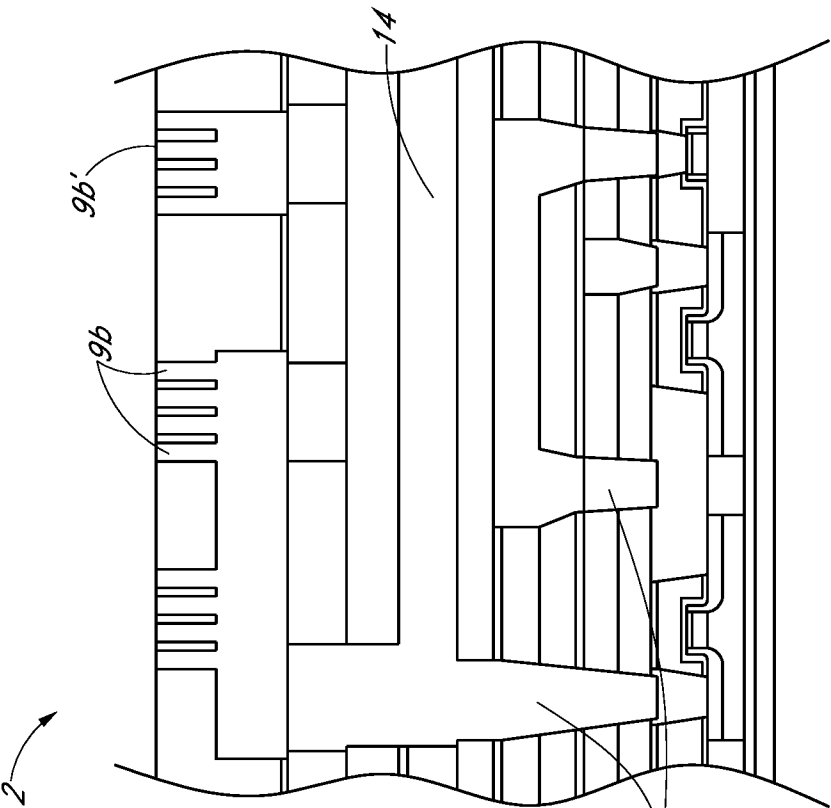


FIG. 5C

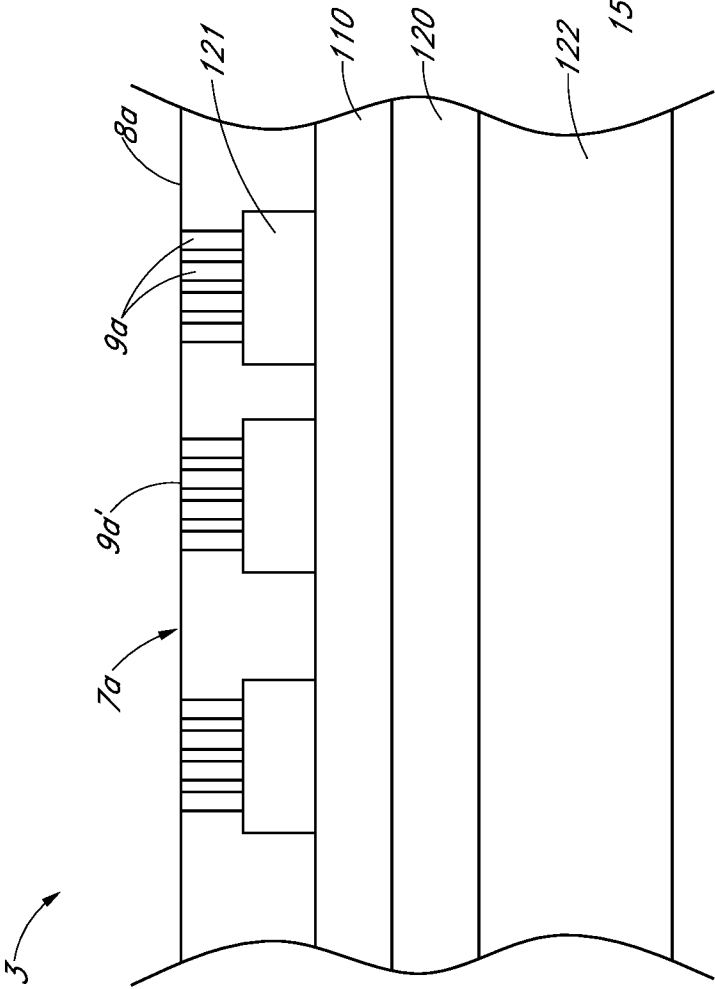
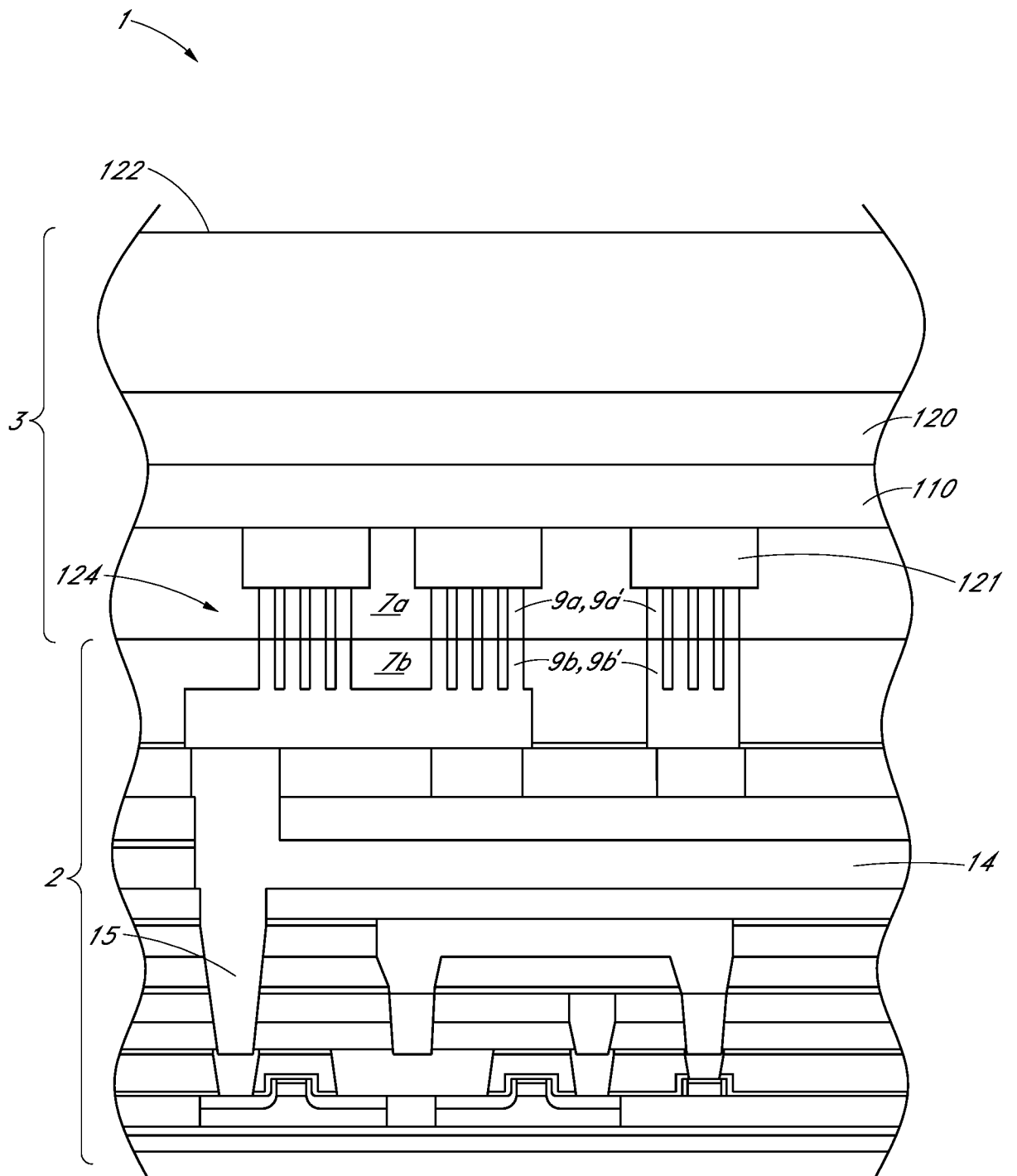


FIG. 5B

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*FIG. 5D*

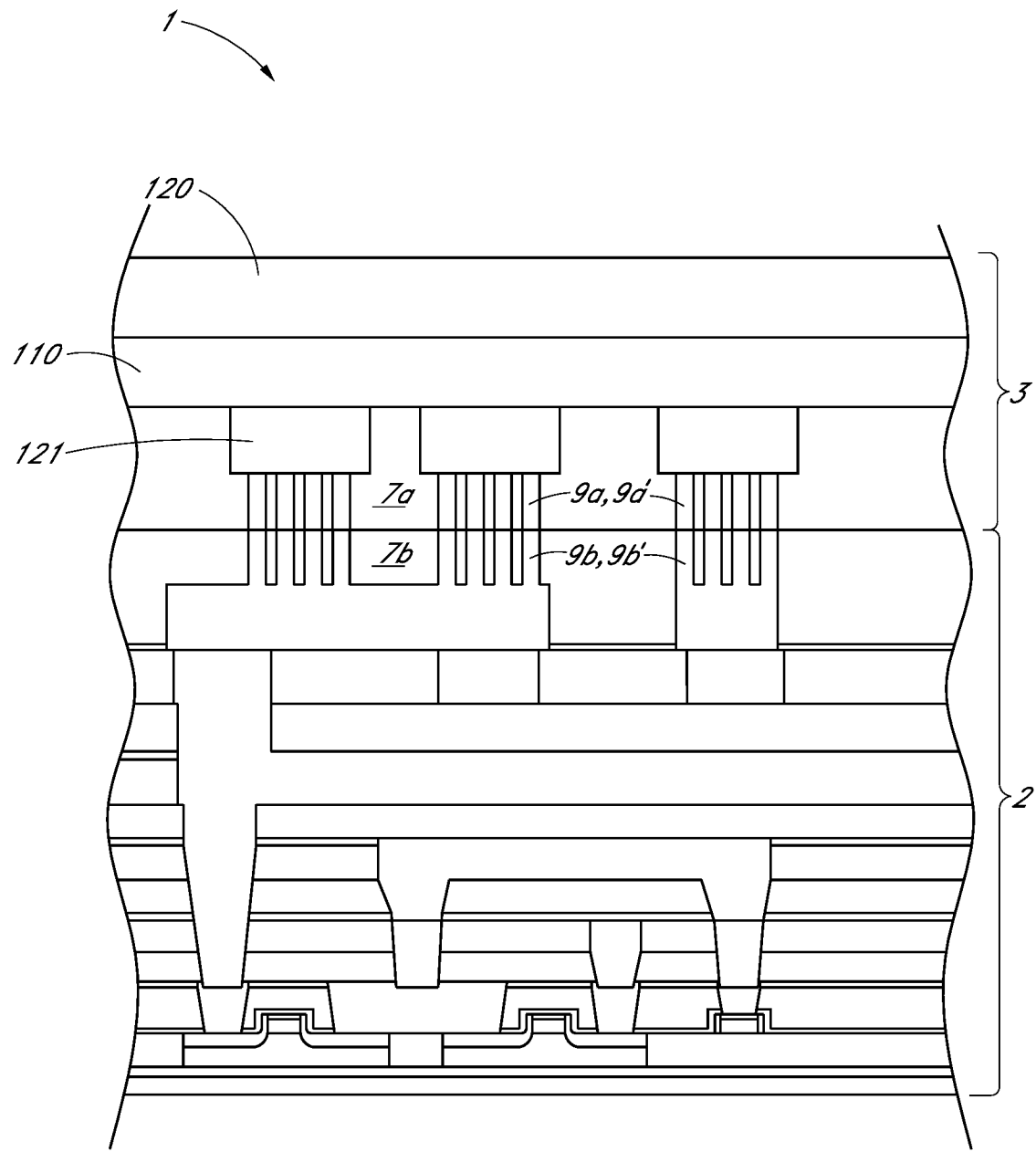


FIG. 5E

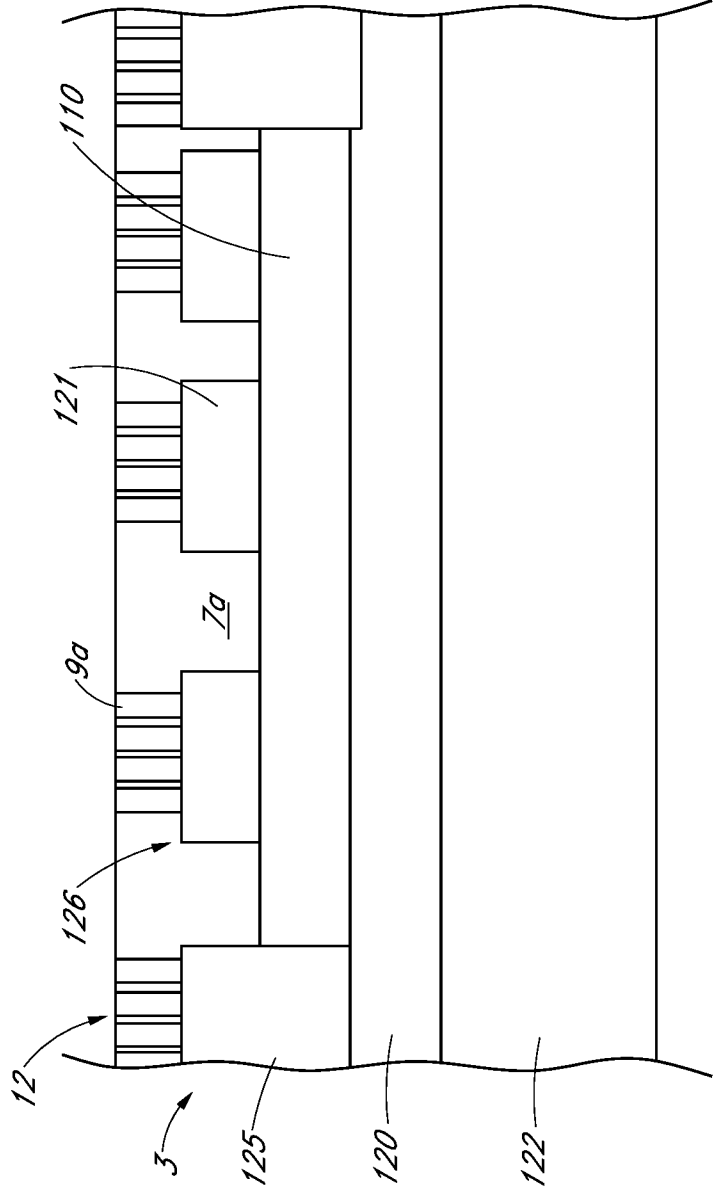


FIG. 5F

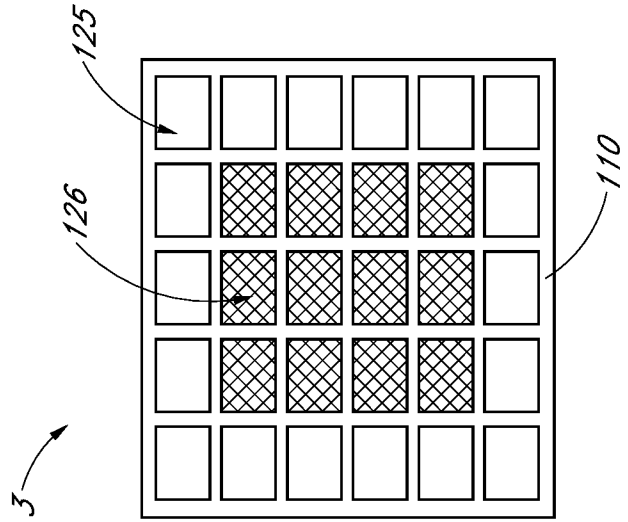


FIG. 5G

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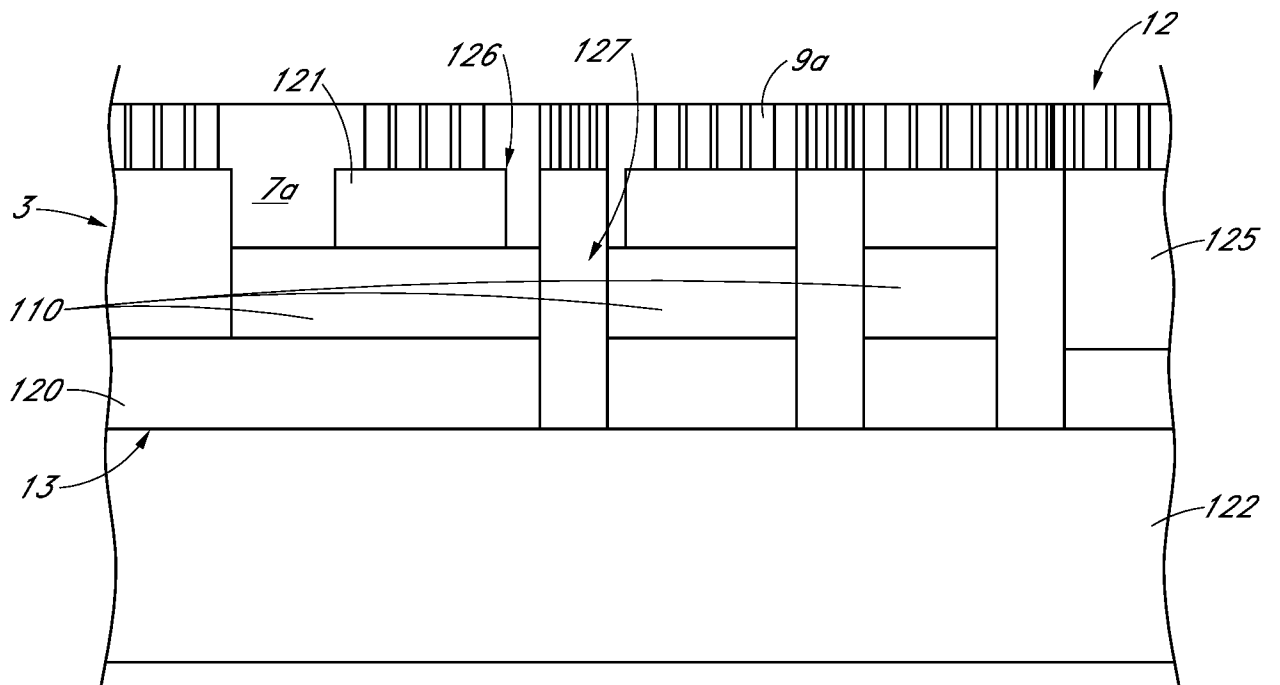


FIG. 5H

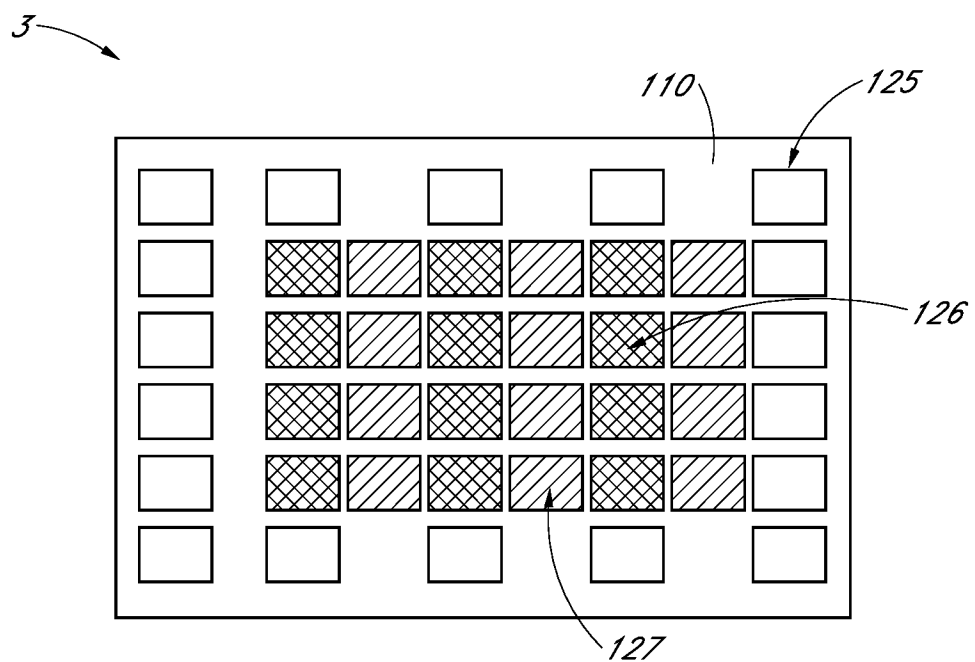


FIG. 5I

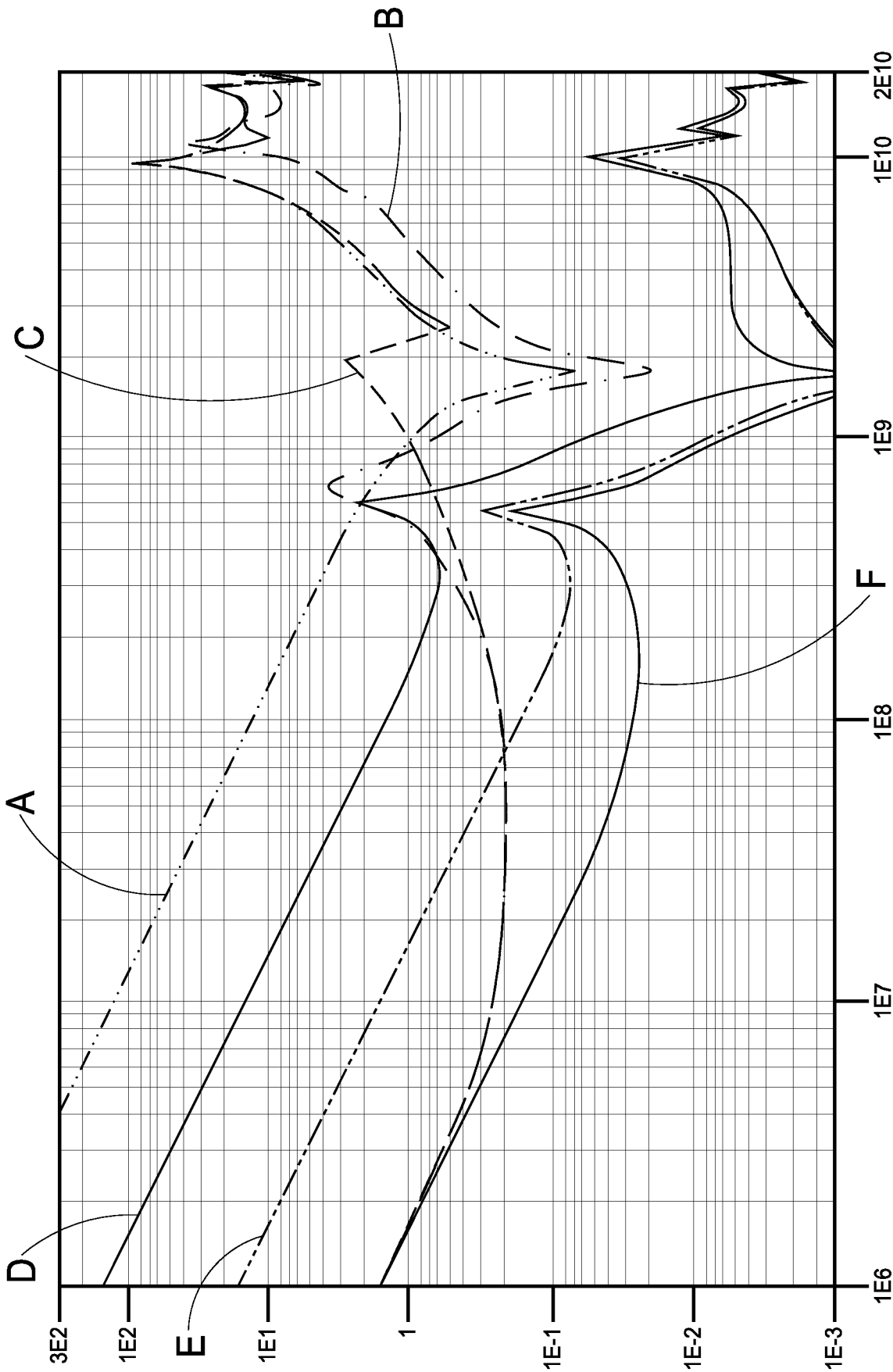
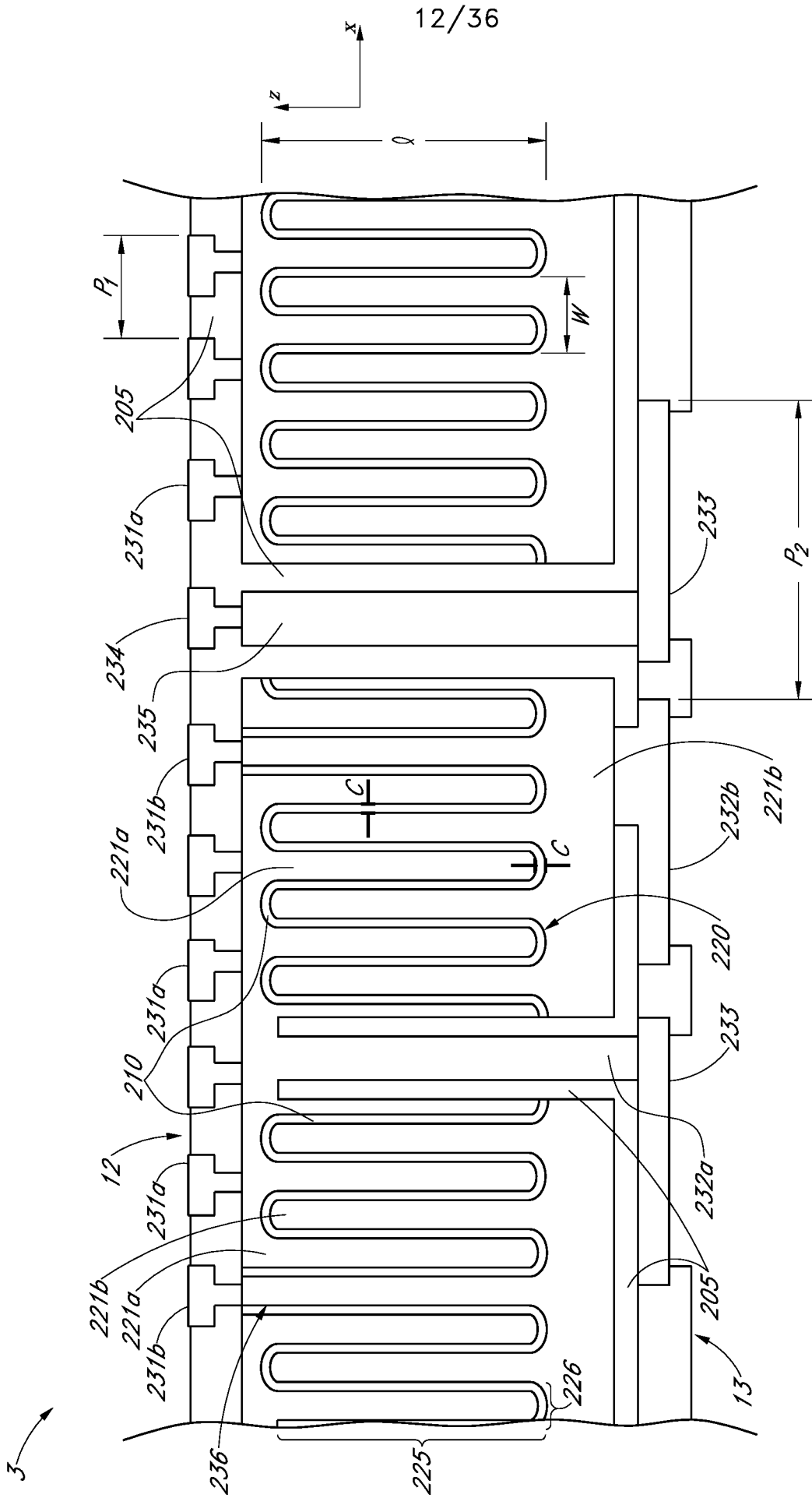


FIG. 6



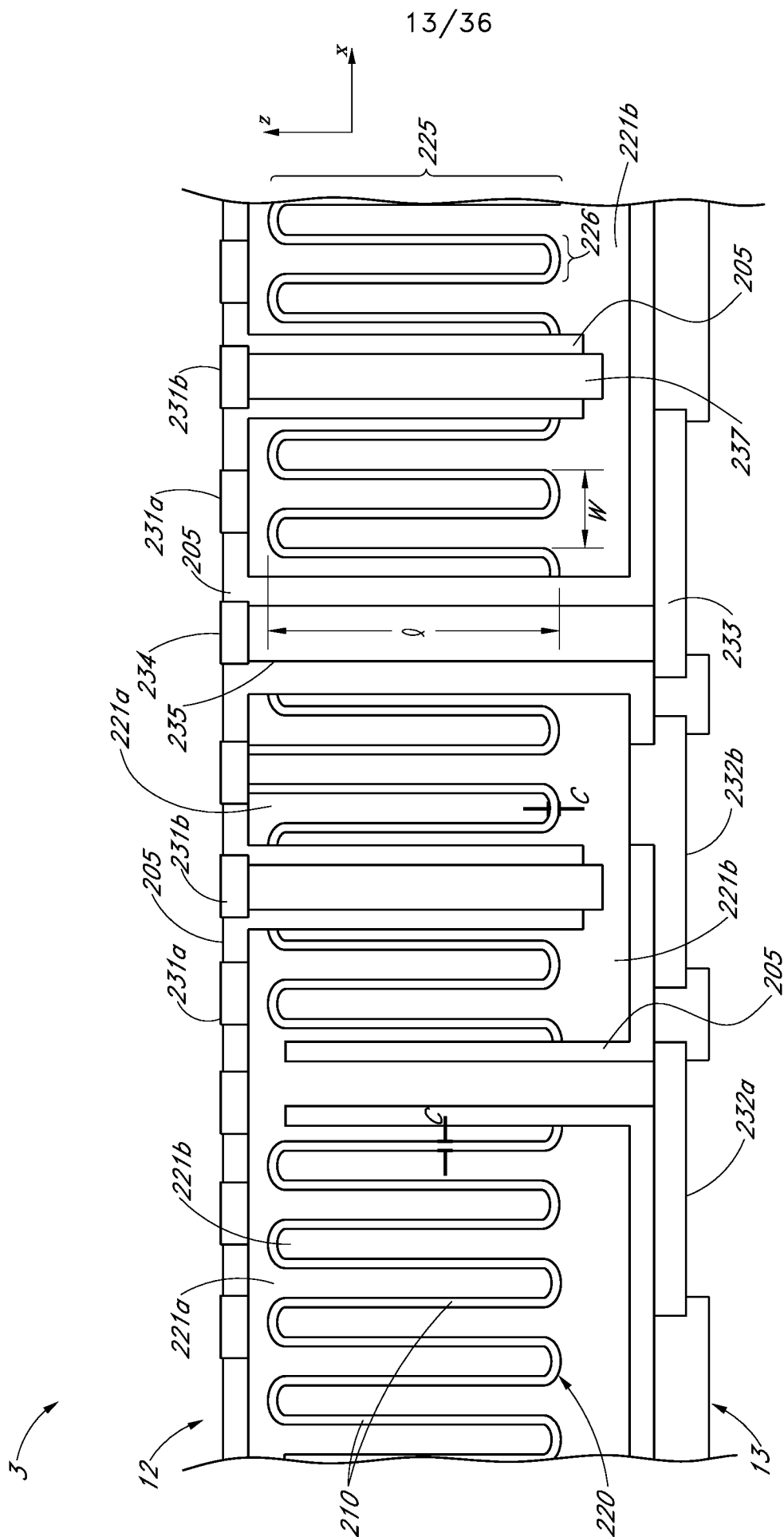


FIG. 7B

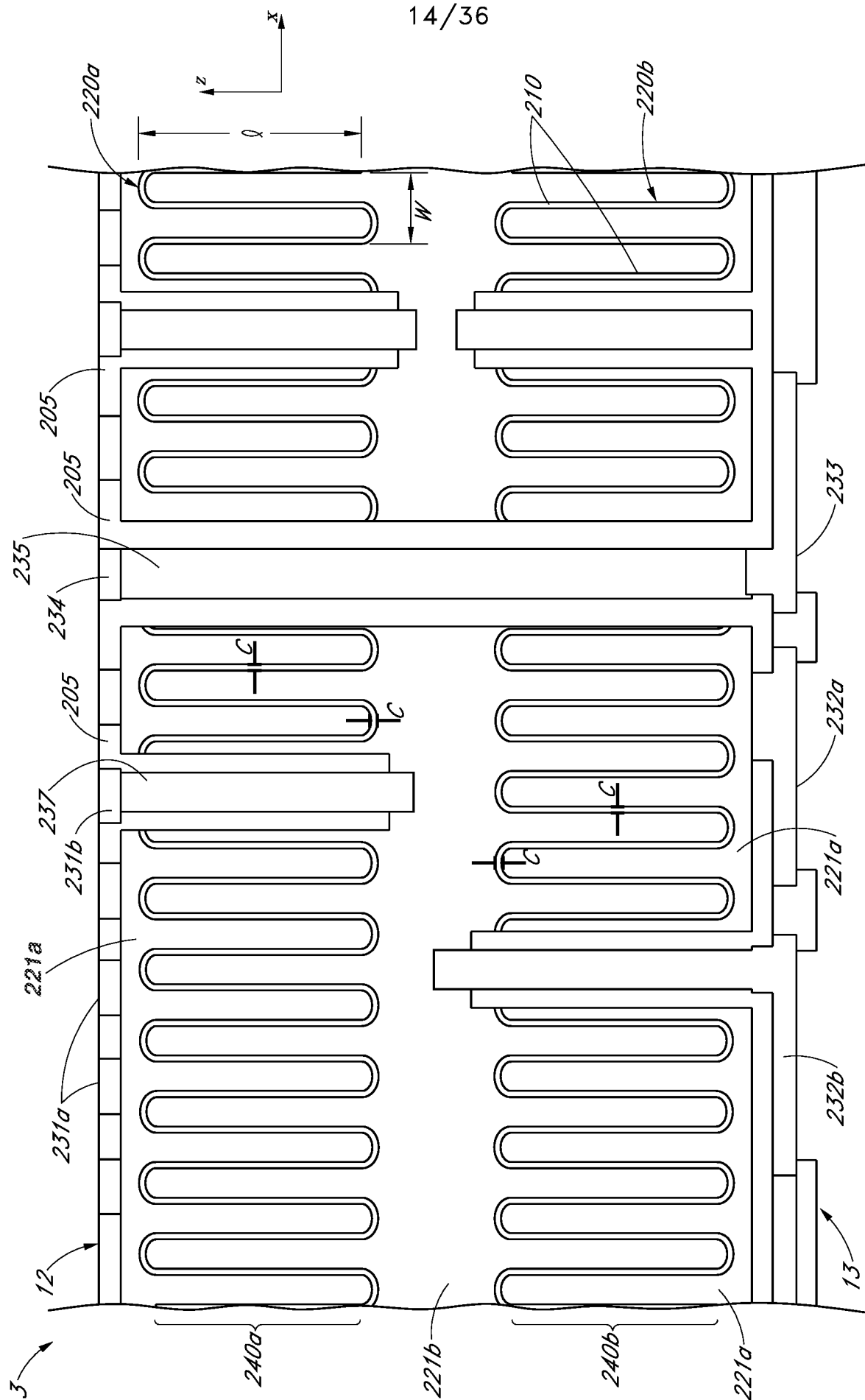


FIG. 7C

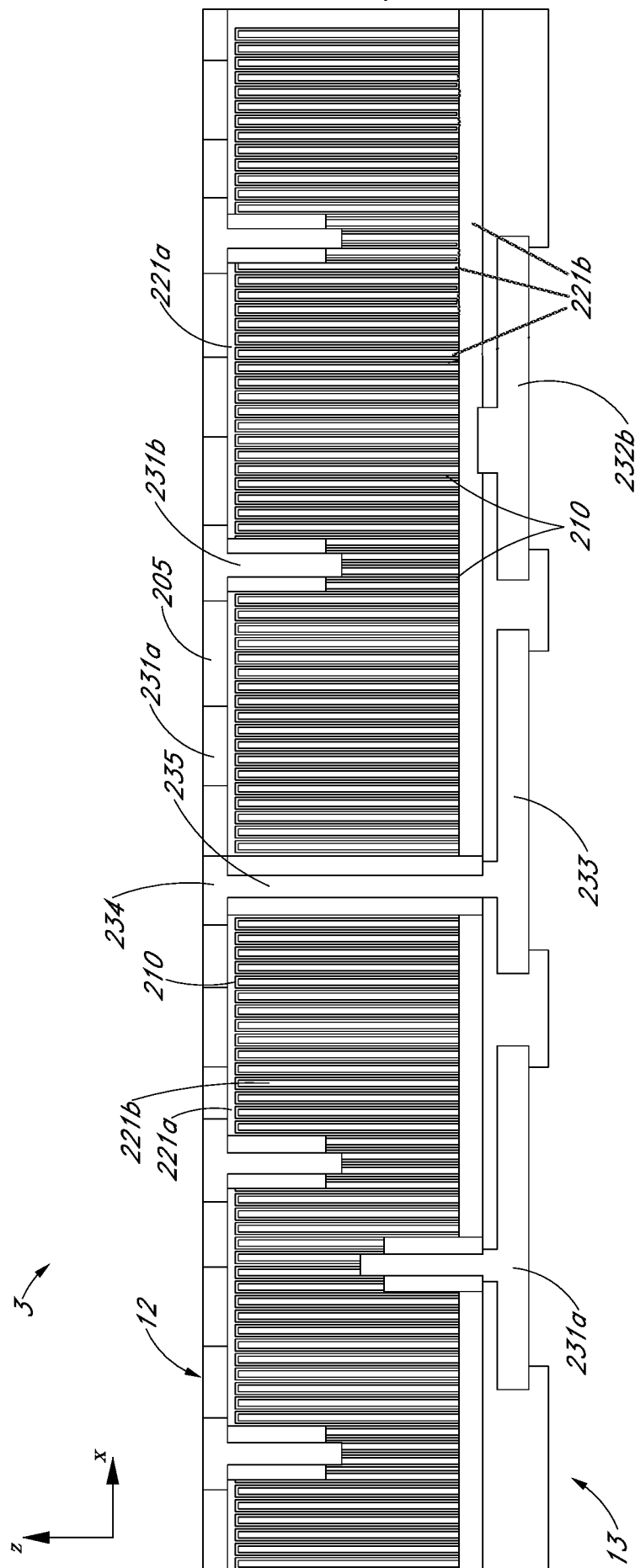
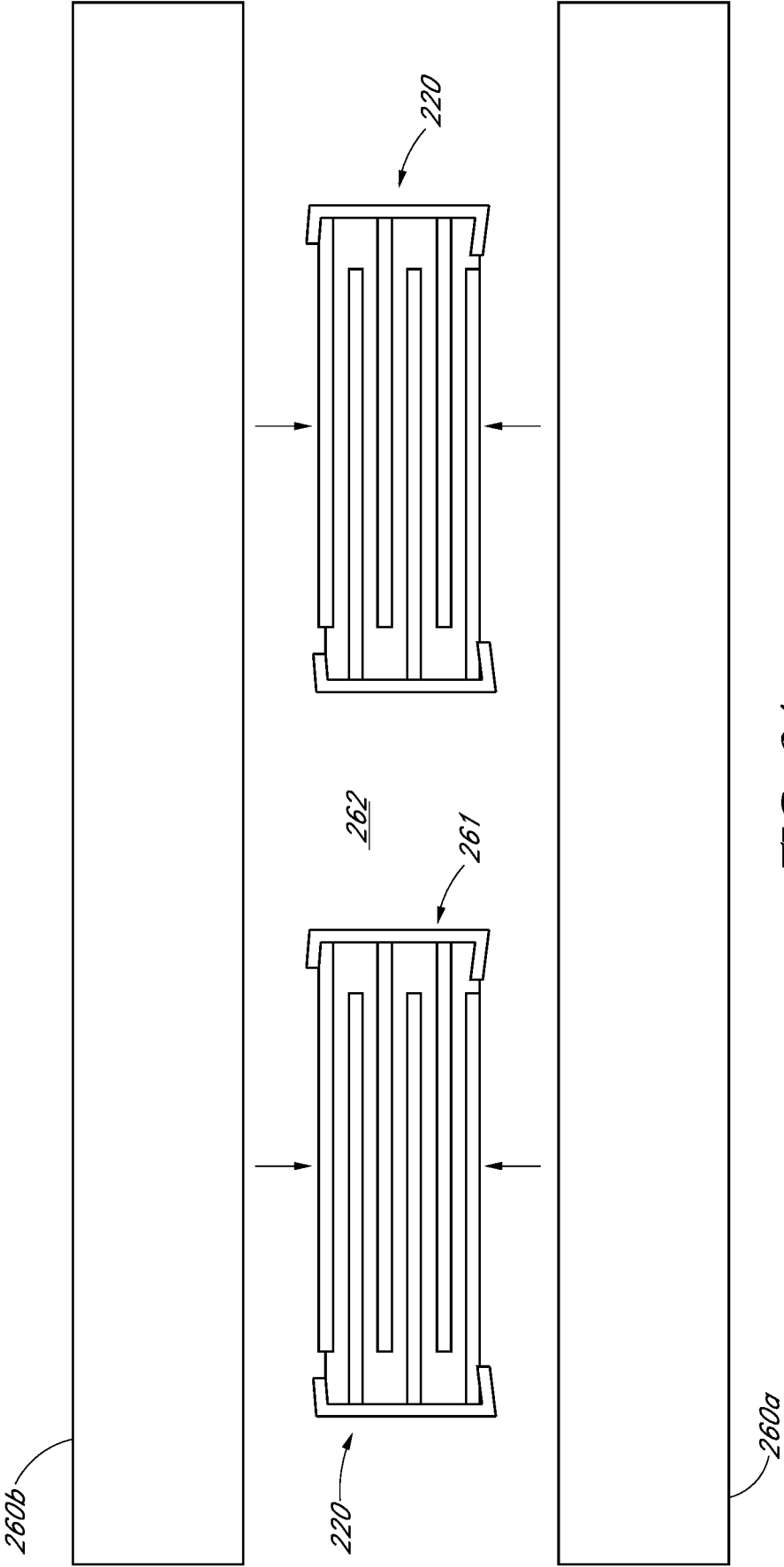
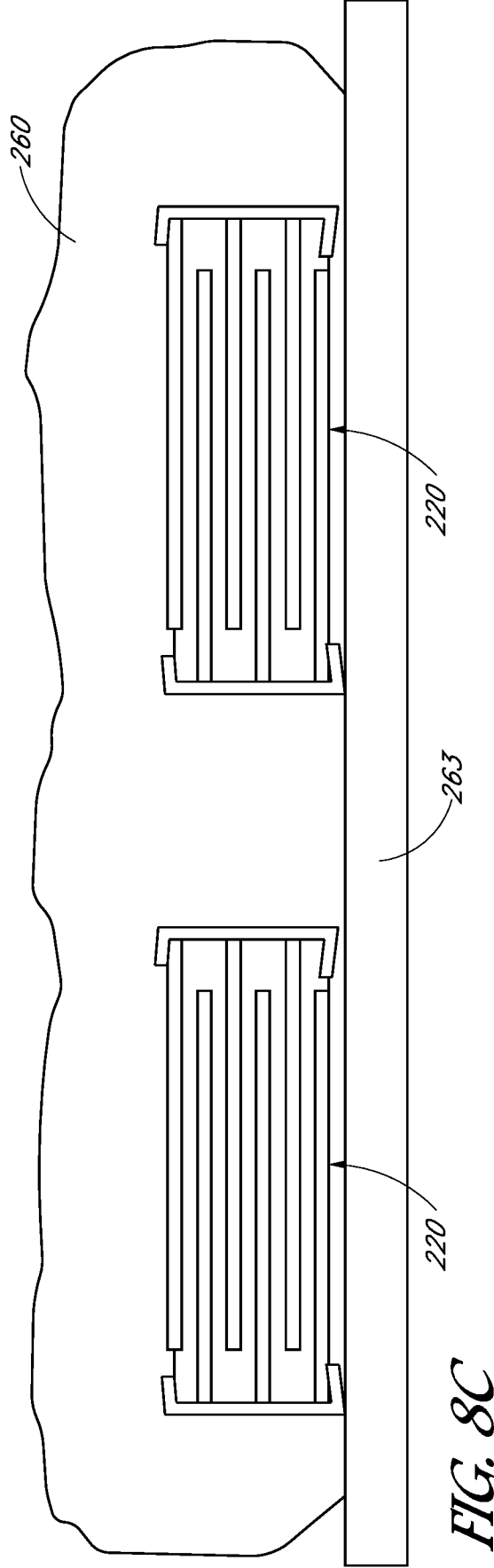
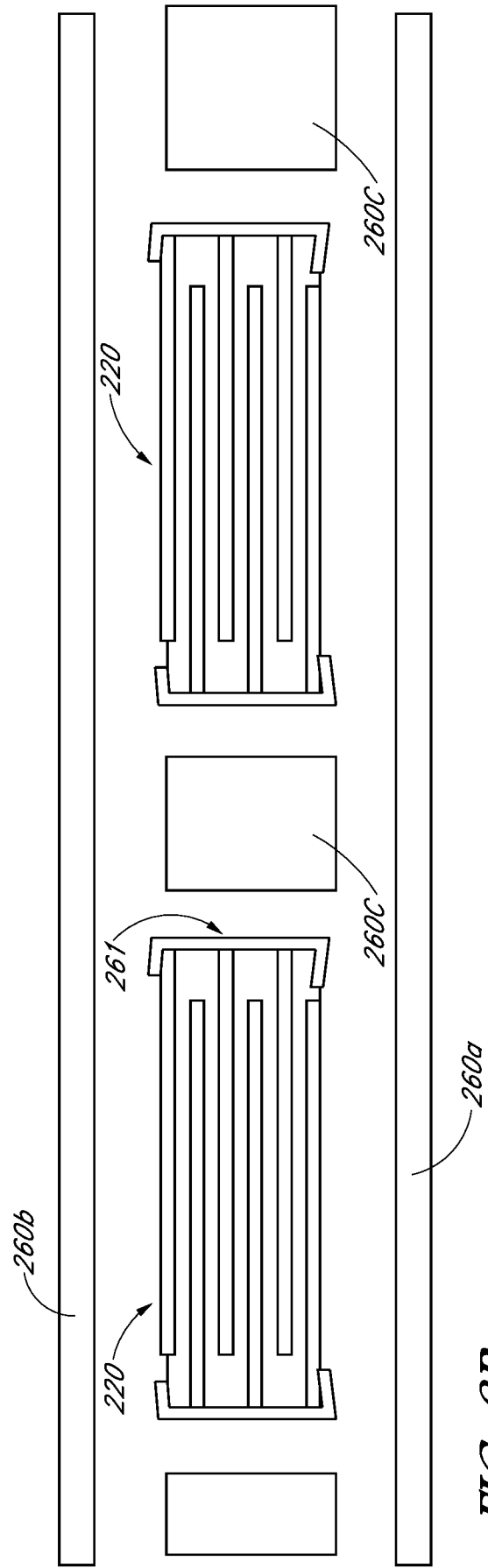
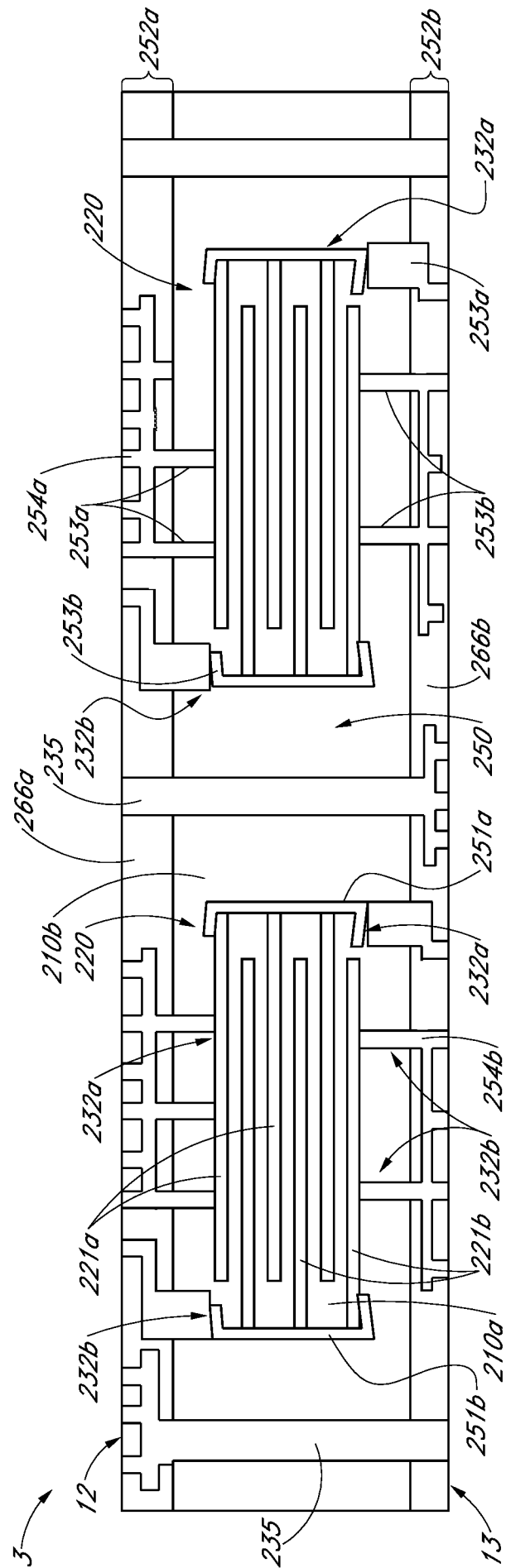
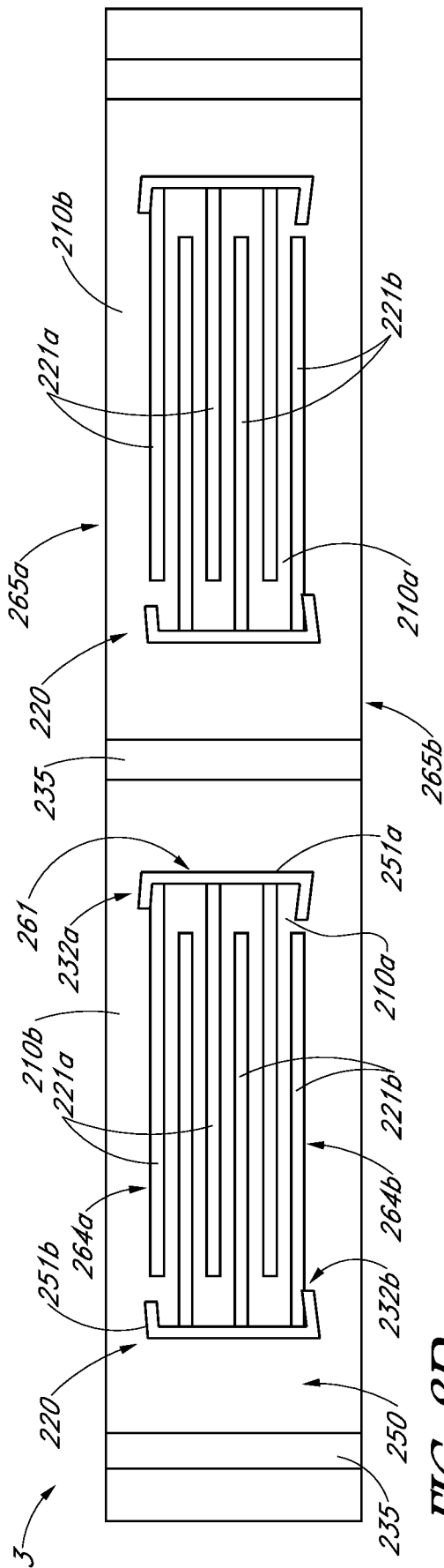


FIG. 7D







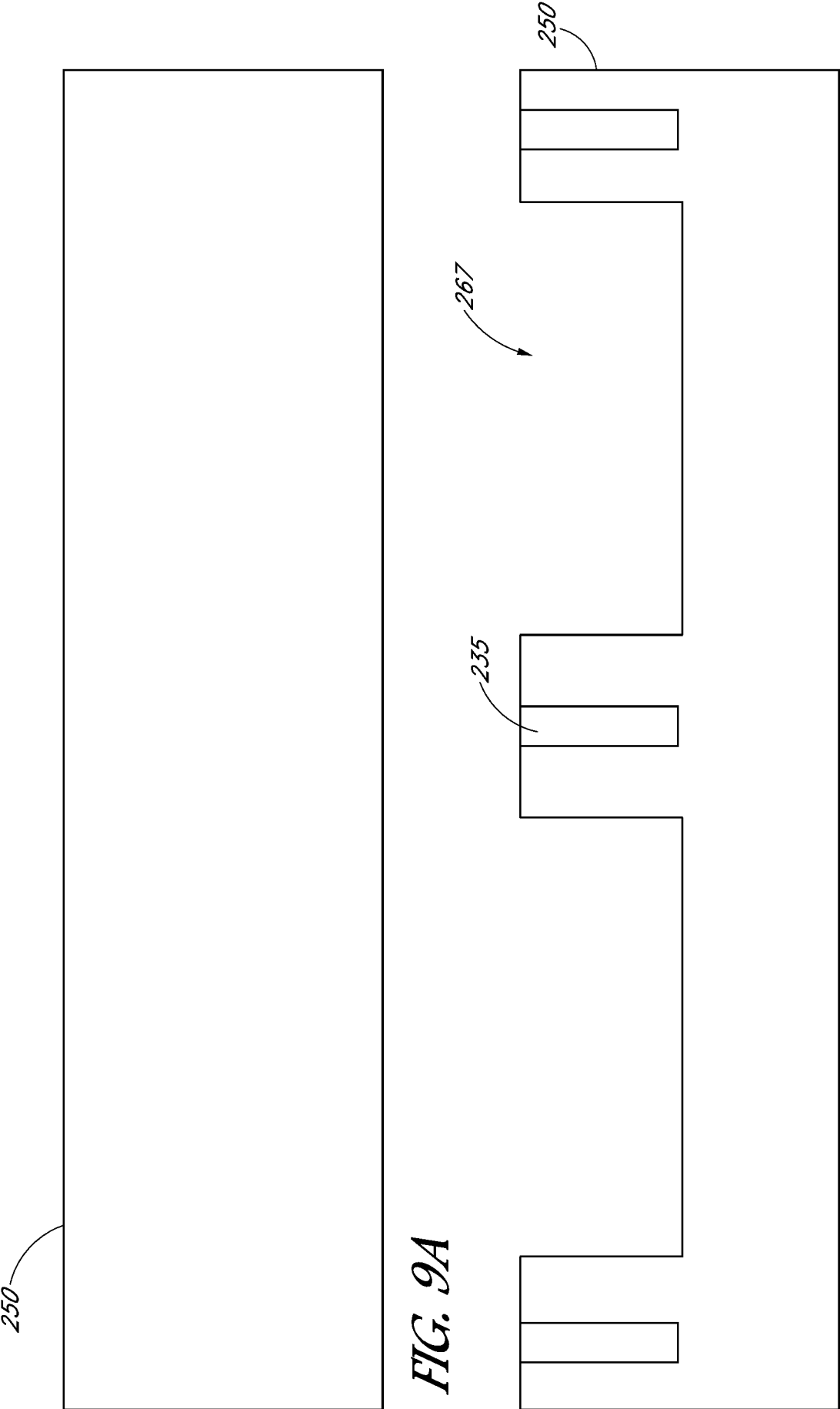
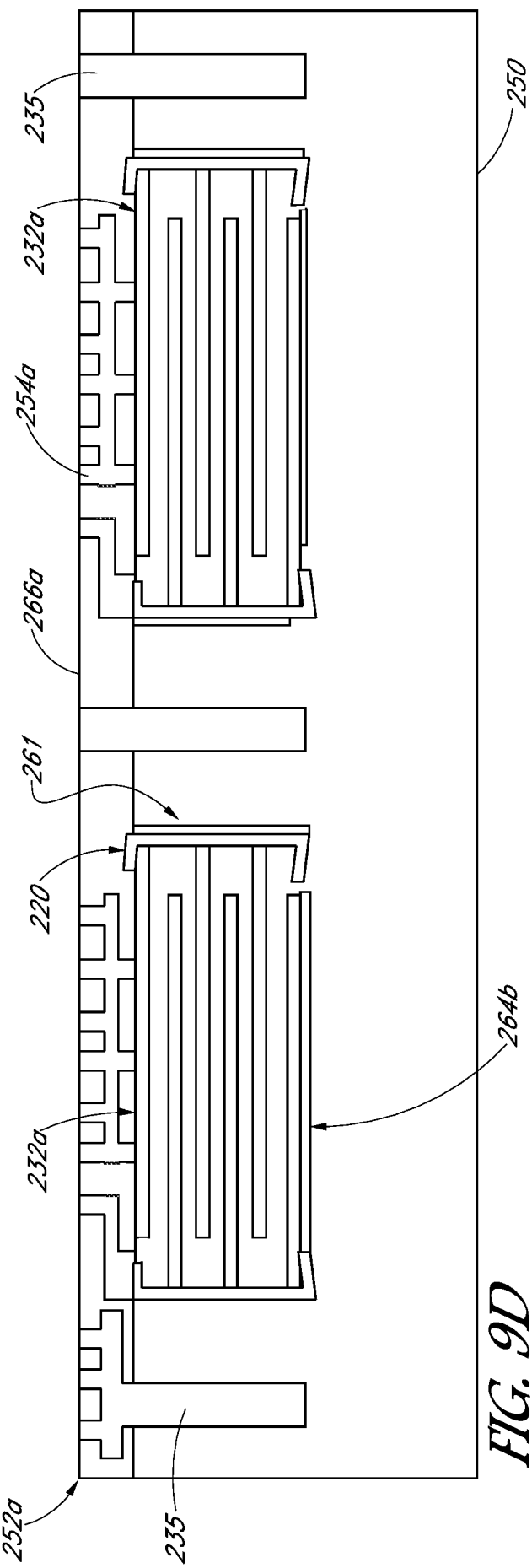
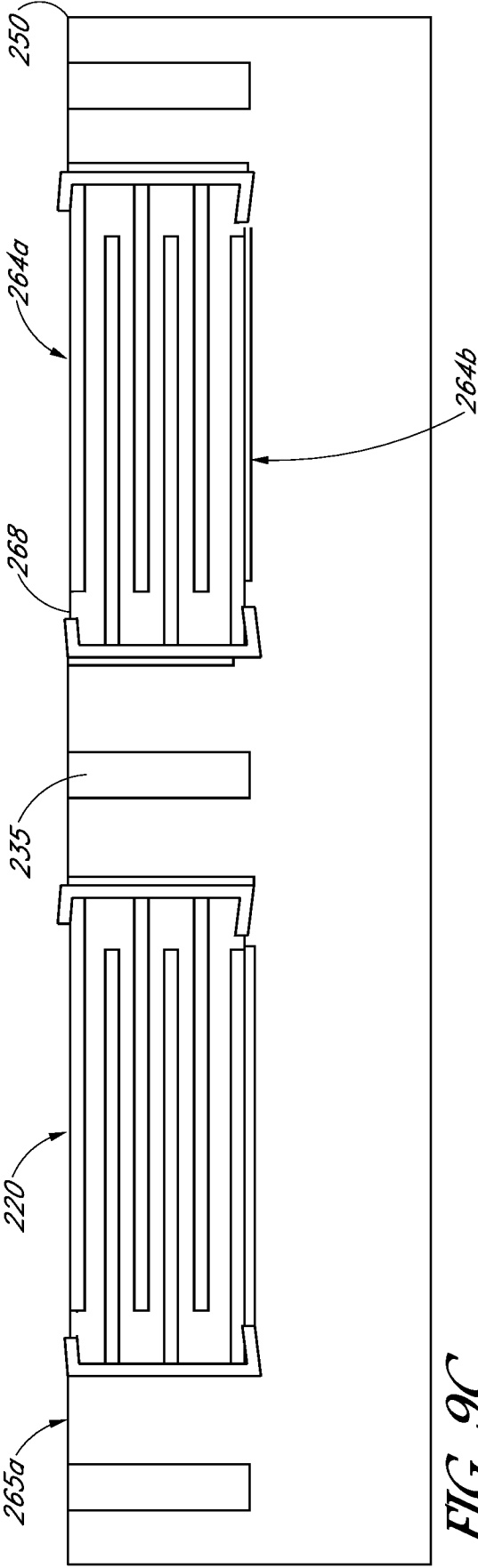


FIG. 9A

FIG. 9B



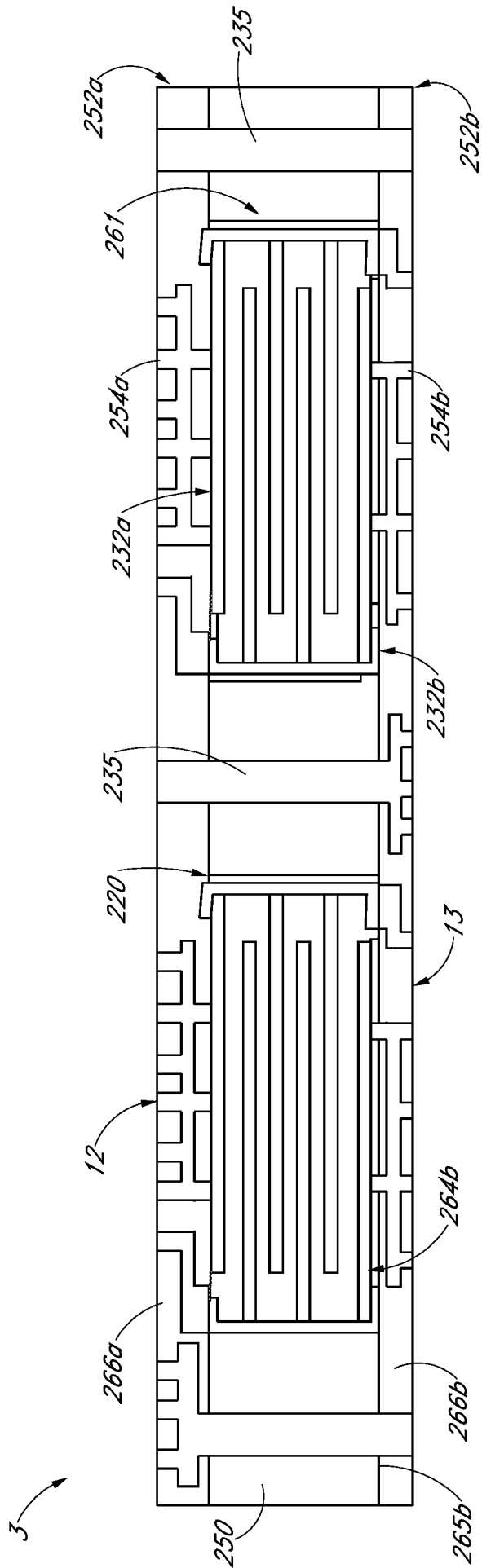


FIG. 9E

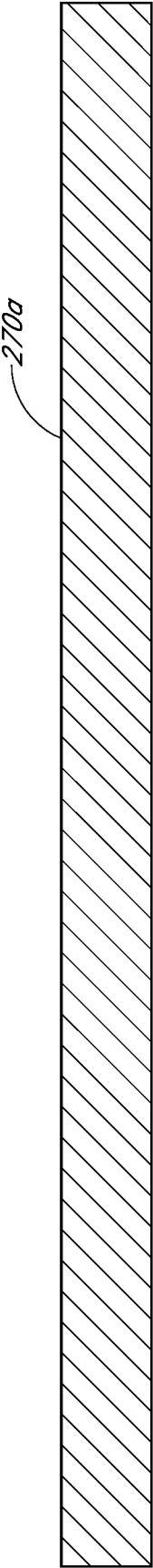


FIG. 10A

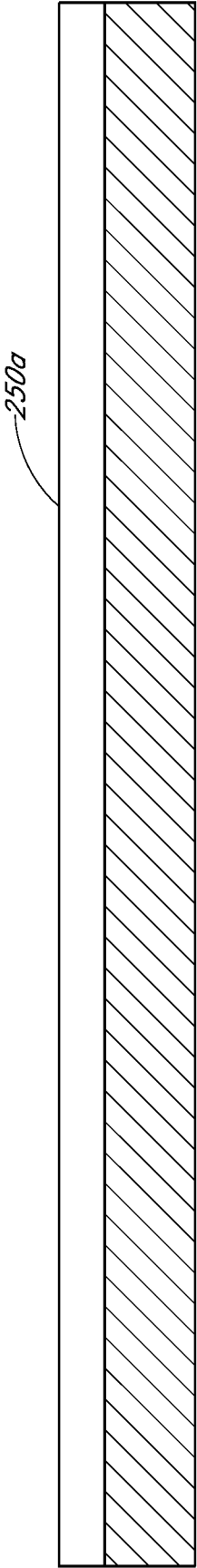


FIG. 10B

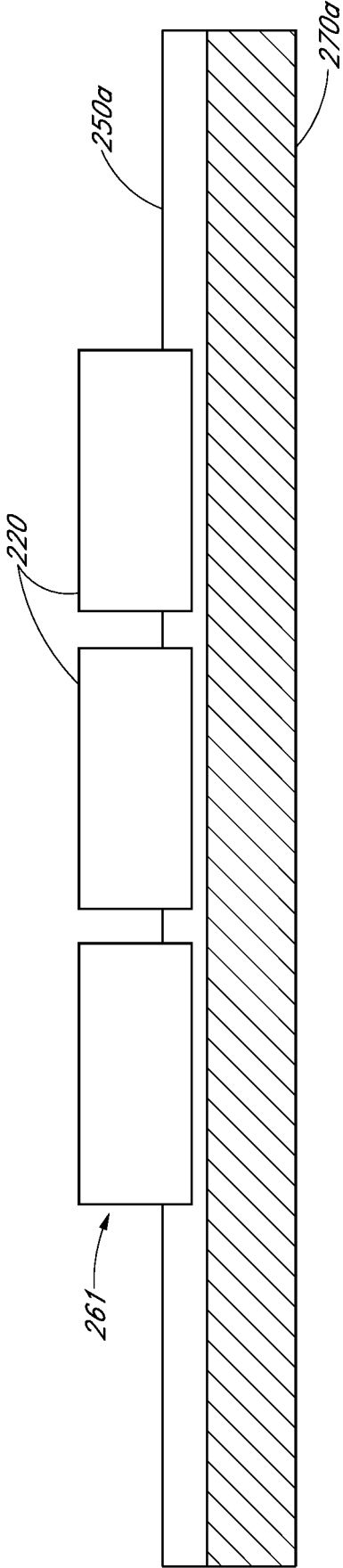


FIG. 10C

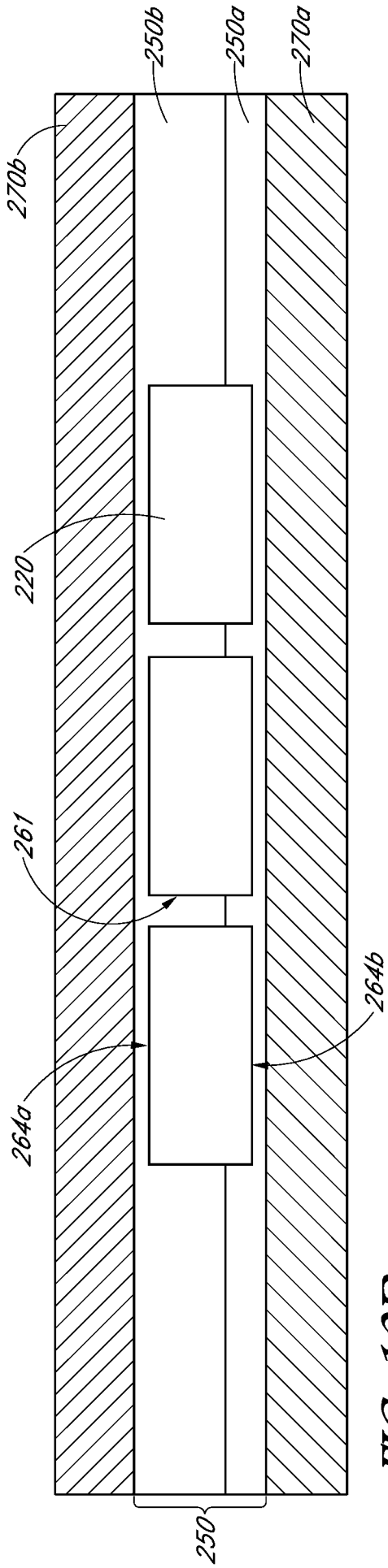


FIG. 10D

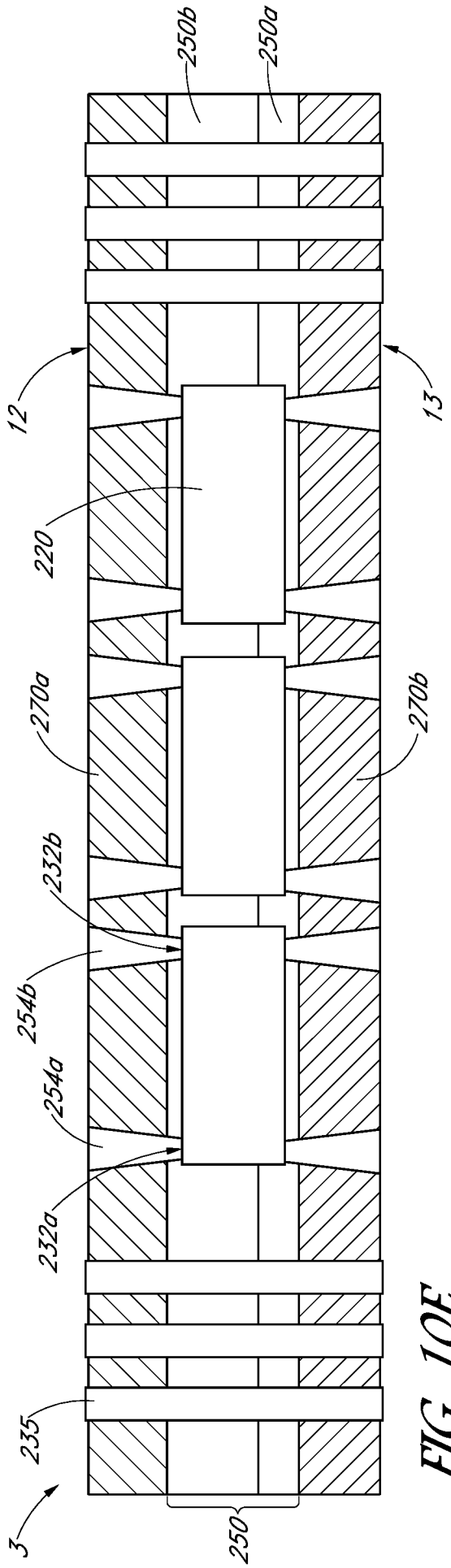


FIG. 10E

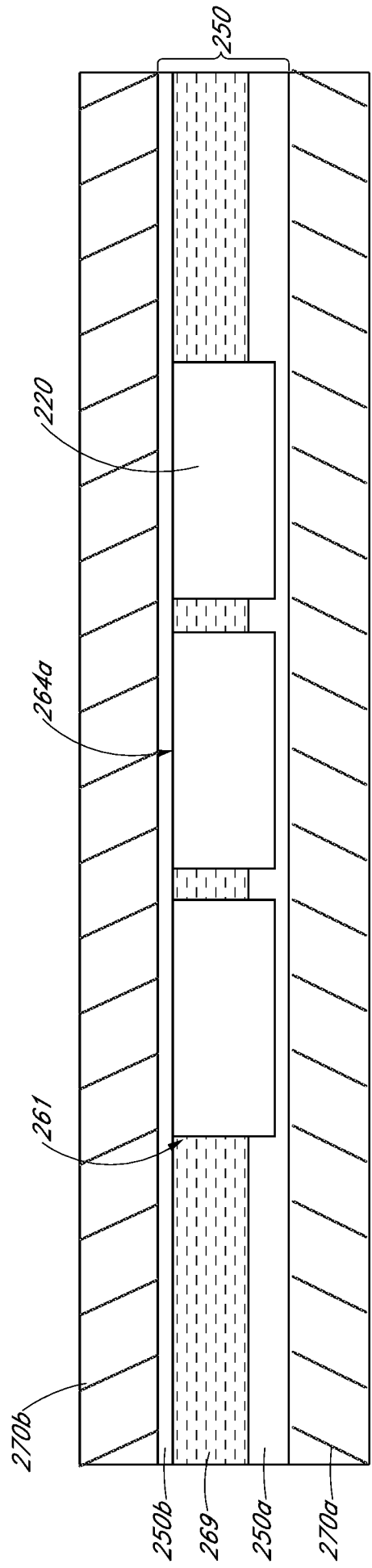


FIG. 10F

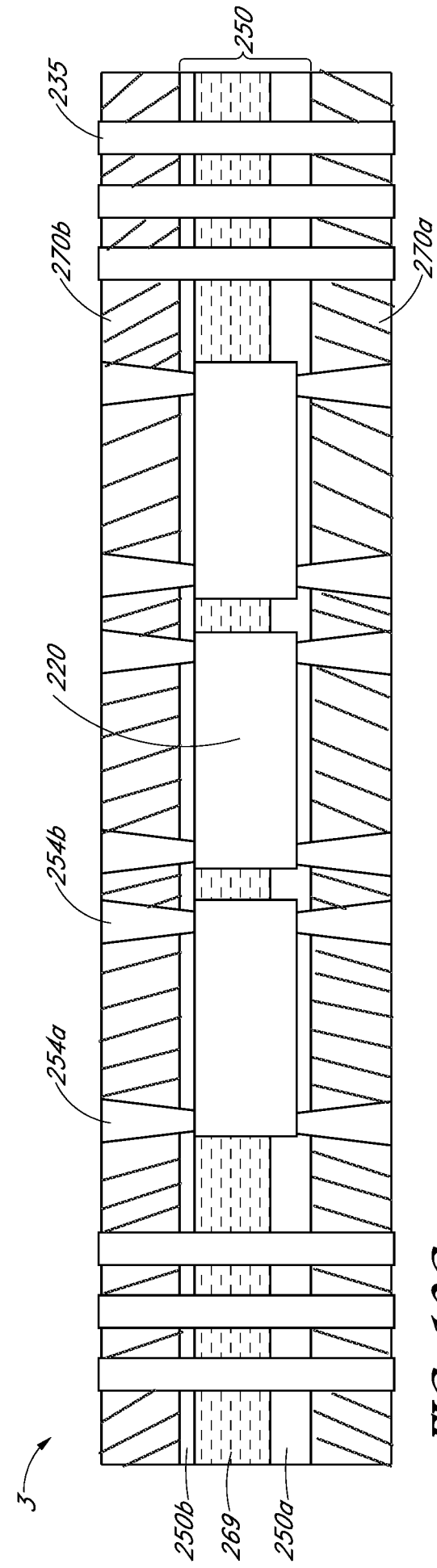


FIG. 10G

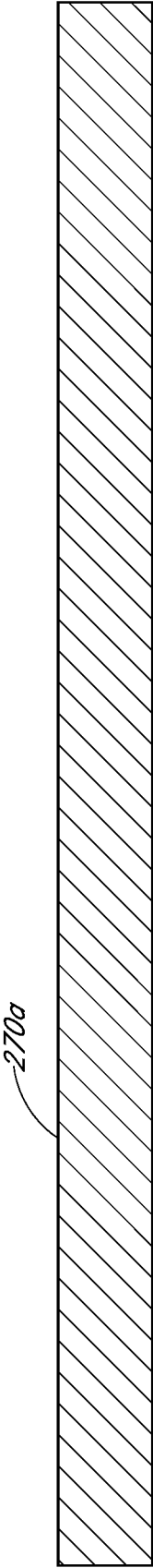


FIG. 11A

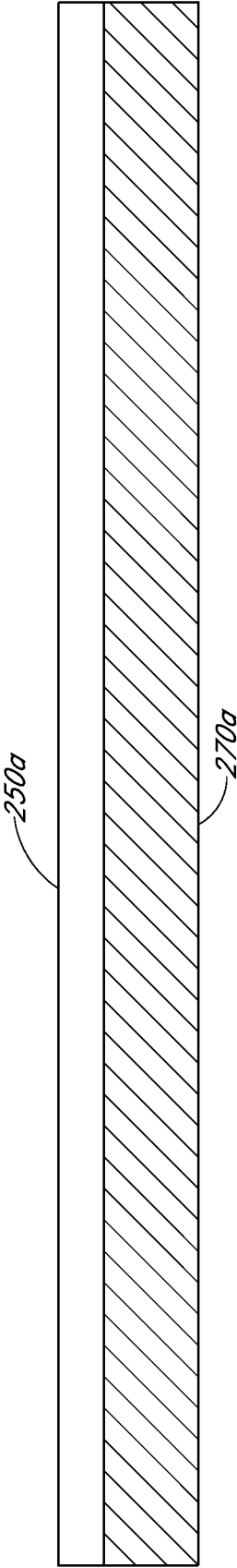


FIG. 11B

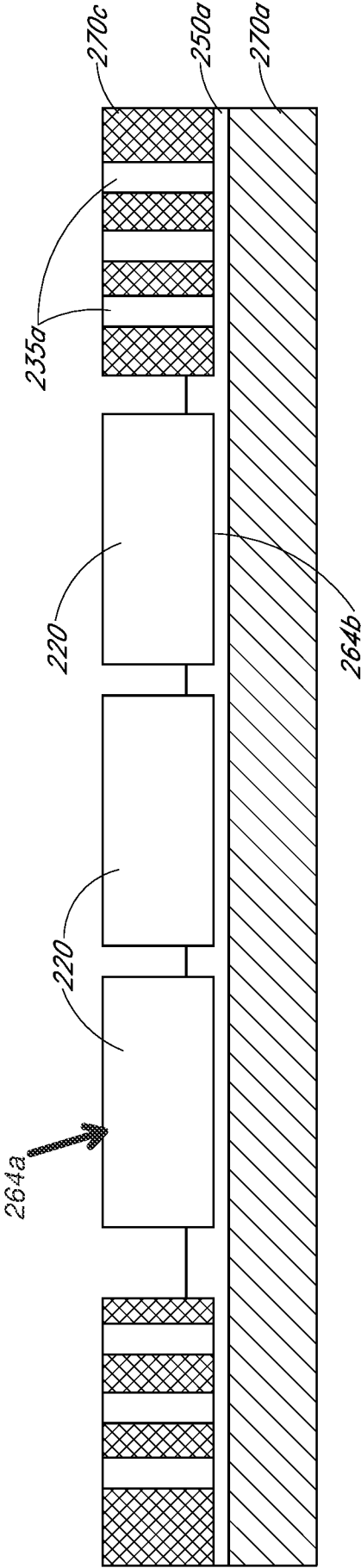


FIG. 11C

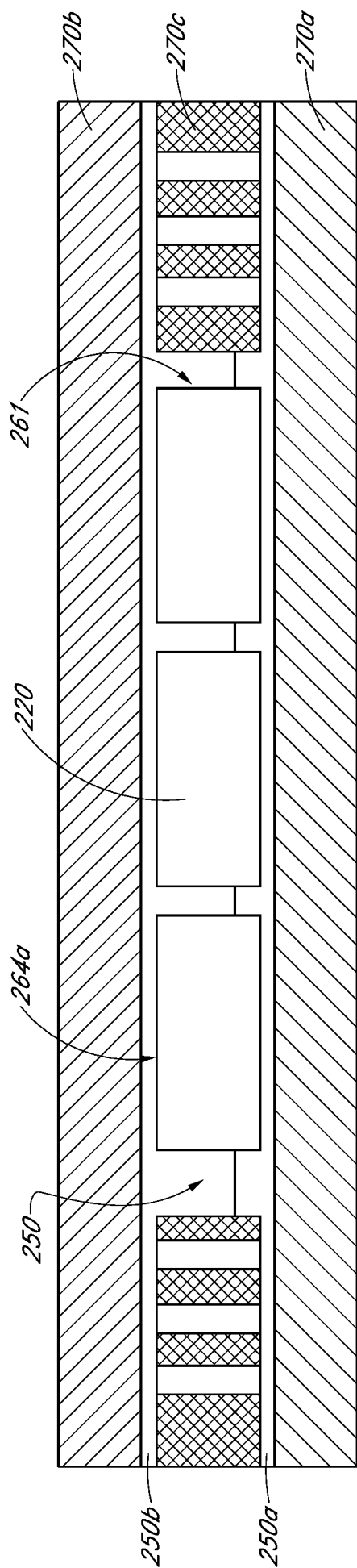


FIG. 11D

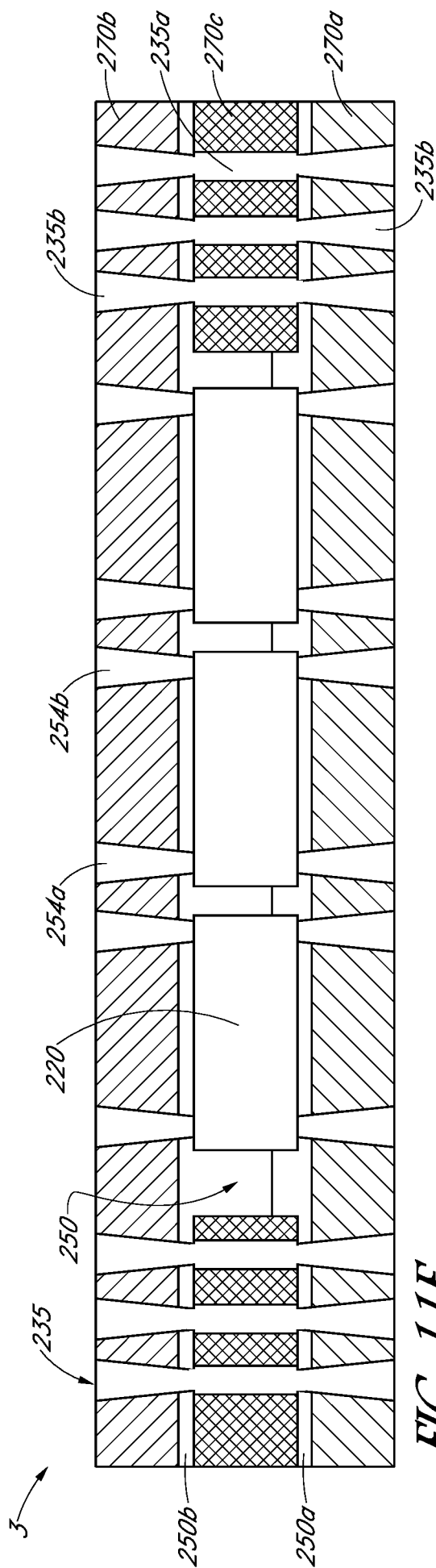


FIG. 11E

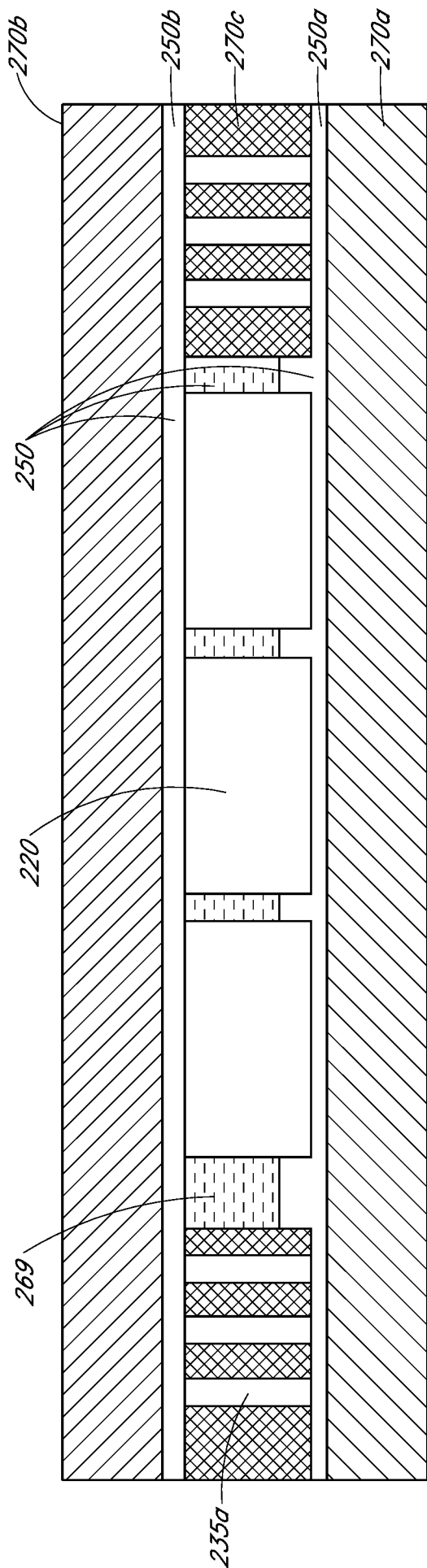


FIG. 11F

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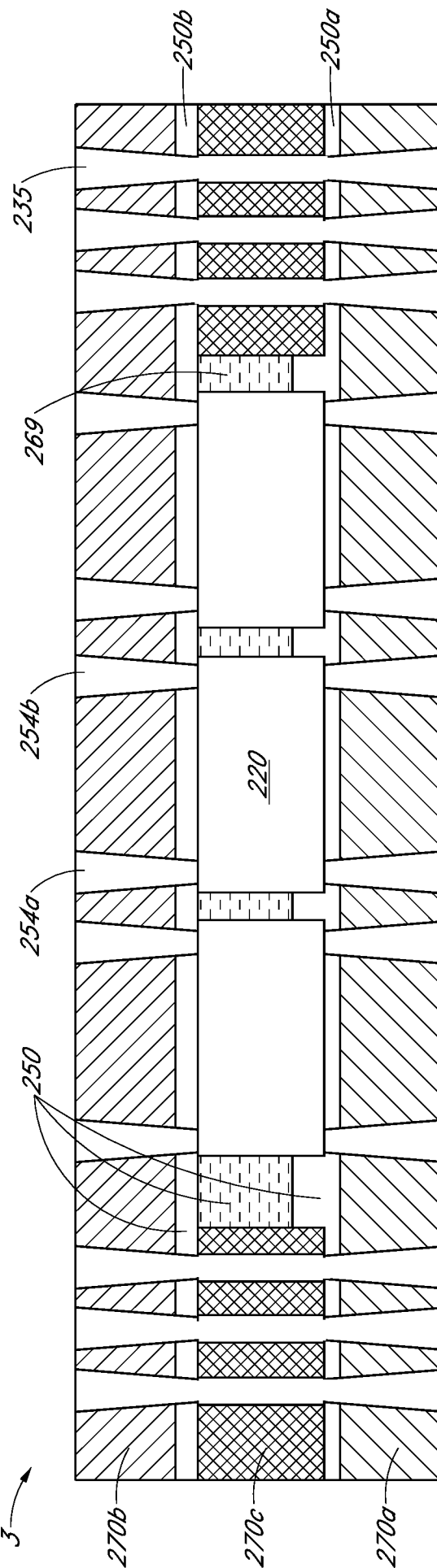


FIG. 11G

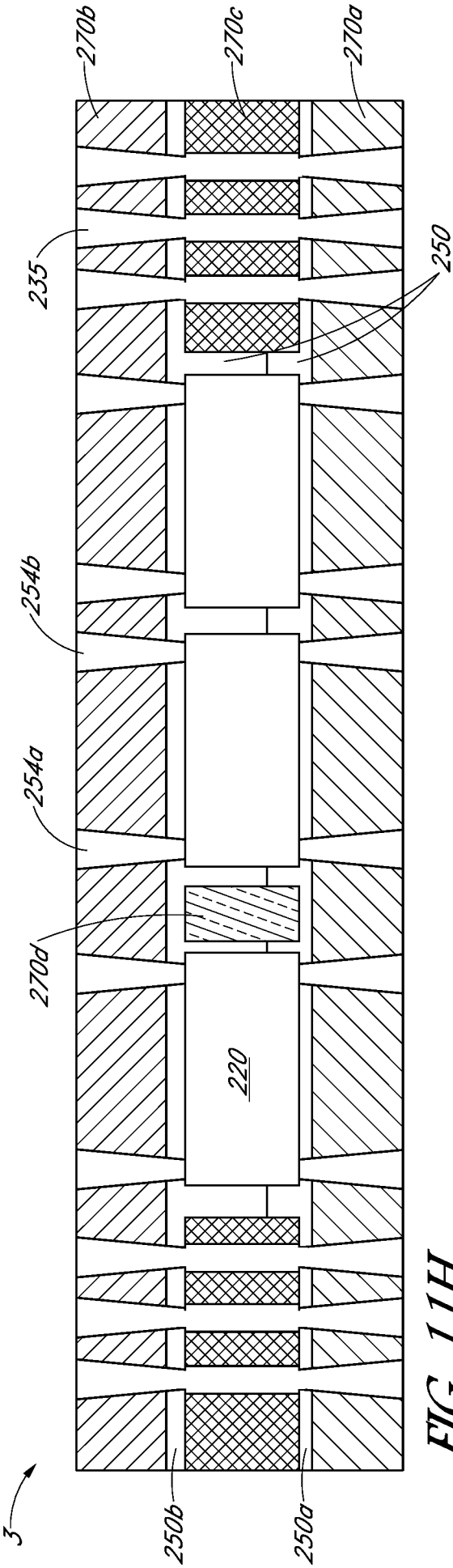


FIG. 11H

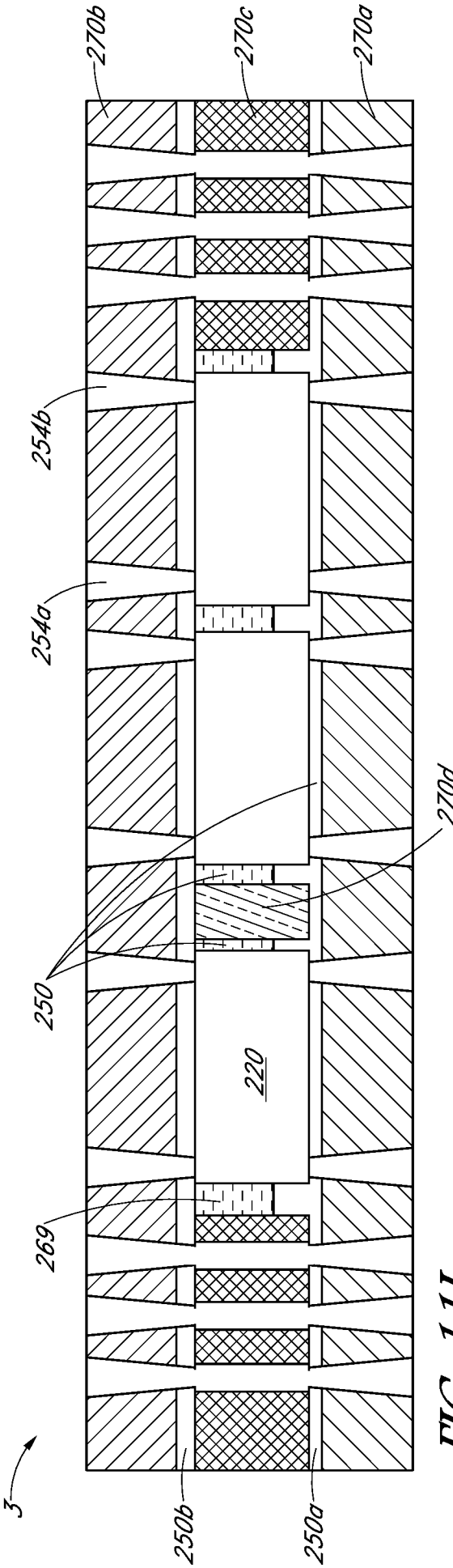


FIG. 11I

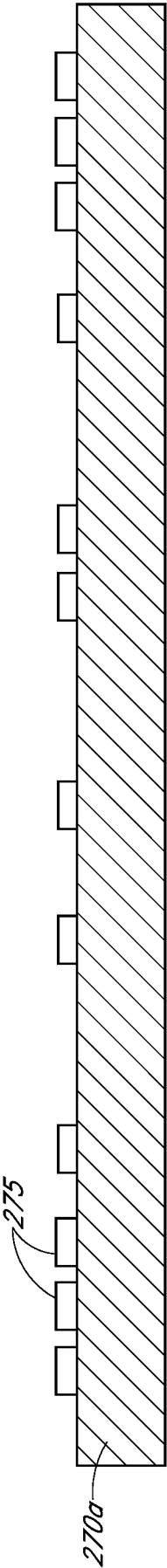


FIG. 12A

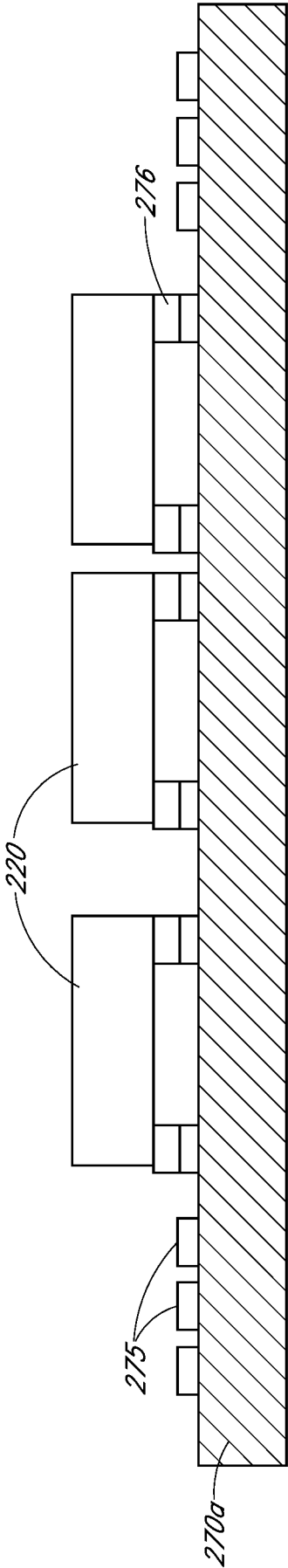


FIG. 12B

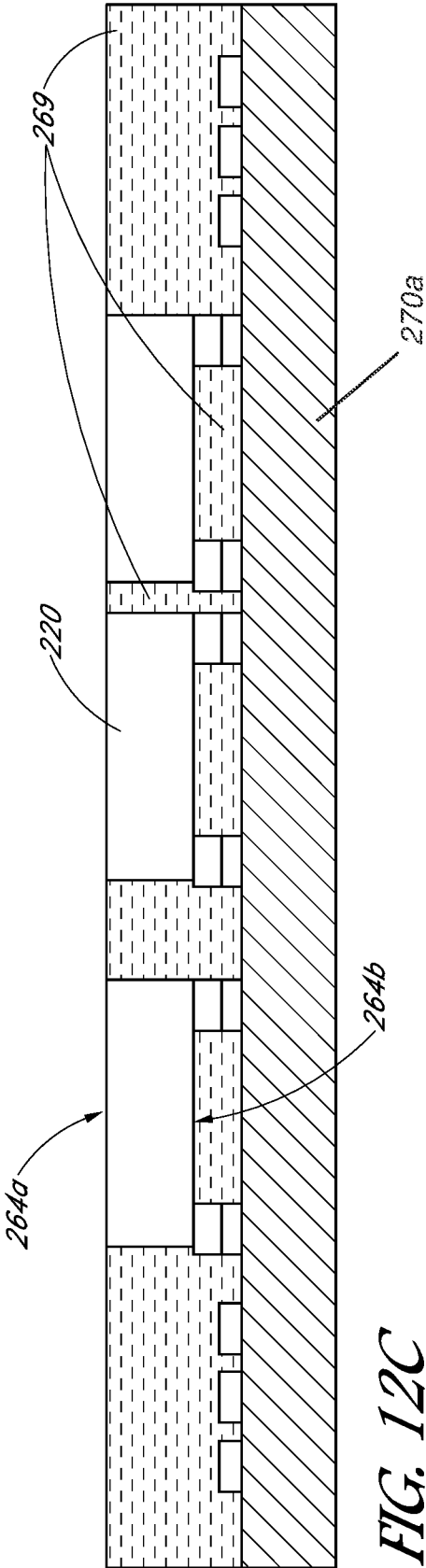


FIG. 12C

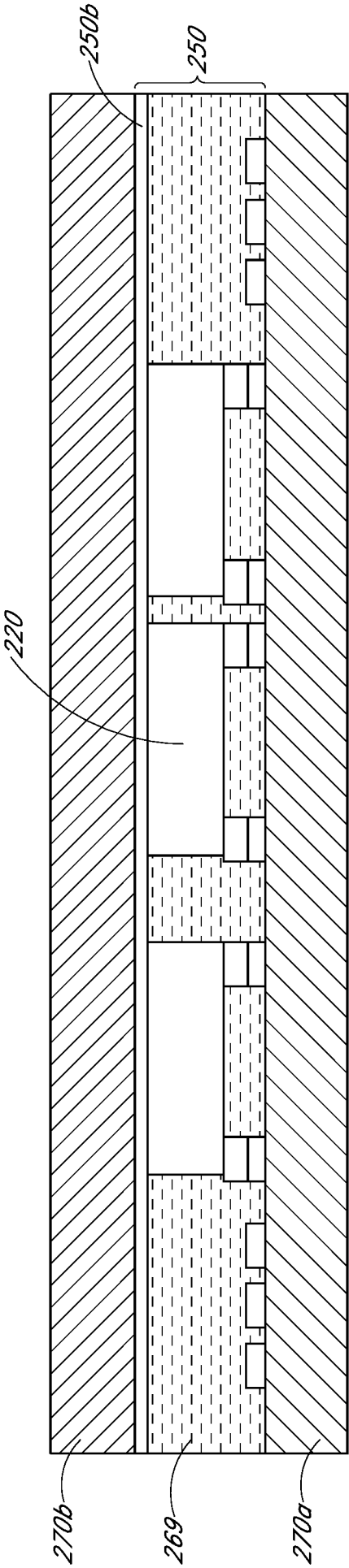


FIG. 12D

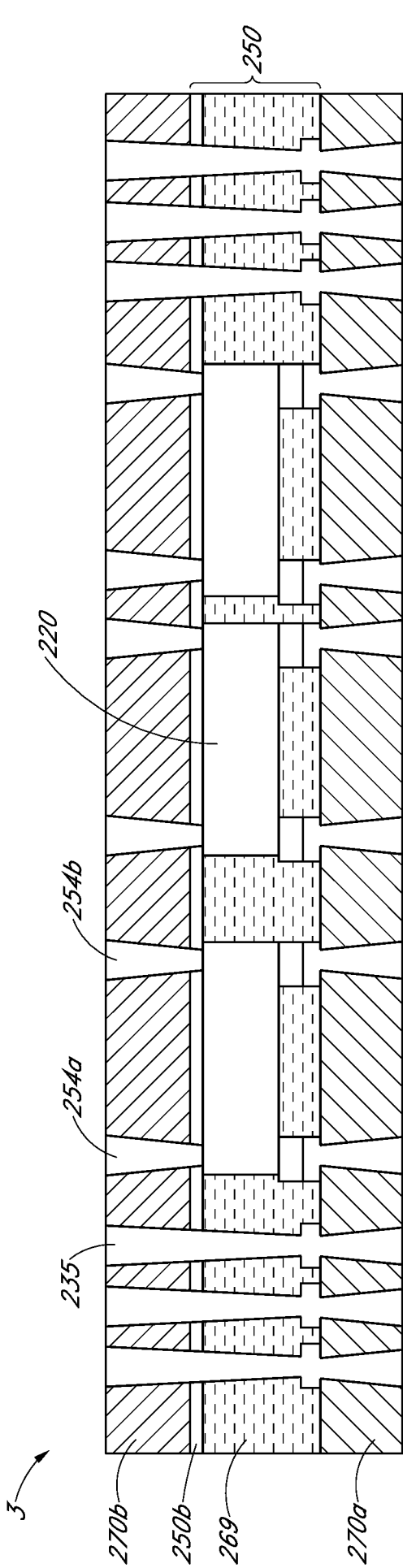


FIG. 12E

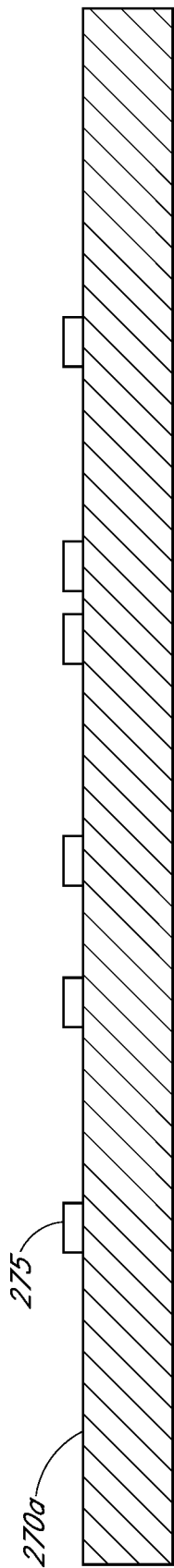


FIG. 13A

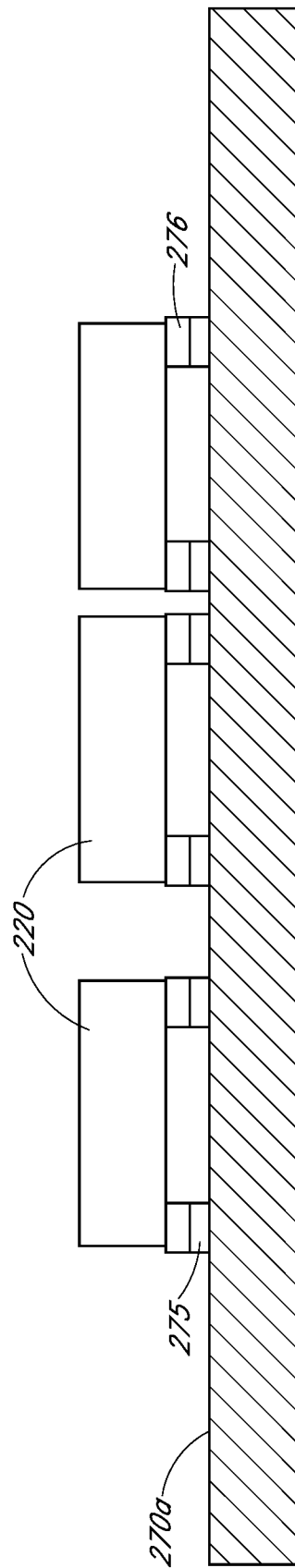


FIG. 13B

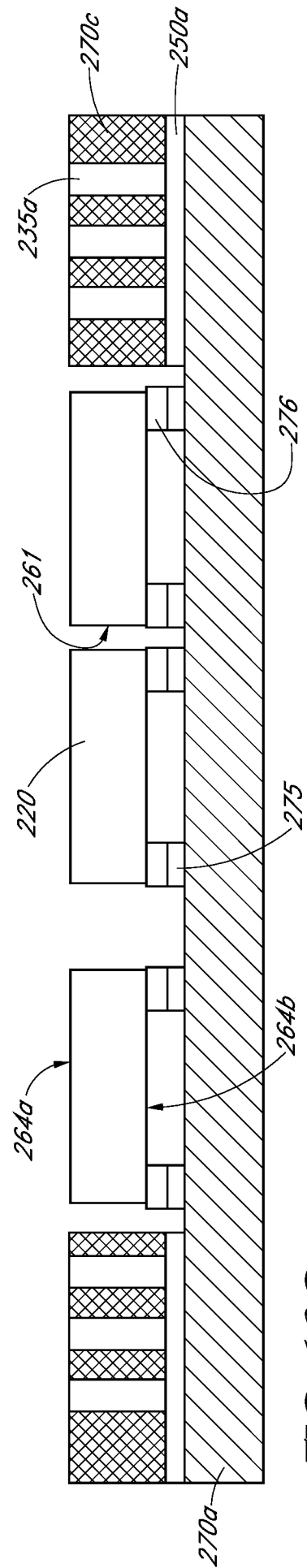


FIG. 13C

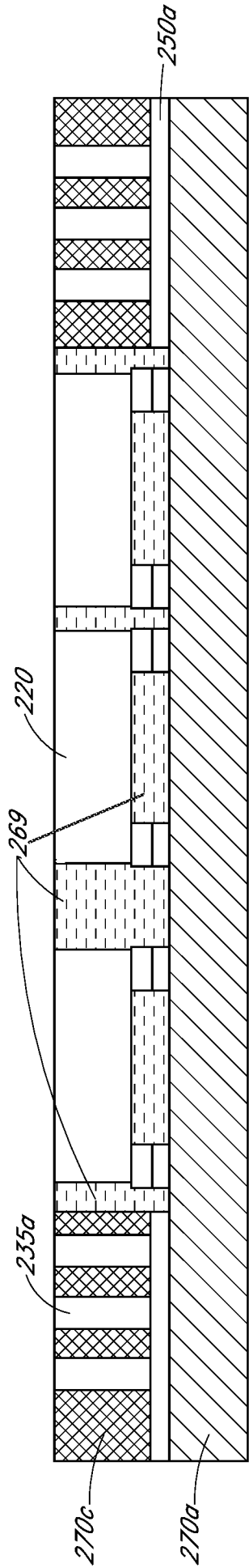


FIG. 13D

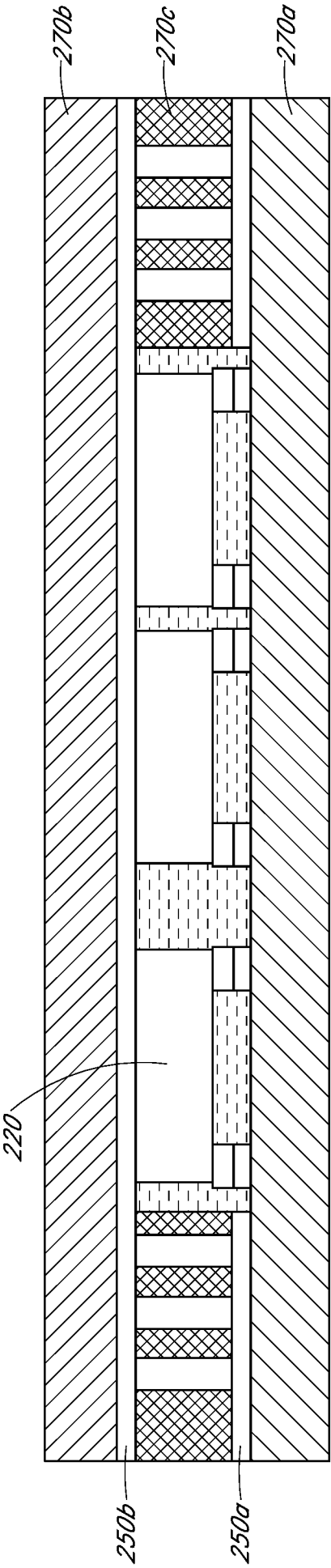


FIG. 13E

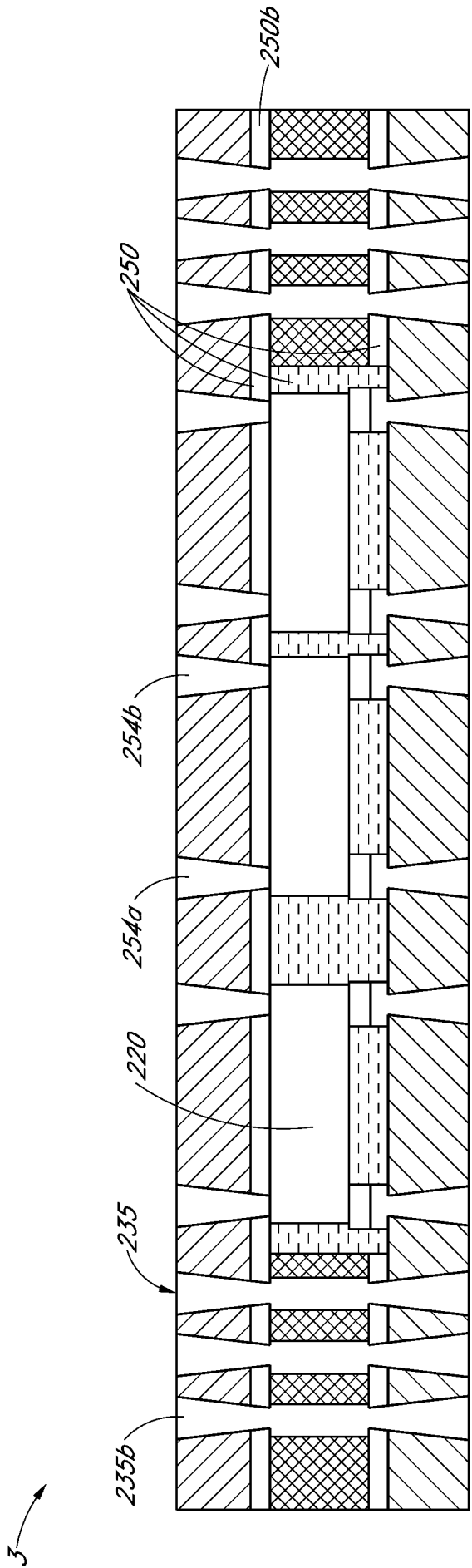


FIG. 13F

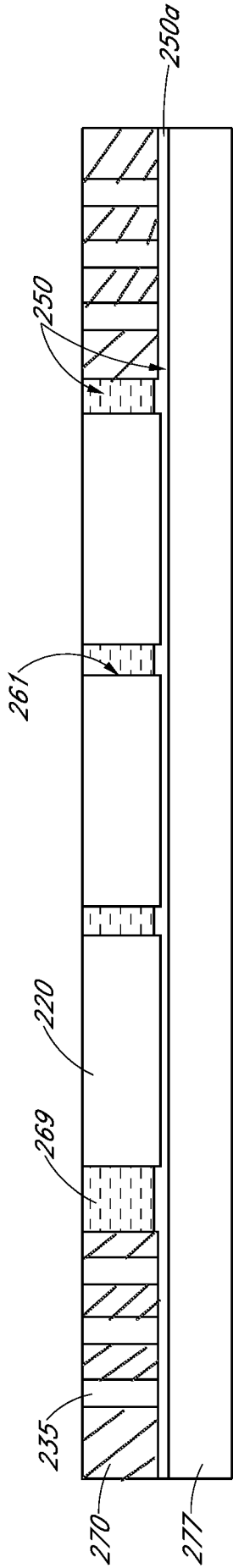


FIG. 14A

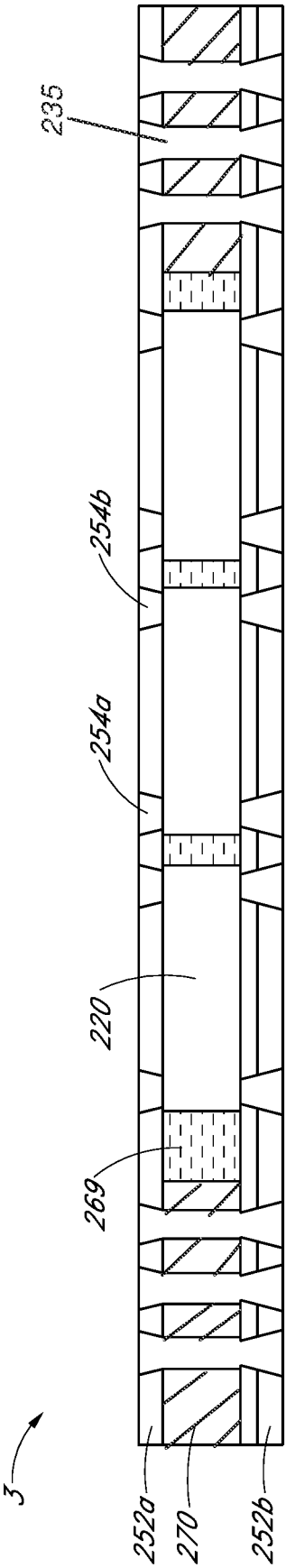
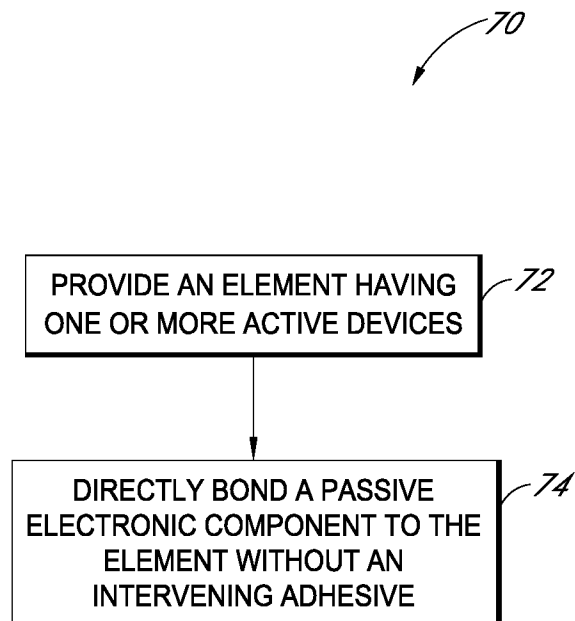


FIG. 14B

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*FIG. 15*

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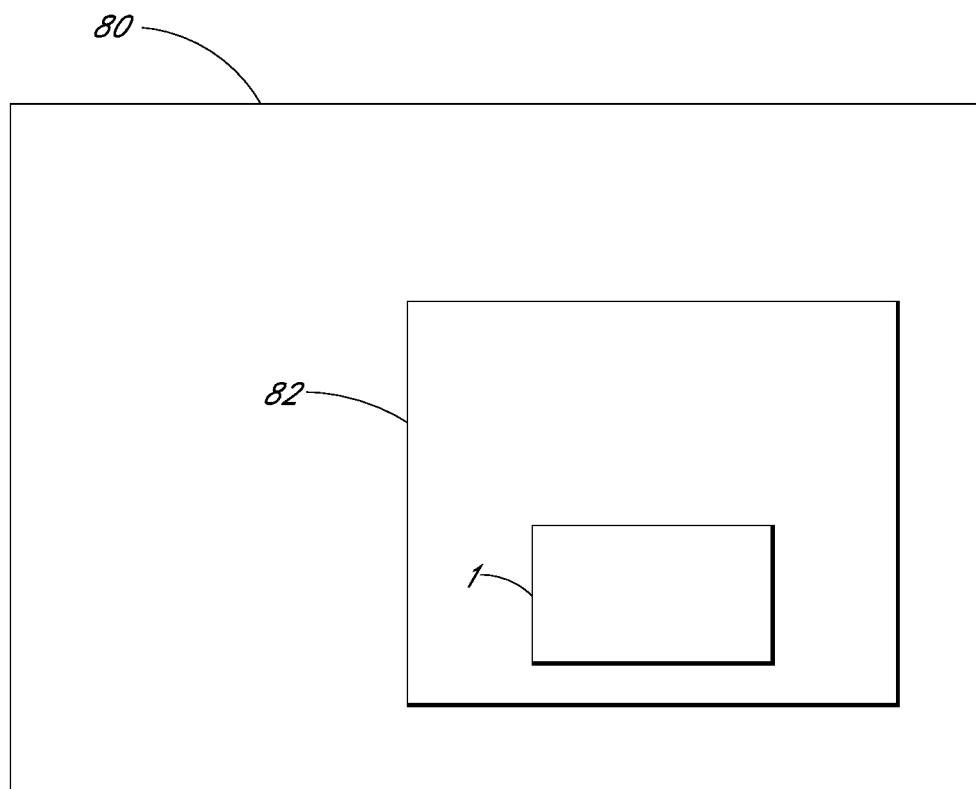


FIG. 16

A. CLASSIFICATION OF SUBJECT MATTER**H01L 23/64(2006.01)i, H01L 49/02(2006.01)i, H01L 23/485(2006.01)i, H01L 23/36(2006.01)i, H01L 25/07(2006.01)i**

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)

H01L 23/64; H01L 27/02; H01L 25/16; H01L 21/50; H05K 1/16; H05K 7/00; H05K 7/06; H01L 27/08; H01L 49/02; H01L 23/485; H01L 23/36; H01L 25/07

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Korean utility models and applications for utility models

Japanese utility models and applications for utility models

Electronic data base consulted during the international search (name of data base and, where practicable, search terms used)

eKOMPASS(KIPO internal) & Keywords: bonding, passive, capacitor, insulating, interconnect

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X	US 2006-0012966 A1 (KISHORE K. CHAKRAVORTY) 19 January 2006 See paragraphs 27-63, claims 1-15 and figures 2-5.	17-28
Y		1-16
Y	US 2012-0168217 A1 (CHIEN-MIN HSU et al.) 05 July 2012 See paragraphs 40-41, claims 1-10 and figure 6.	1-16
A	US 2007-0147014 A1 (CHIA-WEI CHANG et al.) 28 June 2007 See paragraphs 31-32 and figure 4.	1-28
A	US 2016-0111404 A1 (INVENSAS CORPORATION) 21 April 2016 See paragraphs 32-37 and figure 16.	1-28
A	US 2013-0105943 A1 (CHIEN-KUANG LAI et al.) 02 May 2013 See paragraphs 32-43 and figure 2G.	1-28



Further documents are listed in the continuation of Box C.



See patent family annex.

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"P" document published prior to the international filing date but later than the priority date claimed

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"X" document of particular relevance; the claimed invention cannot be considered novel or cannot be considered to involve an inventive step when the document is taken alone

"Y" document of particular relevance; the claimed invention cannot be considered to involve an inventive step when the document is combined with one or more other such documents, such combination being obvious to a person skilled in the art

"&" document member of the same patent family

Date of the actual completion of the international search

23 April 2018 (23.04.2018)

Date of mailing of the international search report

23 April 2018 (23.04.2018)

Name and mailing address of the ISA/KR

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INTERNATIONAL SEARCH REPORT

Information on patent family members

International application No.

PCT/US2017/068788

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